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**About This Manual** 

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This manual supports the field service maintenance and repair of the HD3 Ultrasound System. The user of this document is a qualified ultrasound electronics technician who has completed training classes on the system and its peripherals.

#### **Manual Format**

This manual is in Portable Document Format (PDF), for viewing on a laptop computer with Acrobat Reader. A list of bookmarks functions as an additional table of contents. Those bookmarks, the table of contents, and cross-references use hypertext links to provide access to the referenced information.

## Conventions in This Manual

The following conventions are used in this manual:

- Hypertext links are blue.
- All procedures are numbered, and all subprocedures are lettered. You must complete steps in the sequence they are presented to ensure reliable results.

4535 612 34161 HE CSIP Level I	Page 2 About This Manual
	<ul> <li>Bulleted lists indicate general information about a function or procedure. They do not imply a sequential procedure.</li> </ul>
	<ul> <li>Control names and menu items or titles are spelled as they are on the system, and they appear in bold text.</li> </ul>
	Symbols appear as they appear on the system.
	An English system is assumed.
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4535 612 34161 HD3 Service Manual CSIP Level I	Page 4 Contents
Contents	
About This Manual	I
Audience	
Manual Format	I

Transducers 30

4535 612 34161 HD3 Service Manual Page 5 CSIP Level I Contents	
Figure 1-4 HD3 Ultrasound System Foot Switch	
Physical Description	
Cart	
System Control Panel	
Figure I-5 HD3 Ultrasound System Control Panel	
System Monitor	
Ultrasound Components	
System Power Components	
Software and Data Storage Components	
I/O Panel	
Cables	
Device Safety Requirements and Regulatory Compliance	
Supplies and Accessories	
Open Source Software License	
System Specifications	
Introduction	
Physical Specifications	
Electrical Specifications	
Environmental Specifications	
System PC Specifications	
Table 2-1 Embedded PC Hardware Specifications42	

4535 612 34161 HD3 Service Manual Page 6 CSIP Level I Contents	
Monitor Specifications	
Image Formats	
Table 2-2 Supported Image Formats4	
Safety45	
Introduction	
About Safety Information	
General Operating Safety	
Electrical Safety   46	
Avoiding EMI and RF	
Mechanical Safety	
General Equipment Protection	
About Electrostatic Discharge	
Symbols	
Theory of Operation	
Introduction	
System Architecture	
Operating System	
Functional Description	
Figure 4-1 HD3 System Functional Block Diagram	
Physical Functions	
System Power	

4535 612 34161 HD3 Service Manual Page 7 CSIP Level I Contents
Transducer Connector Assembly (TCA)
Front End (FE) Board
Beamformer (BF)
Digital Scan Converter (DSC)
PCC Board
E-box Backplane
Input/Output Panel
User Interface
Hard Disk Drive (HDD)
CD-RW
Magneto-optical Disk (MOD) Drive
Flash Memory Stick
Installation
Introduction
Installation Checklist
Inspecting the Installation Site
Checking Physical Access for Delivery and Installation
Checking Electrical and Environmental Requirements
Gathering Site Network (DICOM) Information
Uncrating and Unpacking the System
Inspecting the Crate

4535 612 34161 HD3 Service Manual Page 8 CSIP Level I Contents
Uncrating
Inspecting the System
➤ To inspect the system after uncrating
Assembling the System
Installing the Printers, VCR, and Footswitch
Installing the System Power Cord72
Powering On and Configuring the System
Verifying the Local Settings
➤ To check or set the institution name
Figure 5-1 Setup Window (System)
➤ To verify or set the system time and date
➤ To change the user interface language
Verifying the System Options
➤ To verify or activate system software options
Figure 5-2 Setup Window (Option)
Configuring the DICOM Feature
➤ To configure the system DICOM parameters
Figure 5-3 Setup Window (DICOM)
➤ To identify the DICOM storage devices that the system will use
➤ To identify the DICOM printers that the system will use
Figure 5-4 System Network Settings Window (DICOM)

4535 612 34161 HD3 Service Manual Page 9 CSIP Level I Contents
Figure 5-5 Server Configuration Window (DICOM)
➤ To test the communication between the system and a server or a printer
➤ To configure the DICOM Log file83
Figure 5-6 DICOM Device Test Results Message Examples (DICOM)
Figure 5-7 Setup Window (Admin)
Figure 5-8 DICOM Log Window
Configuring Other System Settings
➤ To configure other system settings
Preparing the Peripherals
Checking System Functionality
Presenting the System
Physical Installation Procedures
Figure 5-1 Installation Procedure List89
Uncrating the HD3 Ultrasound System
Figure 5-2 Cutting the Poly Strapping Bands
➤ To uncrate the HD3 Ultrasound System
Figure 5-3 Removing the Corrugated Top Cover
Figure 5-4 Removing the Corrugated Wrap92
Figure 5-5 Removing the Ramp Bolts93
Figure 5-6 Placing the Ramp
Figure 5-7 Removing the System Hold-down Brace95

4535 612 34161 HD3 Service Manual Page 10 CSIP Level I Contents
Figure 5-8 Removing the Wheel Chock96
Figure 5-9 Rotating the Rear Casters
Figure 5-10 Rolling the System Off the Pallet
Figure 5-11 Removing the Shipping Materials (Antistatic Bag and Monitor Support)
Figure 5-12 Removing the Shipping Materials (Yoke Support)
Monitor Support Shipping Foam
Figure 5-13 Locking the Front Casters
➤ To install the monitor support shipping foam
Figure 5-14 Tilting the Video Monitor
Figure 5-15 Placing the Foam Monitor Support
Figure 5-16 Securing the Video Monitor
Top-Mounted Color Printer
Figure 5-17 Adjusting the Universal Peripheral Mounting Plate for the Color Printer
➤ To install the color printer
Figure 5-18 Removing the Top Cover Access Plate Screws
Figure 5-19 Installing the Universal Peripheral Mounting Plate
Figure 5-20 Installing the Mounting Strap on the Universal Peripheral Mounting Plate
Figure 5-21 Placing and Strapping the Color Printer to the Universal Peripheral Mounting Plate
Figure 5-22 Cabling the Color Printer to the <b>HD3</b> System
Top-Mounted VCR
Figure 5-23 Adjusting the Universal Peripheral Mounting Plate for the VCR

4535 612 34161 HD3 Service Manual Page 11 CSIP Level 1 Contents
➤ To install the VCR
Figure 5-24 Removing the Top Cover Access Plate Screws
Figure 5-25 Installing the Universal Peripheral Mounting Plate
Figure 5-26 Installing the Mounting Strap on the Universal Peripheral Mounting Plate
Figure 5-27 Placing and Strapping the VCR to the Universal Peripheral Mounting Plate
Figure 5-28 Cabling the VCR to the HD3 System
MOD Drive
Figure 5-29 Connecting the USB Cable to the MOD Drive
➤ To install the MOD drive
Figure 5-30 Connecting the USB Cable to the HD3 System
Foot Switch
Figure 5-31 Foot Switch Cabling
➤ To install the foot switch
Figure 5-32 Foot Switch Placement
System Power Cord
Figure 5-33 Connecting the System Power Cord (Power Cord with Inline Filter)
➤ To install the system power cord
Figure 5-34 Connecting the System Power Cord (Power cord with Separate Inline Filter Power Adapter) 122
➤ To install the system power cord
B/W Printer Plate (No-Printer Systems)
Figure 5-35 B/W Printer Plate Storage

4535 612 34161 HD3 Service Manual Page 12 CSIP Level I Contents
Performance Tests
Introduction
Warnings and Cautions
Visual Inspection for Mechanical Integrity
System Functionality
Electrical Safety
Chassis to Ground Resistance Test
Figure 6-1 Chassis to Ground Resistance Test Diagram
➤ To test the system for resistance between chassis and ground
Ground Wire Leakage Current Test
Figure 6-2 Ground Wire Leakage Current Test Diagram
➤ To test the system ground wiring for leakage
Transducer Tests
Figure 6-3 Transducer Leakage Current Test Diagram
➤ To test transducer leakage current
Figure 6-4 Transducer Isolation Leakage Current Test Diagram
➤ To test transducer isolation leakage current
Adjustments
Introduction
Adjusting the Monitor
➤ To adjust the monitor brightness

4535 612 34161 HD3 Service Manual Page 13 CSIP Level I Contents	
Positioning the Monitor	
Preventive Maintenance	
Introduction	
Warnings and Cautions	
Exterior and Interior Assemblies	
➤ To clean the trackball	
Exterior Surfaces	
Troubleshooting	
Introduction	
Warnings and Cautions	
All Troubleshooting Starts Here	
Table 9-1 Effective Problem-Solving Checklist	
Clarifying Symptoms         142	
Re-creating a Problem	
Isolating Causes	
Developing a Solution	
Implementing a Solution	
Verifying Corrective Actions	
Returning the System to Service	
Symptoms, Causes, and Corrective Actions	
Disk is Full	

4535 612 34161 HD3 Service Manual Page 14 CSIP Level I Contents	
Checking for EMI and RFI	
System Hangs or Crashes	
DICOM/Network Failures	
Backing Up and Restoring	
Loading Software and Drivers	
Managing System Options	
Viewing System Information and Logs	
➤ To display system information	
➤ To display the keystroke or DICOM log	
Disassembly	
Introduction	
Warnings and Cautions	
Disassembly (Removal) Procedures	
Figure 10-1 Disassembly Procedure List (1 of 2)	
Figure 10-2 Disassembly Procedure List (2 of 2)	
System Enclosures         157	
Figure 10-3 Removing the Left Side Enclosure	
➤ To remove the system enclosures	
Figure 10-4 Removing the Right Side Enclosure	
Figure 10-5 Removing the Front Enclosure	
Video Monitor         160	

4535 612 34161 HD3 Service Manual Page 15 CSIP Level I Contents
Figure 10-6 Removing the Video Monitor
➤ To remove the system monitor
Figure 10-7 Disconnecting the Video Monitor Cables
Control Panel
Figure 10-8 Removing the Top Control Panel Enclosure
➤ To remove the control panel, trackball assembly, keyboard assembly, and splitter board162
Figure 10-9 Tilting the Top Control Panel Enclosure
Figure 10-10 Disconnecting the Control Panel Cables
Figure 10-11 Removing the Trackball Assembly
Figure 10-12 Removing the Keyboard Assembly
Figure 10-13 Removing the Splitter Board
VCR or Color Printer
Figure 10-14 Removing the VCR or the Color Printer
➤ To remove the VCR or the color printer
Universal Peripheral Mounting Plate
Figure 10-15 Removing the Universal Peripheral Mounting Plate
➤ To remove the universal peripheral mounting plate
Peripheral Bay (B/W Printer, Printer Bay, CD/Hard Drive Rack, and Power Transformer)
Figure 10-16 Peripheral Bay Components
➤ To remove the B/W printer, CD/Hard drive rack, power transformer, and printer bay
Figure 10-17 Disconnecting the B/W Printer Cables and Removing the Printer Retaining Bracket

4535 612 34161 HD3 Service Manual Page 16 CSIP Level I Contents
Figure 10-18 Disconnecting the Drive Cables and Removing the Drive Rack Assembly
Figure 10-19 Removing the B/W Printer Bay
Figure 10-20 Power Transformer Cable Tie
Figure 10-21 Sliding the Transformer Back
Figure 10-22 Removing the Power I/O Box
Figure 10-23 Removing the Power Transformer
E-box Bay (E-box Assembly, Transducer Connector Assembly, E-box Boards, Power Supply and Cooling Fans) 178
Figure 10-24 E-box Bay Components
➤ To remove the E-box assembly, transducer connector assembly, E-box boards, power supply and cooling fans 178
Figure 10-25 Removing the E-box Rear Shield
Figure 10-26 Disconnecting the Power Supply Power Cord
Figure 10-27 Removing the Power Supply
Figure 10-28 Removing the BFC Board
Figure 10-29 Removing the FE, BF and DSC Boards
Figure 10-30 Removing the PCC Board
Figure 10-31 Removing the Transducer Connector Assembly (TCA)
Figure 10-32 Removing the E-box Assembly
Figure 10-33 Removing the Backplane Board Shield
Figure 10-34 Removing the Backplane Board
Figure 10-35 Removing the E-box Cooling Fans
Rear I/O Panel Assembly

4535 612 34161 HD3 Service Manual Page 17 CSIP Level 1 Contents
Figure 10-36 Removing the Left and Right Side Enclosures
➤ To remove the Rear I/O panel assembly
Figure 10-37 Removing the Rear I/O Panel
Figure 10-38 Disconnecting the Rear I/O Panel Assembly PCB Cables
Figure 10-39 Removing the Rear I/O Panel Assembly PCB
Power I/O Box
Figure 10-40 Removing the Left and Right Side Enclosures
➤ To remove the Power I/O box
Figure 10-41 Disconnecting the Power Supply Power Cord
Figure 10-42 Cutting the Cable Ties on the Power Cables
Figure 10-43 Removing the Power I/O Box
Lift Column Gas Strut
Figure 10-44 Lowering the Control Panel
➤ To remove the lift column gas strut
Figure 10-45 Removing the Gas Strut from the Ball Stud
Figure 10-46 Removing the Gas Strut from the Lock Bracket
Figure 10-47 Removing the Gas Strut Mount Access Panel
Figure 10-48 Installing the Gas Strut into the Lock Bracket
Figure 10-49 Inserting the Gas Strut onto the Ball Stud
System Casters
Figure 10-50 Preparing the System for Caster Replacement

4535 612 34161 HD3 Service Manual Page 18 CSIP Level I Contents
➤ To remove a system casters
Figure 10-51 Tipping the System to Remove the Rear Casters
Figure 10-52 Tipping the System to Remove the Front Casters
Crating the HD3 Ultrasound System
Figure 10-53 Locking the Front Casters
➤ To crate the HD3 Ultrasound System
Figure 10-54 Raising the Control Panel
Figure 10-55 Placing the Foam Yoke Support
Figure 10-56 Lowering the Control Panel
Figure 10-57 Tilting the Video Monitor
Figure 10-58 Placing the Foam Monitor Support
Figure 10-59 Securing the Video Monitor
Figure 10-60 Fastening the Two Foam Supports Together
Figure 10-61 Covering the System with an Antistatic Bag
Figure 10-62 Placing the Ramp
Figure 10-63 Loading the System onto the Crate
Figure 10-64 Rotating the Rear Casters
Figure 10-65 Placing the Wheel Chock
Figure 10-66 Placing the System Hold-Down Brace
Figure 10-67 Mounting the Ramp to the Crate
Figure 10-68 Placing the Corrugated Wrap

4535 612 34161 HD3 Service Manual Page 19 CSIP Level I Contents
Figure 10-69 Placing the Corrugated Top Cover
Figure 10-70 Banding the System Crate
Cabling
Introduction
System Cabling Diagrams
Cable Part Numbers
System Connectors
Figure 11-1 HD3 Ultrasound System Signal Interconnect Diagram
Figure 11-2 HD3 Ultrasound System Power Distribution Diagram
Cable Parts List
Table 11-1 HD3 System Signal and Power Cable Part Numbers
Peripheral Cabling Diagrams
Figure 11-1 Sony UP-895MD B/W Printer Cabling Diagram
Figure 11-2 Sony UP-21MD Color Printer Cabling Diagram
Figure 11-3 Mitsubishi HS-MD3000UA/EA VCR Cabling Diagram
System Connector Illustrations
Figure 11-4 HD3 System Connector Locations (Front Panel)
Figure 11-5 HD3 System Connector Locations (Rear I/O Panel)
Figure 11-6 HD3 System Connector Locations (Power Connectors)
Figure 11-7 HD3 System Connector Locations (Power I/O Box Connectors)
Figure 11-8 HD3 Video Monitor PCB Cable Connector Locations

4535 612 34161 HD3 Service Manual Page 20 CSIP Level I Contents
Figure 11-9 HD3 Control Panel PCB Cable Connector Locations (Splitter Board)
Figure 11-10 HD3 Rear I/O PCB Internal Cable Connector Locations (Side View)
Figure 11-11 HD3 PCC PCB Cable Connector Locations
Change History
Introduction
Initial System Release (v1.00.00 Build 085)
Configuration
Introduction
Compatibility Information
System Software         246
Table 13-1 System Software CD Part Numbers
Locating and Identifying Primary PCBs
PCB Reference Information
Figure 13-1 HD3 Primary System PCB Names and Locations (E-box)
Figure 13-2 HD3 Primary System Board Names and Locations (Rear I/O Panel)
Figure 13-3 HD3 Primary System PCB Names and Locations (Power I/O Box)
Figure 13-4 HD3 Primary System PCB Names and Locations (Control Panel)
Video Monitor PCBs         252
Figure 13-5 Video Monitor PCBs (Back of Monitor LCD)
Control Panel PCBs
Figure 13-6 Control Panel Interface and Keyboard PCBs (Top Half of Control Panel)

	Page 21 Contents
Figure 13-7 Control Panel Splitter Board (Bottom Half of Control Panel)	254
E-box PCBs	255
Figure 13-8 Transducer Connector Assembly (TCA)	255
Figure 13-9 Backplane Assembly	256
Figure 13-10 Beamformer - to - Frontend Connector (BFC)	257
Figure 13-11 Front End (FE) Assembly	258
Figure 13-12 Beamformer (BF) Board	259
Figure 13-13 Digital Scan Converter (DSC) Board	260
Figure 13-14 PCC Board	261
Rear I/O Panel PCB	262
Figure 13-15 Rear I/O Panel PCB	262
Power I/O Box PCB	263
Figure 13-16 Power I/O Box PCB	263
Disk Drive Settings	264
Hard Drive Jumpers	264
Figure 13-17 Hard Drive Jumper Settings	264
CD-RW Drive Jumpers	265
Figure 13-18 CD-RW Drive Jumper Position	265
MOD Drive Jumpers	266
Peripheral Settings	266
B/W Printer	266

4535 612 34161 HD3 Service Manual Page 22 CSIP Level I Contents
Table 13-2 UP-895MD Printer Switch Settings
Color Printer
Table 13-3 UP-21MD Printer Settings
VCR 271
Table 13-4 HS-MD3000U/E VCR Control and Switch Settings
Table 13-5 HS-MD3000U/E VCR Displayed Menu Settings
➤ To change the VCR displayed menu settings
Table 13-6 Mitsubishi HS-MD3000E/U VCR Hidden Menu Settings
➤ To change the VCR hidden menu settings
Parts
Introduction
How and Where to Find a Part Number
Parts Ordering Information
Illustrations
Figure 14-1 HD3 Ultrasound System Parts Locator Map (Front and Rear Views)
Figure 14-2 HD3 Ultrasound System Parts Locator Map (Right Side)
Figure 14-3 Video Monitor Assembly
Figure 14-4 Video Monitor Assembly (LCD Front Panel and Housing)
Figure 14-5 Control Panel
Figure 14-6 Control Panel (Knobs and Cable Hooks)
Figure 14-7 Control Panel (Top, Handle and Splitter Board)

4535 612 34161 HD3 Service Manual Page 23 CSIP Level I Contents
Figure 14-8 Control Panel (Keyboard and Trackball)
Figure 14-9 Control Panel (Monitor Support Shipping Foam)
Figure 14-10 System Enclosures
Figure 14-11 Cart (Internal)
Figure 14-12 E-box Assembly
Figure 14-13 Transducer Connector Assembly (TCA) and E-box Motherboard (Front Side of E-box) 293
Figure 14-14 E-box Boards and Power Supply Access Panel (Rear-side of E-box)
Figure 14-15 Power Supply and BFC Board
Figure 14-16 E-box Boards
Figure 14-17 E-box Cooling Fans
Figure 14-18 Peripheral Bay Components
Figure 14-19 B/W Printer Bay
Figure 14-20 Hard Drive and CD Drive Rack
Figure 14-21 Power Transformer
Figure 14-22 Rear I/O Panel Assembly
Figure 14-23 Power I/O Box Assembly
Figure 14-24 Power I/O Box (PCB and Fuse Holder)
Figure 14-25 Power I/O Box (Inline Filter Power Cord and Cord Retainer)
Figure 14-26 Lift Mechanism (Mechlok Assembly and Gas Strut)
Figure 14-27 Peripheral Top Deck (VCR or Color Printer and MO drive)
Figure 14-28 Peripheral Mounting Plate (Uni-mount)

	age 24 ntents
Figure 14-29 System Casters	309
Figure 14-30 MO Drive	310
Figure 14-31 Foot Switch Assembly and Adapter Cable	311
Figure 14-32 RM-91 Sony Color Printer Remote Control Print Switch	312
Figure 14-33 R-3001 Mitsubishi VCR Wired Remote Control	313
Figure 14-34 System Labeling (HD3 System Nameplate)	314
Parts List	315
Table 14-1 HD3 Ultrasound System Parts List	315
Peripherals Parts List	320
Table 14-2 Peripherals and Applicable Cables	320
Transducers	322
Introduction	322
Table 15-1 C4-2 Information	323
Table 15-2 C5-2 Information	324
Table 15-3 C7-3 Information	325
Table 15-4 C9-4ec Information	326
Table 15-5 L9-5 Information	327

### **General Information**

#### Introduction

This section describes the contents of this manual and provides the following information:

- A general overview and physical description of the HD3 Ultrasound System (also referred to as the HD3 system or the system)
- A summary of system application, feature, and regulatory information

#### NOTES

- The information in this manual is based on the assumption that you are trained in the operation of this system and that you will operate it as intended.
- For detailed user information and instructions for operating the system, refer to the HD3 Getting Started manual.
- The instructions in this manual assume that the system language is set to English.

# More About This Manual

This manual is organized as follows:

- Section I, "General Information": Provides a general overview of the HD3 system and this document.
- Section 2, "System Specifications": Provides a summary of the system specifications.
- Section 3, "Safety": Identifies the safety information and is required reading.
- Section 4, "Theory of Operation": Provides a functional description of the system: A breakdown of the system functional elements and a description of their relationships and basic principles of operation (how the system works).
- Section 5, "Installation": Provides step-by-step initial delivery pre-installation and installation instructions for the system.

- Section 6, "Performance Tests": Provides tests that determine functional confidence and ensure that the system is operating as intended at initial installation and after upgrades or repairs.
- Section 7, "Adjustments": Provides brightness and position adjustment information for the system monitor. There are no calibration or alignment adjustments to make in the field for this system. There are no voltage adjustments to make in the field for this system.

Section 8, "Preventive Maintenance": Identifies activities supporting the quality assurance

- audit (QAA) concept that you should perform in accordance with Customer Field Service policy.
- Section 9, "Troubleshooting": Provides information about troubleshooting, backing up and restoring, software and device driver loading, and managing system options.
- Section 10, "Disassembly": Provides specific information about system disassembly that may be required for the removal and installation of field-replaceable parts. If not covered by a detailed procedure, the means of removing a system part can be discerned from the illustrations in this section as well as from those in Section 13, "Configuration" and in Section 14, "Parts". Instructions for crating the system for shipment are also included.
- Section 11, "Cabling": Provides system signal and power interconnect information, cable part number information, and (sold-with-system) peripheral connection diagrams.
- Section 12, "Change History": Chronicles the software and hardware changes associated with specific software releases.
- Section 13, "Configuration": Lists all the released software version part numbers for the system, identifies the primary system electronics, and shows where each circuit board is located in the system. When applicable, additional circuit board reference information is provided.

- Section 14, "Parts": Provides field-replaceable part numbers and information for the system
  parts that are not dependent upon system features and software versions (primary circuit
  boards and certain hardware assemblies). Call your Philips representative for the core information you need to determine the compatibility of primary system PCBs and certain hardware assemblies with respect to the system software releases.
- Section 15, "Transducers": Summarizes general and part number information for the transducers that can be used with the HD3 system.

# System Overview

The HD3 system, shown in Figure 1-1, is intended for general imaging. The cart is ergonomically designed to be both highly mobile and adjustable for a range of users and operating conditions. The HD3 system uses an embedded computer featuring the Linux operating system.

HD3 operators can measure anatomical structures and generate reports for health-care professionals. The system has a basic set of imaging modes and measurement tools and supports up to five transducers. There are optional modes and measurement tools that are available only when a specific mode or an analysis package is purchased and enabled for customer use. Options and upgrade security is controlled through the use of system-specific passwords and software.

- See "Applications" on page 29.
- See "Modes" on page 29.
- See "Transducers" on page 30.
- See "Options" on page 31.

#### Figure I-I

#### **HD3 Ultrasound System**



3D

M-mode

2D

- Pulsed-wave (PW) spectral Doppler
- Color flow
- Color Power Angio (CPA) imaging
- Duplex mode and Simultaneous mode

C4-2

C5-2

C9-4ec

• C7-3

• L9-5

### Languages

The system software supports the following languages at initial release:

English

• French

• German

Italian

Spanish

### Options

loaded into every system and because most of the system options are "software only" features, each system can have whatever software options the customer purchases enabled at the factory or, with the correct key-codes, on site. Purchased hardware options are shipped with the system.

The HD3 system software contains all of the available software options. The same software is

The following options are available for this system at initial release:

#### **Software Options**

- Image Review
- DICOM networking
- Freehand 3D (shown on the system as an option, but is currently enabled in every system shipped)
- Harmonic Imaging (shown on the system as an option, but is currently enabled in every system shipped)
  - Color Flow

#### **Peripheral Options**

See "Peripherals" on page 32.

#### Figure I-2

#### **HD3 Ultrasound System Image Printers and VCR**



**UP-21MD Sony Color Printer** 



HS-MD3000UA/EA Mitsubishi Video Cassette Recorder



UP-895MD Sony Graphic Printer (Black and White)

Figure 1-3

4535 612 34161

**CSIP Level I** 

#### HD3 Ultrasound System Data Media



CD-RW Drive



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**CSIP Level I** 





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tem (Figure 1-1) consists of a cart, a user interface (control panel), a visual display (video monitor), and the ultrasound electronic components. Other important physical components are the power circuits, software and data storage devices, and the system input/output (I/O) connection panel.

See Section 4, "Theory of Operation" for a functional description of these system components.

Cart

The cart is made up of a base and framework that provides a chassis on which all system components are installed and interconnected.

Swivel-casters at the four corners of the cart base provide system maneuverability and braking. The front casters can be fixed straight and locked, or unlocked, by foot-operated wheel locks to mobilize or immobilize the system as needed.

System Control

**Panel** 

The control panel (Figure 1-5) is a replaceable, self-contained module.

#### **HD3 Ultrasound System Control Panel**



#### **System Monitor**

The video monitor (Figure 1-1) is a non-interlace 26.4 cm (10.39-in) color TFT LCD display that is mounted on a mechanism that allows tilt and swivel positioning of the display.

## Ultrasound Components

The physical components that comprise the primary ultrasound elements of the system are the Transducer Connector Assembly and the E-box circuit boards. See Section 13, "Configuration" for pictures and locations of these system components.

#### **Transducer Connector Assembly**

The Transducer Connector Assembly (TCA) has the transducer connectors (contained in metal shielding) that interconnect to the E-box Front End board.

#### E-box

The E-box is a card cage that houses the ultrasound signal generation and echo acquisition circuits. The following ultrasound system electronic circuits are contained in the E-box:

- E-box Motherboard (backplane)
- Front End (FE) Assembly
- Beamformer (BF) Board
- Beamformer-to-Front End Connector (BFC) (physically and electronically connects BF and FE boards)

The system electronic power components are the Isolation Transformer, Power Supply, and the

drive (HDD), CD-RW drive, and when installed, the optional magneto-optical disk (MOD) drive.

- Digital Scan Converter (DSC) Board
- PCC Board (embedded computer)

Components

Power I/O Assembly.

See Section 14, "Parts" for illustrations and locations of these system components.

Software and **Data Storage** Components

**System Power** 

The software and data storage components (Figure 1-3) are physically comprised of the hard disk

Physical cables provide system signal interconnect and power distribution. Refer to Section 11,

For information about applicable safety standards and specifications, see the HD3 Getting Started

**Device Safety** The HD3 Ultrasound System complies with the following requirements for the International Electrotechnical Commission (IEC), the Canadian Standard Association (CSA), and the Under-Requirements writers Laboratories (UL). and IEC60950/EN60950 for data processing equipment Regulatory IEC 60601-1/EN 60601-1 for medical equipment

IEC 60601-1-1/EN 60601-1-1 for medical equipment

"Cabling", for detailed cable information.

CSA22.2 No. 601.1

manual shipped with the system.

UL 2601-1

**HD3 Service Manual** 

4535 612 34161

**Compliance** 

**Cables** 

Open Source

**Software** 

License

102 First St. South
Kalona, IA 52247-9589

Phone: (800) 445-6741, Ex. I for Customer Service (USA)

+1 319-656-4447 (International)

Fax: (877) 329-2482 (USA)

+1 319-656-4451 (International)

E-mail: info@civcomedical.com
Internet: www.civco.com

The HD3 system uses an embedded computer featuring the Linux operating system, parts of which are open source software. The following notification is included in the customer's Operating Notes:

**CIVCO Medical Instruments** 

Instruments:

which are *open source* software. The following notification is included in the customer's Operating Notes:

This Philips ultrasound system may contain "open source" software. According to the terms of the General Public License, a recipient may request a copy of any GPL-licensed source code modules present in the system, for the cost of shipping and handling. Please contact your local customer service representative for additional information.

The "additional information" is that the customer is entitled to a copy of the operating system software and that you can order it for them if they want it. The part number for the HD3 system Open Source Software is 453561228511.

#### 2 System Specifications

#### Introduction

4535 612 34161

CSIP Level I

This section summarizes the system specifications for the HD3 Ultrasound System. For transducer specifications, see Section 15, "Transducers".

#### **Physical Specifications**

The physical dimensions and weight of the HD3 are as follows:

- Height:
  - Lowest position: 1,280 mm (50.4 in)
  - Highest position: 1,455 mm (57.3 in)
- Depth: With no peripherals: 798 mm (31.4 in)
- Width: With no peripherals: 505 mm (19.9 in)
- Weight: Less than 61.2 kg (135 lb.) including monitor, and without peripherals.

#### **Electrical Specifications**

The electrical specifications of the HD3 are as follows:

- AC input: 90 to 264 Vac, 47 to 63 Hz
- Ground impedance: 100 m $\Omega$  maximum
- Load: 1.150 VA maximum.
- AC output (including PC): non-sinusoidal 120 VRMS, 350 VA maximum

### mental **Specifications**

4535 612 34161

CSIP Level I

**Environ-**

The environmental specifications for the HD3 system are as follows:

- Operational:
- Temperature range:  $10^{\circ}$ C to  $+40^{\circ}$ C ( $+50^{\circ}$ F to  $+104^{\circ}$ F)
  - Relative humidity: 15% to 95% non condensing
  - VCR and printers temperature limit: 10°C to +40°C (+50°F to +104°F) at 80% RH
  - Altitude: 697 hPa to 1013 hPa (0 to 10,000 feet) at 35°C (95°F)
- Storage:
  - Temperature range:  $-20^{\circ}$ C to  $+60^{\circ}$ C ( $-4^{\circ}$ F to  $+140^{\circ}$ F)
  - Relative humidity: 15% to 95%, non condensing
  - Altitude: 572 hPa to 1013 hPa

#### System PC **Specifications**

Table 2-1 lists the PCC hardware specifications.

Table 2-1 **Embedded PC Hardware Specifications** 

Table 2-1	Embedded i C Hardware Specifica
Component	Specification
OS	Linux
Memory	128 Synchronous DRAM
Hard drive	80 GB
VGA	640×480
ROM	2 Mbit Flash BIOS
Network Interface	10/100 Mb/s Tx
Keyboard	PS/2
•	·

 Table 2-I
 Embedded PC Hardware Specifications (Continued)

Component	Specification
Mouse	PS/2
IDE port	Enhanced IDE interface

#### Monitor Specifications

The monitor specifications are:

- Type: TFT LCD
- Size: 10.4 inch
- Pixel Pitch: 0.33mm x 0.33mm
- 640 x 480 VGA at 60 Hz
- Color Depth: 8-bit, 262,144 colors
- Power Consumption: Total 3.5 Watt

#### Image Formats

4535 612 34161

**CSIP Level I** 

The following image storage formats are supported by each HD3 storage device (Table 2-2):

Table 2-2Supported Image Formats

Device	Format			
	BMP	JPEG	TIF	DICOM
Hard Drive	Χ	X	X	X
Flash Memory	Χ	X	X	X
CD R/W	X	X	Х	Х
MOD	Χ	X	X	X

### 3 Safety

#### Introduction

This section summarizes the safety information for the HD3 Ultrasound System.

## **About Safety Information**

Please read this and related information before using or servicing a Philips ultrasound system. It applies to the ultrasound system, transducers, recording devices, and any optional equipment.

This system is intended for use by, or by the order of, and under the supervision of a licensed physician qualified to direct the use of the device.

In this manual, **WARNING** is used to indicate the presence of a hazard that can cause personal injury, death, or substantial property damage if the warning is ignored.

In this manual, **CAUTION** is used to indicate the presence of a hazard that can cause equipment damage if the caution is ignored.

In this manual, **NOTE** is used when additional comment or explanation is required about installation, operation, or maintenance information that is important but not necessarily hazard-related.

# General Operating Safety

Read the *HD3 Getting Started* for detailed safety and standards information for the HD3 Ultrasound System. This guide includes critical information about the intended uses of the HD3 system, patient and operator safety, and device standards. This is information that maintenance personnel should be aware of.

# Electrical Safety

with Type BF and Type CF isolated patient-applied parts and Type B accessories. For maximum safety observe these warnings:

#### WARNINGS

- Do not connect the ultrasound system to the same circuit used for life-support devices.
- Shock hazards may exist if this system, including all externally mounted recording and monitoring devices, is not properly grounded. Protection against electrical shock is provided by grounding the chassis with a three-wire cable and plug. The system must be plugged into a grounded outlet. The grounding wire must not be removed or defeated.

To avoid risks of electrical shock and fire hazards, inspect the system power cord and plug on

- a regular basis. Ensure that they are not damaged in any way.
  Do not remove the protective covers on the system; hazardous voltages are present inside.
- Cabinet panels must be in place while the system is in use. All internal adjustments and replacements must be made by a qualified Philips Ultrasound field service engineer.
- Do not operate this system in the presence of flammable gases or anesthetics. Explosion can result from electrical ignition.
- To avoid risk of electrical shock hazards, always disconnect the system from the wall outlet before cleaning the system.

#### WARNINGS

4535 612 34161

**CSIP Level I** 

- To avoid risk of electrical shock hazards, always inspect transducers before use: Check the face, housing, and cable before use. Do not use if the face is cracked, chipped, or torn; the housing is damaged; or the cable is abraded.
- To avoid risk of electrical shock, do not use any transducer that has been immersed beyond the specified cleaning or disinfection level.
- All patient-contact devices, such as transducers, pencil probes, and ECG leads must be removed from the patient contact prior to application of a high-voltage defibrillation pulse.
- Connection of optional devices not supplied by Philips Ultrasound could result in electrical shock. When such optional devices are connected to your ultrasound system, ensure that the total system earth leakage current does not exceed 300 µA.
- Avoid placing the system in an environment that may produce electrostatic discharges (ESD) that could affect the ultrasound system performance. (Electrostatic discharges can cause the ECG heart rate display to increase by 10% to 15% for a few seconds after the discharge, even though the ECG heart rate display returns to normal within a few seconds. See "About Electrostatic Discharge" on page 51.)
- Avoid placing the system in an environment that may produce electromagnetic interference (EMI) that could impact the diagnosis of a patient. (Only a physician can determine if an artifact caused by radiated interference has a negative impact on image quality and the subsequent diagnosis.) See "Avoiding EMI and RF" on page 48.

**CAUTION** 

other electrical devices used within the same room or an adjacent room. Communication devices such as cellular phones and pagers can cause these emissions. The existence of radio, TV, or microwave transmission equipment located nearby can cause emissions. In cases where EMI is causing disturbances, it may be necessary to relocate your system.

Electrosurgical units (ESUs) and other devices intentionally introduce radio frequency (RF) electromagnetic fields or currents into patients. Because imaging ultrasound frequencies are also in

being used, to identify possible sources of radiated emissions. These emissions could be from

tromagnetic fields or currents into patients. Because imaging ultrasound frequencies are also in the RF range, ultrasound transducer circuits are susceptible to RF interference. While an ESU is in use, the noise generated can severely interfere with the black-and-white image and completely obliterate the color image.

Avoid placing the system in an environment that may produce electrostatic discharges (ESD) that could damage the ultrasound system. (See "About Electrostatic Discharge" on page 51.)

### Mechanical Safety

Although the system is designed to be mobile, remember that it is very heavy, and that you must take precautions when moving it. The physical aspects of this system present a hazard that can cause injury, property damage, or equipment damage if the following information is ignored:

#### WARNINGS.

- Before moving the system, be sure to power it off, remove any loose equipment from the top of the system, disconnect the system power cord, and disconnect all external devices. Move and secure external devices away from the system.
   Make sure the control top is locked to prevent its up/down movement and uplock the caster.
  - Make sure the control top is locked, to prevent its up/down movement and unlock the caster locks before moving the system. Push with the handle at the front of the cart. After the system is in position, engage the caster locks to immobilize the system.
- Be aware of the casters as well as the extremities of the system when moving it. The system
  is heavy enough in any configuration that it can cause injury to you or others. Exercise additional caution when going up or down inclines.

When attempting to overcome an obstacle, do not push the system with enough force to

- cause it to tip over. Do not exceed 10 degrees of incline.
- Never park the system on an incline.
- For transport, make sure the control top is locked and secure the system so that it cannot roll or tip. Engage the caster locks and use wheel chocks and restraining straps. Do not attempt to hold the system in place manually. Never strap or secure the system at any point on the control top or monitor.

#### CAUTIONS

- Ensure that the cables for all patient-applied parts are secure before moving the system. Use the cable management system to ensure that transducer cables are protected from damage.
  - Do not roll the system over transducer cables or power cables.
- If the system behaves abnormally after moving or transporting, contact Philips Ultrasound Customer Service immediately. The components can withstand considerable shock, but excessive shock can cause a system failure.

# General Equipment Protection

Follow these additional precautions to protect the system from damage:

#### **CAUTIONS**

dedicated solely for the ultrasound system.

For optimal performance, the ultrasound system should be connected to a power circuit

- Verify system and peripheral power sources are appropriate before connecting to them.
- Avoid placing the system in an environment that may produce electrostatic discharges (ESD) that could damage the ultrasound system. See "About Electrostatic Discharge" on page 51.

Excessive bending or twisting of cables on patient-applied parts may cause failure or intermittent operation of the system. Take care not to run over cables with the system, which may damage them.

In general, only the area of the transducer acoustic window is watertight. Except where

- specified in specific transducer cleaning instructions, do not immerse the remainder of a transducer in any liquid.
- Practice proper cleaning or sterilization of a patient-applied part to avoid damage.
- Do not submerge the cables of patient-applied parts in solution. The cables are not liquidtight beyond the applied part/cable or cable/connector interfaces.
- Do not use solvents such as thinner or benzine or abrasive cleaners on the system, transducers, video monitor, touch screen, or any printer.

**About Electro-**

static Discharge

Electrostatic discharge (ESD), commonly referred to as a static shock, is a naturally occurring phenomenon. ESD is most prevalent during conditions of low humidity, which can be caused by

heating or air-conditioning. During low-humidity conditions, electrical charges naturally build up

on individuals and can create static shocks. An ESD condition occurs when an individual with an electrical energy buildup comes in contact with objects such as metal doorknobs, file cabinets, computer equipment, and even other individuals. The static shock or ESD is a discharge of the electrical energy buildup from a charged

individual to a lesser or non-charged individual or object. The level of electrical energy discharged from a system user or patient to the ultrasound system can be significant enough to cause damage to the system or transducers. The following precautions can help to reduce ESD: antistatic spray on carpets; antistatic spray on linoleum; antistatic mats; or a ground wire connection between the system and the patient table or bed.

#### **ESD Safeguards**

Follow these general ESD guidelines to minimize deterioration or destruction of ESD-sensitive electronic components:

- Avoid working in carpeted areas.
- If you use a vacuum cleaner to clean the interior of any part of the system sensitive to static electricity, take the necessary ESD precautions to avoid static buildup and discharge.
- Use a properly grounded wrist strap.
- Use a grounding mat for assembly work on sensitive areas.

#### **Symbols**

The International Electrotechnical Commission has established a set of symbols for medical electronic equipment that classify a connection or warn of potential hazards. The classifications and symbols are shown below.

#### Symbols on the System

大	Isolated patient connection. (Type BF)
	Isolated patient connection for applied parts in direct contact with major vessels. (Type CF)
Ф	Identifies the On/Off button on the system control panel.

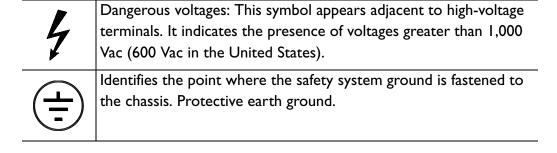
ı	On the system AC Mains power switch, "I" represents on and
ı	"O" represents off.
$\cap$	
$\wedge$	This symbol identifies a safety note. Ensure you understand the
/▼\	function of this control before using it. Refer to the appropriate
<u>_ · \</u>	section of the system documentation for an explanation of the
	control.
	The patient-applied part provides a degree of protection from
	electrical shock. This symbol indicates that the patient-applied part
	is defibrillator-proof. The patient-applied part is suitable for all
	patient applications including direct cardiac applications.
-	Identifies fuse location. For continued protection from fire or
	shock, replace only with the same type and rating fuse.
	Identifies equipotential ground.
$\bigvee$	
	Indicates that this device is protected against vertically falling water
IPx-I	drops.
	игорь.
	Indicates that this device is protected against the effects of fluid
IPx-7	immersion. This degree of protection can apply to transducers and
	the foot switch.
	the foot switch.

$\sim$	The connector near this symbol receives alternating voltages.
AUX POWER ISOLATE OUTPUT	This isolated output auxiliary power is provided for connection of the Philips-approved remote accessories.
$\left( \left( \stackrel{(\bullet)}{\blacktriangle} \right) \right)$	Indicates that interference may occur in the vicinity of equipment marked with this symbol.
	ESD (electrostatic discharge): The product is marked with this symbol to warn the user not to touch exposed pins. Touching exposed pins can cause electrostatic discharge, which can damage the product.
H9 <b>1</b>	This product consists of devices that may contain lead or mercury, which must be recycled or disposed of in accordance with local, state, or federal laws.
X	Indicates separate collection for electrical and electronic equipment in compliance with the Waste Electrical and Electronic Equipment (WEEE) Directive.
£3	Do not throw away. Dispose of in accordance with local, state, or federal laws.

R	Right and left audio output.
L	Color composite video output.
$ \longrightarrow$	
	Microphone input.
$\longrightarrow$	S-Video connection.
B/W	Black-and-white composite video output.
P-P-	Ethernet connection.
<b>€</b>	Universal Serial Bus (USB) input/output port.
>	Foot switch connection.
	ECG input.

	External VGA connection.
	Print trigger.
س	Date of manufacture.

The following symbols are used inside the system:



4535 612 34161

**CSIP** Level I

The following symbols appear on the product packaging to indicate environmental considerations:

#### Symbols on the Product Packaging

<u>م</u>	Atmospheric pressure range of 700 to 1,060 hPa for transport and storage.
<b>%</b>	Relative humidity range of 20% to 90% (noncondensing) for transport and storage.
1	Ambient temperature range -20°C to +60°C (-4°F to +140°F) (noncondensing) for transport and storage. (Does not apply to media).

### Theory of Operation

#### Introduction

This section provides a functional overview of the HD3 Ultrasound System by breaking down the system into functional elements and describing their relationships and basic principles of operation.

## System Architecture

The HD3 system architecture is made up of the following basic functional elements:

- Physical assemblies comprising the mobile cart and system components
- Electrical power functions
- Ultrasound signal generation and control functions
- Echo acquisition and control functions
- Signal and image data processing and analysis functions
- Image display and audio presentation functions

# Operating System

A Linux operating system (OS) provides an integrated range of resources: drivers and handlers for storage, video, serial and parallel ports, and support of file system services and graphical user interfaces. The OS is resident on the hard drive. The system software performs these tasks:

- Processes requests from the control panel
- Sets up beamforming parameters
- Processes acquired ultrasound echoes into digital visual representations for conversion into analog signals
- Performs measurements and calculations on acquired data
- Stores acquired data (such as images and user-entered data) for subsequent retrieval

# Functional Description

components comprise digital beamformer technology that combines with the operating system to support the system functions.

The HD3 system stores the ultrasound images and patient data on the hard drive and can copy that data to the removable media, such as magneto-optical drive (MOD) disks, CD-R and

The HD3 system produces ultrasound images using transducers, digital beamforming, and Doppler processing. The central processing unit of the system is the PCC Board. The ultrasound

CD-R/W disks, and USB flash memory sticks for off-system review. The system can send the images to a black-and-white printer, color printer, or to a VCR. It also generates reports that can be printed.

After operating power is applied, the major functional elements combine to produce ultrasound

images. The user interface allows system control and viewing of the results.

The overall system functional flow is power development and distribution, analog signal process-

ing, beamforming, continuous-wave and color Doppler processing, scan conversion, digital signal processing, and video and audio presentation.

The HD3 system ultrasound engine physically and functionally comprises five primary circuit boards, the TCA (page 63), the FE (page 63), the BF (page 63), the DSC (page 63), and the PCC (page 64). Most of the ultrasound signal processing, image processing, analysis, and display functions are performed by software using the native processing power of the embedded computer of the PCC Board.

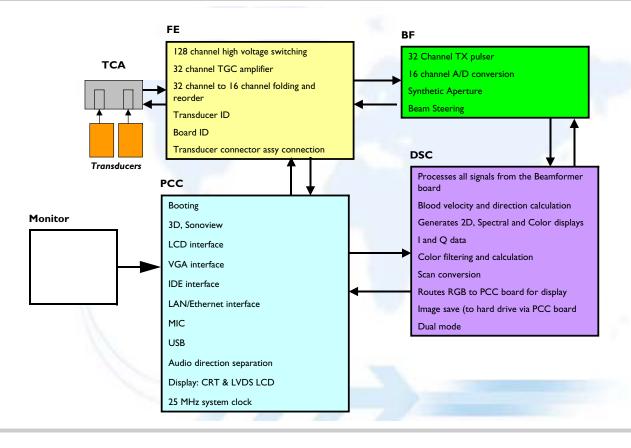
Figure 4-1 is a simplified block diagram of the HD3 system, showing the relationship between the primary circuit boards and indicating the major functional tasks performed by each.

Figure 4-1

**CSIP Level I** 

4535 612 34161

#### **HD3 System Functional Block Diagram**



## Functions

ultrasound electronic components. Other important physical components are the power circuts, software and data storeage devices, and the system input/output (I/O) connection panel.

The location and identification of the physical parts of the system are described in the General Information, Cabling, Configuration, and Parts sections of this document. The functional nature of each is described in the following paragraphs.

System power development and distribution is provided by the installation site source voltage, the system isolation transformer, power supply, backplane power bus, and power interconnect

tem consists of a cart, a user interface (control panel), a visual display (video monitor), and the

System Power

cables.

#### System Power Supply

- Input Voltage: (auto sensing)
- 100-120 Vac ±10%
- 200-240 Vac ±10%
- 50/60 Hz

4535 612 34161

**CSIP Level I** 

- Output Voltage:
  - + 3.3 Vdc
  - + 5 Vdc
  - 5 Vdc
  - + 12 Vdc
  - + 12 Vdc
  - + 97 Vdc
  - - 97 Vdc
  - + HV (+ 20 to + 80 Vdc)
  - - HV (- 20 to 80 Vdc

The system power supply has these features:

- Fault Protection: The AC outputs are fault-protected from an overload condition (including turn-on surges). The AC input may be cycled to restore power.
- Overcurrent Protection: All outputs have overcurrent protection to protect damage to the power supply from overcurrent load or short circuit conditions. Latched AC outputs will be reset once the input power is cycled. The latched DC output will be reset if the input power is cycled.

#### **Power Distribution**

System power distribution diagrams are shown in Figure 11-2.

The Transducer Connector Assembly (TCA) is the transducer select module, providing the sys-

tem interface for two transducers (see Section 15, "Transducer Information"). It works with the

FE Board for transducer detection and identification, engaging the appropriate number of relays

**Beamformer** The Beamformer Board is responsible for generating and transmitting pulses for the transducer (BF)

The DSC Board is multi-functional, performing functions supported by separate circuit boards in

**DSP** functions:

Receives all signals from BF board

Calculates blood velocity and direction

elements. When the returning echoes come back into the system, they are sent in analog form through the FE to the Beamformer (via the Beamformer Connector Board that bridges and

larger systems. The DSC performs the functions of a digital signal processor, digital scan con-

verter and real time clock, and video manager.

**Digital Scan** Converter

The signal processing functions of digital beamforming that determine the real image quality of the system include dynamic apodization, multiplication, coefficient loading, variable sample clock generation, and dynamic gain control.

converted into digital data. Once the data is digitized, specialized circuits perform the beam forming and steering.

(DSC)

interconnects the FE and the BF boards) for processing, where they are filtered prior to being

**Board** identification and enable function, and downloads operational parameters from the PCC, providing real-time control of the transmit, receive, and beamforming functions.

to accommodate transmitting and receiving pulses and echoes. Front End (FE) The Front End Board provides the physical and electrical interface to the TCA, the transducer

**Transducer** 

**Connector** 

Assembly (TCA)

Video management functions:

- From DSC output to Main Monitor
- Image Save (save image at HDD by PC)
- Color Keying (VGA data + image data)
- Post Mapping (control image curve)

**HD3 Service Manual** 

- D 1M 1
- Dual Mode

- Edge Enhancement

The PCC Board is similar to the motherboard used in a personal computer. The PCC acts as a central processing unit, performing further processing of the image data, including the generation of the image display to the screen. The PCC also serves as the main controller of the other boards and as the organizer of all of the image management functionality.

Page 64

**Theory of Operation: Functional Description** 

The PCC determines system functionality and coordinates the overall communication between the user and the system, which includes storing and saving images. The PCC communicates continually with the hard drive for operating parameters and hosts the following functions:

- ....,
- USBBattery
- VGA

4535 612 34161

CSIP Level I

PCC Board

Page 65

PCI Interface Non-interlace to VGA conversion Non-interlace to interlace conversion Doppler sound

E-box Backplane

Input/Output

**User Interface** 

**Panel** 

4535 612 34161

The Backplane (Motherboard) is the physical and functional "backbone" of the ultrasound engine. It is connected to the power supply, from which it receives DC operating voltages to distribute to the system components via a power bus and power cabling. The Backplane also pro-

cabling. The FE, BF, DSC, and PCC boards are all plugged into connectors on the Backplane. The I/O Panel at the rear of the system includes a circuit board that accomplishes the intercon-

nection between system components and peripheral devices (see Figure 11-5 for connection descriptions).

The user interface comprises the controls, indicators, and output devices of the system. The control panel (in conjunction with the monitor displays) is the primary operating interface

**HD3 Service Manual** 

with the ultrasound system. The footswitch, with freeze and display change functions, is an

extension of the control panel. The control panel consists of TGC slide pot controls, trackball, additional system control knobs and buttons, and a QWERTY keyboard. An internal interface PCB reads all of the control inputs, determines the function that has been selected, and transmits that information to the PCC for processing.

vides control and signal interconnection between the system components via buses and signal

Page 66

**Theory of Operation: Functional Description** 

**HD3 Service Manual** 

4535 612 34161

**CSIP Level I** 

**CD-RW**The CD-RW drive, housed in the system enclosure and connected to the PCC by an EIDE cable, is a removeable-media device used for image and report archiving and system upgrading.

Magneto-optical

The MOD drive, an external device that connects to the PCC via one of the I/O panel USB connectors, is a removeable-media device used for image and report archiving.

Drive

Flash Memory

The flash memory stick, an external device that connects to the PCC via one of the I/O panel

USB connectors, is a removeable-media device used for image and report archiving.

#### 5 Installation

#### Introduction

4535 612 34161

CSIP Level I

This section contains pre-installation and installation information for an FSE-install of the HD3 Ultrasound System. FSE installation consists of a pre-installation site check, uncrating and unpacking the system, physically installing the VCR or color printer if purchased, and verifying that the system is configured properly. Read this section completely before starting the system installation. The instructions in this section assume that the system language is set to English.

**NOTE** Some customers may be offerred the option to install their own system. Customers electing to install their own system will be provided with an HD3 Ultrasound System Installation User Guide, which starts with the assumption that all pre-installation actions are complete, that the system and system accessories have been uncrated and unpacked, and that the system does not have the DICOM option enabled.

### Installation

Use the following checklist to review what steps are necessary for proper system installation and to verify that you have performed them all.

Checklist

Perform a pre-installation site check (page 68).....

Check physical access for delivery and installation (page 68).....

Perform electrical and environmental checks (page 69)......

Uncrate and unpack the system (page 70).....

Assemble the system (page 72).....  $\Box$ 

Install the peripherals (page 72)..... □

Page 68

Inspecting the Installation Site	

**Physical Access** 

for Delivery and

Checking

Installation

system.

Check that the installation site is physically acceptable as follows:

Set or verify the institution name, user language, and time and date settings (page 73 through Verify system options (page 76)..... 🖵 Configure the DICOM/connectivity network, if required (page 77)...... Configure other system settings (optional) (page 87)......

Present the system (page 88)......

Conduct an inspection of the site prior to system installation to ensure a trouble-free installation and to assist the customer in providing an environment that supports reliable performance of the

- With the customer, evaluate site access for delivery. Consider the availability of a loading dock, elevators, ramps, and the width of passageways and doors.
- Verify that there is adequate space available for system uncrating and installation.
- At each location where the system will be operated, verify that there is enough space for the system and any external peripherals.
- Check adjacent rooms for activity and types of equipment that might negatively affect the ultrasound system.

Verify that the system is to be installed and operated in a room or rooms that meet the electrical

If the system DICOM feature will be used, it will be necessary to have the following connectivity

#### Requirements **Gathering Site Network** (DICOM) **Information**

Checking

**Electrical** and

**Environmental** 

information before entering the DICOM settings as described in "Configuring the DICOM Feature" on page 78.

and environmental requirements given in Section 2, "System Specifications".

#### **NOTE** If the system is to communicate over a network, the customer site network administra-

The customer or their contractor shall install network cabling. If in-wall cabling is used, it is the customer's responsibility to install the correct type of cable in accordance with all applicable

building and fire codes. It is also the customer's responsibility to maintain the in-wall cabling for

the life of the system. Determine and record the following network information for later DICOM configuration:

tor must be available to supply configuration data.

- Identify the system administrator (and backup person, if possible).
- Obtain the following information from the system administrator:
  - A list of all equipment that is part of the image management network. Also include device type, model number, and software version applicable to each piece of equipment.
  - Logical diagram of the network showing topology, subnets, and so forth.
  - Locations of equipment.
  - Locations of all DICOM Connectivity LAN attachment points.
  - Locations of power outlets and connector types.

- Locations of any dedicated analog phone lines.
- All necessary Internet Protocol (IP) addresses and subnet information.
- IP address, subnet mask, Port number, and DICOM AE Title for the HD3 system.
- IP Address, Port number, and AE Title for each DICOM server.
- Determine the type of network cabling installed.
- Identify OEM equipment installers and contact them regarding the installation.
- Check device compatibility prior to connecting new devices (such as, printers or archive devices) to the network.

Inspect the shipping container and uncrate the system as described in the following sections.

# Unpacking the System

**Uncrating and** 

Inspect the shipping crate before unpacking the system:

- Examine the shipping crate for damage. Look for evidence that the crate was opened.
- Verify that the Shockwatch and Tiltwatch indicators on the outside of the carton have not been activated. If the indicators are red, report this fact to the carrier and to the Philips Ultrasound traffic department. Be sure to check the system for damage when it is uncrated.
- Report any damage or missing inventory to the carrier and to the Philips Ultrasound traffic department.

**NOTE** Before uncrating the system, ensure the area in front of the shipping crate ramp is clear for at least 2.74 m (9 ft). (The ramp is the front side and is labeled "OPEN THIS END.")

### Inspecting the

Crate

Page 71

#### Uncrating

page 90. (Instructions for re-crating the system for shipment are provided in Section 10, "Disassembly".)

Uncrate the system by following the instructions in "Uncrating the HD3 Ultrasound System" on

#### Inspecting the **System**

After the system is uncrated ("Uncrating the HD3 Ultrasound System" on page 90), conduct the following inspections. Report any damage or missing inventory to the carrier and to the Philips Ultrasound traffic department.

Dangerous voltages are present inside the system. Do not install the system power cord or connect it to AC line voltage until correct line voltage has been verified, a thorough inspection of the

#### WARNING

➤ To inspect the system after uncrating

system has been performed, and the system has been properly assembled.

- Inventory the shipment against the packing list.
- Inspect the outside surfaces of the system, monitor, and peripherals for damage.
- Unlatch and rotate the control panel to verify that proper left and right swivel and up/down movement.
- 4. Verify that the system rolls and turns smoothly on its casters.
- Verify that proper caster brake and swivel operation.
- Remove the system covers.
- Remove any loose packing material, dust, or debris from the interior of the system.
- Verify that there is good continuity between the power supply and system ground.

mended settings (refer to "Peripheral Settings" on page 266).

printer or VCR installation instructions ("To install the color printer" on page 105, or "To install

already installed, install the system power cord by following the instructions in "To install the sys-

the VCR" on page 111). If the system comes with a footswitch, you will need to connect it. Follow the footswitch installation instructions ("To install the foot switch" on page 119).

Installing the

Cord

**System Power** 

**Powering On** 

and Config-

uring the

**System** 

**NOTE** The peripherals come from the factory already configured with the Philips-recom-

After the system has been inspected and properly assembled, if the system power cord is not

tem power cord" on page 121. When physical installation is complete, it is necessary and important to verify that the system is

properly configured. switch is pushed in) and then plug the system power cord into a proper AC outlet. Push the AC

After the system has been inspected and properly assembled as instructed in this section, verify that the green AC Mains power switch (Figure 11-6) is in the off position ("O" label on rocker

Mains power switch to the on position ("I" label on rocker switch is pushed in) and then press,

Page 73

tem.

Basic initial configuration is addressed in the following sections. For detailed user information

Basic initial configuration is addressed in the following sections. For detailed user information and instructions for configuring and operating the system, refer to the HD3 Getting Started manual.

## Verifying the Local Settings

#### ➤ To check or set the institution name

I. Press **Setup (FI0)**.

The Setup window opens (Figure 5-1).

2. In the Setup window, click **Local**.

Type in, verify, or change the name of the institution.

At this (or a later time) you can also specify whether or not the Caps Lock setting is to be on or off at startup and whether or not to have the system automatically create a medical record number for new patients. See "Configuring Other System Settings" on page 87.

Figure 5-1 Setup Window (System)

4535 612 34161

**CSIP Level I** 

System	Measure	DICOM	Option	Peripherals	Admin
Local	Display				
Institution					
Date 24/03/2005	Set	Time 13:53:57	Set	2 J	
J YYYY-MM J MM-DD-Y T DD-MM-Y	<b>YYY</b>	☐ 12 Hour			
Language English	\ <u>A</u>	*	aps Lock Statu	s	MRN Creation
		, OII		Save	Cancel

CSIP Level I

- ➤ To verify or set the system time and date
- I. Press **Setup (FI0)**.

The Setup window opens (Figure 5-1).

- 2. In the Setup window, click **Local**.
- 3. In the Date and Time segments, select the desired date and time format.
- 4. In either the Date or Time segment, click **Set**.

The Date and Time setup window opens.

- In the Date and Time setup window, click the up or down arrows to specify the current year, month, day, hour, and minute.
- 6. Click OK.
- 7. Click Save.
- ➤ To change the user interface language
- I. Press **Setup (FI0)**.

The Setup window opens (Figure 5-1).

- 2. In the Setup window, click **Local**.
- 3. In the Language segment, select the desired language.

The selected language will not take effect until the system is rebooted.

**CAUTION** 

Verifying the

**System Options** 

## 3. Option rows showing a checkmark and a **Lock** button, indicate that the option is active. Ver-

Click **OK**. Click Save.

authorization codes).

If an incorrect password is entered and okayed, the available option becomes unavailable.

identifier), from the top left corner of the Option window, when requesting option

dialog box that opens. It is necessary to have the System Key (based on the hard drive

a. Click the corresponding **Unlock** button and enter the option code in the Unlock Code

ing to activate an option:

(option must be purchased to obtain an Unlock code from the factory). Perform the follow-

ify that these options correspond to those that the customer is entitled to according to the sales order. 4. Option rows without a checkmark and having an **Unlock** button, are not yet activated

2. Click the **Option** tab.

The Setup window opens (Figure 5-1).

The Option setup window opens (Figure 5-2).

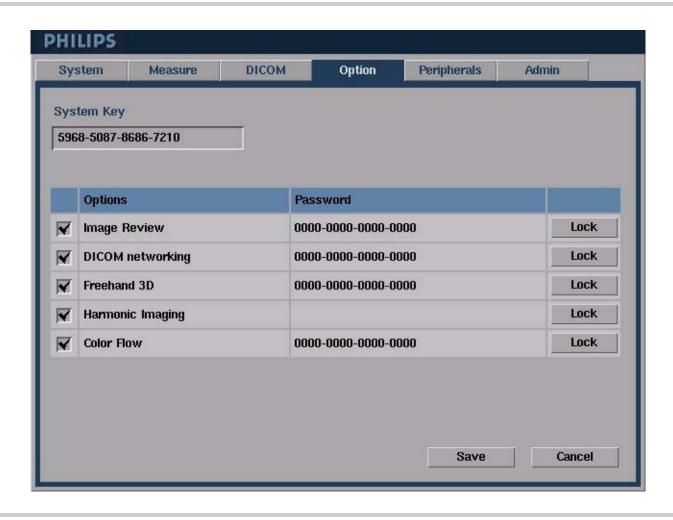
(password) to activate system options in the field.

➤ To verify or activate system software options I. Press **Setup**.

HD3 systems leave the factory with all available software options onboard. All purchased options are activated, those that haven't been purchased are not. Verify that the activated options are those that the customer ordered. You must have the correct authorization code

Figure 5-2 Setup Window (Option)

**CSIP Level I** 



## Configuring the DICOM Feature

4535 612 34161

**CSIP Level I** 

If the system you are installing has the DICOM option, you or the customer will need to configure the system DICOM feature. Since configuring the system for DICOM operation requires specific information from the customer network administrator (see "Gathering Site Network (DICOM) Information" on page 69), Philips recommends that you work with the customer to configure the DICOM feature with the specific values that need to be entered. At initial installation, refer the customer to the HD3 Getting Started manual, which has instructions for viewing, setting, or changing DICOM information and gives a description of each field in the "Glossary." The basic steps for initially configuring the system for DICOM communications over a network

are as follows:

- I. Enter the system DICOM parameters:
  - Enter the AE Title, Station Name, and Port number for the HD3 system (page 78).
  - Enter the network settings for the HD3 system (page 80).
- 2. Identify the DICOM storage devices (servers) that the system will use (page 80).
- 3. Identify the DICOM printers that the system will use (page 80).
- 4. After the DICOM feature has been configured, you may want to test the communication between the system and a server or a printer that was entered.(page 83).
- 5. Configure the DICOM Log file settings (page 83).

#### ➤ To configure the system DICOM parameters

I. Press Setup.

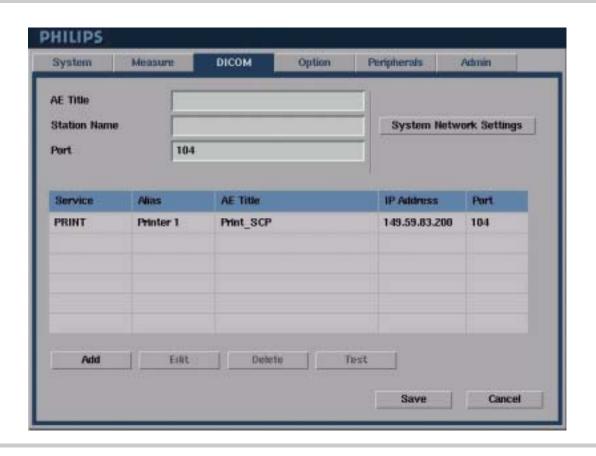
The Setup window opens (Figure 5-1).

2. Click the **DICOM** tab.

The DICOM setup window opens (Figure 5-3).

3. Enter the AE Title, Station Name, and Port number for this HD3 system. You will need to re-boot the system in order for the AE Title change to take effect.

#### Figure 5-3 Setup Window (DICOM)



CSIP Level I

4. Click System Network Settings.

The System Network Settings window opens (Figure 5-4).

- 5. View or enter the Network properties for this HD3 in the corresponding fields. If you enter properties, click **Apply** when finished, otherwise click **Close**.
- ➤ To identify the DICOM storage devices that the system will use
- 1. Click **Add** in the DICOM setup window (Figure 5-3).

The Server Configuration window opens (Figure 5-5).

- 2. Select STORE from the **Service** menu.
- Enter all of the parameters for the storage device.
- Click **OK**. 4.
- 5. Repeat step I through step 4 for each storage device the system will use.

**NOTE** You can configure multiple storage devices and printers, but the system will send only to the storage device and the printer selected.

#### ➤ To identify the DICOM printers that the system will use

1. Click **Add** in the DICOM setup window (Figure 5-3).

The Server Configuration window opens (Figure 5-5).

- 2. Select PRINT from the **Service** menu.
- Enter all of the parameters for the printer.
- 4. Click OK.
- 5. Repeat step I through step 4 for each storage device the system will use.

**CSIP** Level I

System Network Settings Window (DICOM)

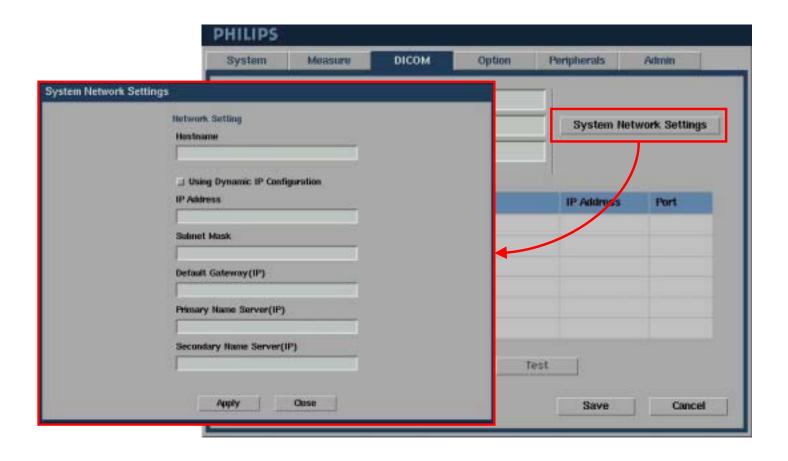
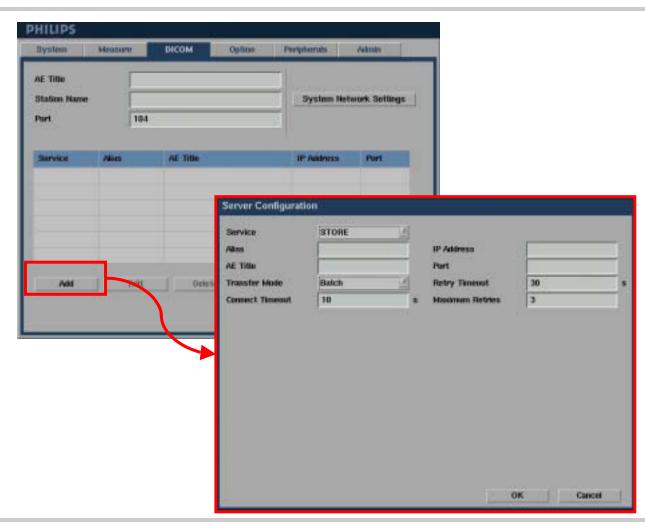


Figure 5-5 **Server Configuration Window (DICOM)** 



CSIP Level I

- ➤ To test the communication between the system and a server or a printer
- I. Press **Setup**.

The Setup window opens (Figure 5-1).

2. Click the **DICOM** tab.

The DICOM setup window opens (Figure 5-3).

- 3. Highlight the device that you want to test.
- 4. Click **Test** to initiate a DICOM verify ("ping") test signal from the system to the device. The test will produce a results message similar to one of the examples shown in Figure 5-6.
- ➤ To configure the DICOM Log file

## **NOTE** The defaults for the DICOM logging parameters are reasonable for most circumstances. Do not change the settings unless you have a specific troubleshooting need.

I. Press **Setup**.

The Setup window opens (Figure 5-1).

2. Click the **Admin** tab.

The Admin setup window opens (Figure 5-7).

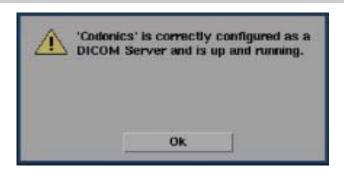
3. Click (DICOM Log) Open.

The DICOM Log window opens (Figure 5-8).

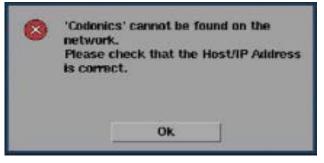
- 4. Enter the DICOM Log parameters and click **Close**.
- 5. Click **Save** on the the **Admin** tab.

**CSIP Level I** 

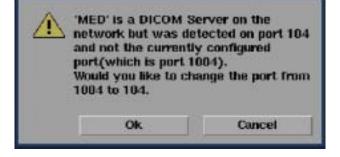
#### **DICOM Device Test Results Message Examples (DICOM)**



**Setup** is correct



Physical connection problem or wrong IP address



Wrong port number

Figure 5-7 Setup Window (Admin)

4535 612 34161

**CSIP Level I** 

HILIPS					
System	Measure	DICOM	Option	Puripharals	Admin
Presets	and Settings				
Backup Presets & Settings				Backup	
Restore Presets & Settings				Restore	
Softwar	re and Drivers				
Install Software				Install	3
Update Device Drivers				Update	
Service					
Display System Info			1	Show	
Keystroke Log			Open		
DICOM Log				Open	
Service Tools				Service	
				Save	Cancel

Figure 5-8 DICOM Log Window

4535 612 34161

**CSIP Level I** 

DICOM Log		
Log settings		
Delete archived log file after	31	days
Log file mædmum size (Kbytes)	100	
Explanation		
Delete log files older than 31 days.		
Start a new log when the current log reaches	100 Kbytes.	
DICOM Log		
Select log files to copy	Copy to	
2005-04-13 08:21:33 ~ 2005-04-13 15:46:53	17 KBytes	□ CD
		□ MOD
		□ USB Memory
		☐ Delete files after copy
		Copy selected files
		Delete Selected files
View selected file.		Close
The contract of the contract o		

# Other System Settings

Configuring

in the HD3 Getting Started manual to initially configure the system settings not yet set to the customer's preference. There are several categories of user setups:
System

If appropriate for this installation, work with the customer and follow the respective instructions

- System
- Measure
- DICOM
- Option
- Peripherals
- Admin

#### ➤ To configure other system settings

Refer to Section 6, "Customizing Your System," in the HD3 Getting Started manual.

# Preparing the Peripherals

Refer to Section 6, Customizing four system, in the HD3 Getting started manual.

Confirm that the system settings are appropriate for the installed peripherals.

HD3 peripherals are shipped and installed with their device settings set to the manufacturer's default values. Printer and VCR device settings can be checked as described in "Peripheral Settings" on page 266.

As applies, correctly load paper and ribbon in the printers and insert a tape cassette in the VCR.

Verify system functionality using the information in Section 6, "Performance Tests". If system testing reveals any problems, troubleshoot, repair, and retest the system before presenting it to the customer for use.

## Checking System Functionality

# Presenting the System

When the system is ready, present it to the operators:

chased and its options.

- Review the customer order with the customer to familiarize them with the system as pur-
- Review the "Read This First" section of the HD3 Getting Started manual with the customer. Show them the important safety and operating information that it conatins and that it itemizes what user information has been provided for their system and peripherals.
- Review any Operating Notes with the customer.
- Show the operators how to turn the system and any external peripherals on and off. Explain the importance of letting the system shut down completely before disconnecting the power cord.
- Explain the importance of cycling the power at least once a week on systems that are left on permanently.
- Instruct the customer how to back up and restore presets. Make a backup disk of the customer's presets and configurations, and store it where service staff and the customer can find it readily.
- Explain why it is important for them to never remove covers from the system because of ESD and warranty considerations.
- Review with the customer, procedures for placing service calls or calling for technical assistance.

### **Physical Installation Procedures**

Figure 5-1 Installation Procedure List



**Uncrating the HD3 Ultrasound System** 



**Monitor Support Shipping Foam** 



**Top-Mounted Color Printer** 



**Top-Mounted VCR** 



**MOD Drive** 



**Foot Switch** 



**System Power Cord** 



**B/W Printer Plate** (No-Printer Systems)

NOTE

The numbers in the installation illustrations correspond to the steps in the installation procedure.

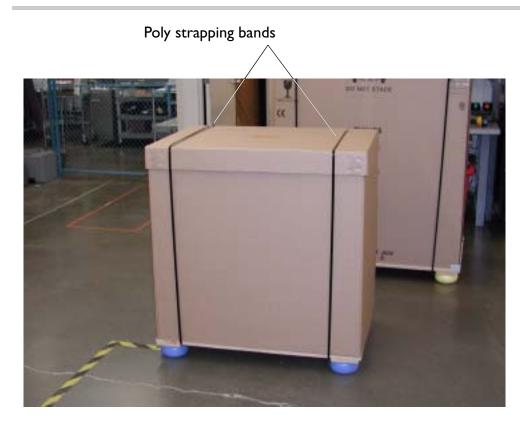
#### **Uncrating the HD3 Ultrasound System**

Figure 5-2

4535 612 34161

**CSIP:** Level 2

**Cutting the Poly Strapping Bands** 



To uncrate the HD3 Ultrasound **System** 

#### NOTES -

- Instructions for re-crating the system for shipment are provided in Section, "Disassembly (Removal) Procedures".
- Estimated time to uncrate the system is 10 minutes.
- I. Remove (cut) the two poly strapping bands from around the corrugated container.

**CSIP:** Level 2

#### **Removing the Corrugated Top Cover**



2. Remove the top cover from the corrugated crate.

4535 612 34161

**CSIP:** Level 2

#### Removing the Corrugated Wrap



3. Remove the one-piece corrugated wrap by lifting it straight up and over the crate ramp.

**CSIP:** Level 2

#### **Removing the Ramp Bolts**



4. Remove the four bolts securing the ramp to the pallet.

**CSIP:** Level 2

**Placing the Ramp** 

5 6





- 5. Lift the ramp off the pallet.
- 6. Turn the ramp around and place the ramp in front of the system with the beveled edge facing up.

Figure 5-7

**CSIP:** Level 2

#### Removing the System Hold-down Brace



7. Remove the hold-down brace securing the rear of the system.

4535 612 34161

**CSIP:** Level 2

Removing the Wheel Chock



8. Remove the wheel chock from the open (ramp side) of the crate.

**CSIP:** Level 2

#### **Rotating the Rear Casters**



9. Rotate the rear casters 180 degrees.

4535 612 34161

**CSIP:** Level 2

#### Rolling the System Off the Pallet



- 10. Ensure the ramp is properly aligned in front of the crate.
- 11. Unlock the front casters.
- 12. Lift the antistatic bag and position yourself on one side of the crate toward the front of the ultrasound system.
- 13. Grasp the control panel handle and carefully guide the system down the ramp and onto the floor.

4535 612 34161 **CSIP:** Level 2

#### Removing the Shipping Materials (Antistatic **Bag and Monitor Support)**

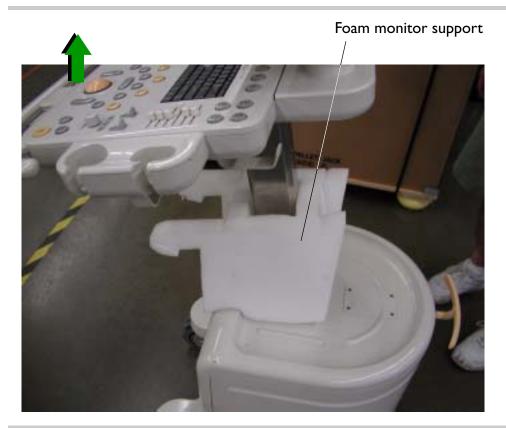


- 14. Remove the antistatic bag.
- 15. Remove the foam monitor support by sliding it toward the front of the system and off the control panel.
- 16. Tilt the monitor up to its vertical position.

4535 612 34161

**CSIP:** Level 2

Removing the Shipping Materials (Yoke Support)



- 17. Engage the handle trigger and raise the control panel to its highest point.
- 18. Remove the foam yoke support from around the lift column.
- 19. Inspect the system as described in "Inspecting the System" on page 71.
- 20. Dispose of the crate and packing materials properly.

**NOTE** Do NOT return the crate or packing materials to Philips.

Return to Installation Procedure List.

#### **Monitor Support Shipping Foam**

**CSIP:** Level 2

Figure 5-13 **Locking the Front Casters** 



To install the monitor support shipping foam

**NOTE** The monitor support shipping foam is used to protect the video monitor from shake stress during transport of the HD3 system in vans or by other means of transportation.

I. Lock both front casters by pressing down on each caster lock lever to prevent the system from moving while installing the foam shipping support.

**CSIP:** Level 2

4535 612 34161

Tilting the Video Monitor



2. Grasp both sides of the video monitor and tilt it toward the front of the system until it is in a horizontal position above the control panel.

4535 612 34161

**CSIP:** Level 2

#### **Placing the Foam Monitor Support**



Carefully slide the foam monitor support over the control panel. Ensure that the opening in the foam for the monitor is at the top.

**CSIP:** Level 2

#### **Securing the Video Monitor**



- 4. Align the video monitor with the cut-out in the foam support.
- 5. Slide the foam support further up the control panel allowing the monitor to slide through the upper cut-out.

Return to Installation Procedure List.

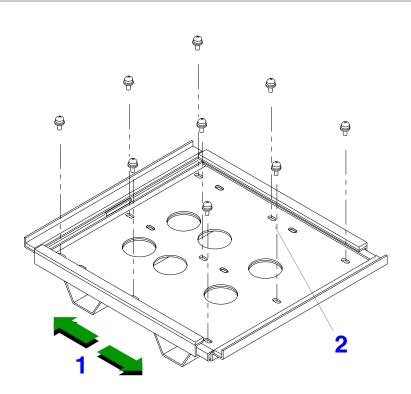
#### **Top-Mounted Color Printer**

Figure 5-17

4535 612 34161

**CSIP:** Level 2

Adjusting the Universal Peripheral Mounting Plate for the Color Printer

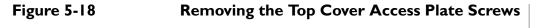


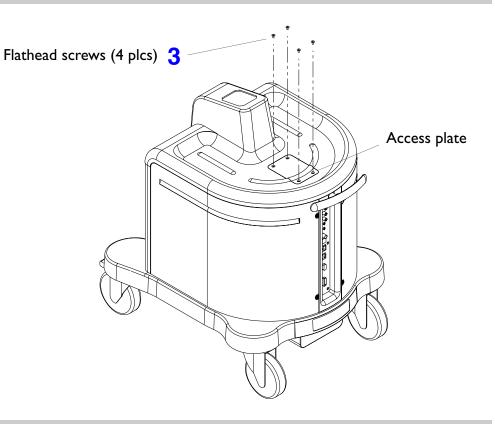
#### ➤ To install the color printer

**NOTE** Perform step I through step 5 only if the peripheral mounting plate is not already installed and sized correctly.

- I. Adjust the universal peripheral mounting plate to the correct size for the color printer.
- 2. Line-up the mounting holes so the screws fit through the proper holes shown.

**CSIP:** Level 2

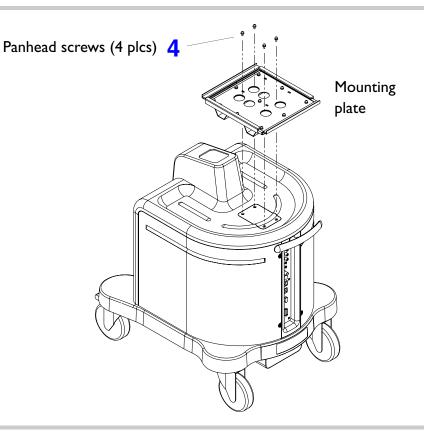




3. Remove the four screws securing the top cover access plate. Do not remove the plate.

**CSIP:** Level 2

Figure 5-19 **Installing the Universal Peripheral Mounting Plate** 



4. Install the universal peripheral mounting plate to the HD3 system top cover using four screws.

**CSIP:** Level 2

#### Installing the Mounting Strap on the **Universal Peripheral Mounting Plate**

Mounting strap 5



5. Thread the mounting strap through the appropriate slots in the universal peripheral mounting plate.

Figure 5-21

4535 612 34161

**CSIP:** Level 2

### Placing and Strapping the Color Printer to the Universal Peripheral Mounting Plate

6 **Placement** 



Strapped



- 6. Decide which side you want the color printer to face and place it centered on the mounting plate.
- 7. Strap the color printer to the mounting plate, tighten the straps, and secure the straps with the Velcro end.

Figure 5-22

4535 612 34161

8

**CSIP:** Level 2

### Cabling the Color Printer to the HD3 System



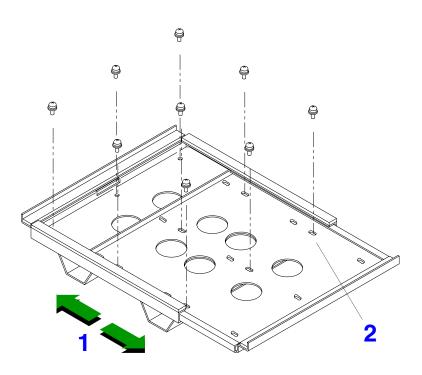
8. Install the color printer cables. Refer to Figure 11-2 for the top-mounted color printer cabling diagram.

### **Top-Mounted VCR**

4535 612 34161

**CSIP:** Level 2

Figure 5-23 Adjusting the Universal Peripheral Mounting Plate for the VCR



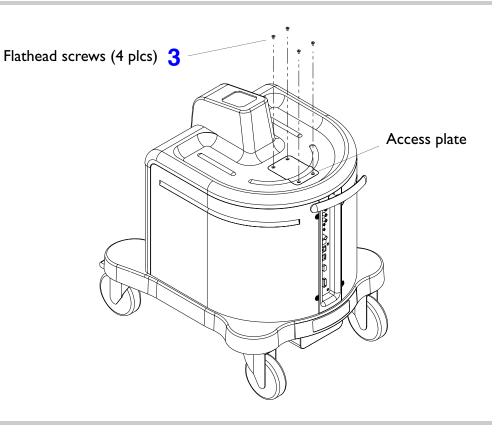
### ➤ To install the VCR

**NOTE** Perform step | through step 5 only if the peripheral mounting plate is not already installed and sized correctly.

- I. Adjust the universal peripheral mounting plate to the correct size for the VCR.
- 2. Line-up the mounting holes so the screws fit through the proper holes shown.

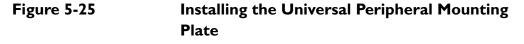
**CSIP:** Level 2

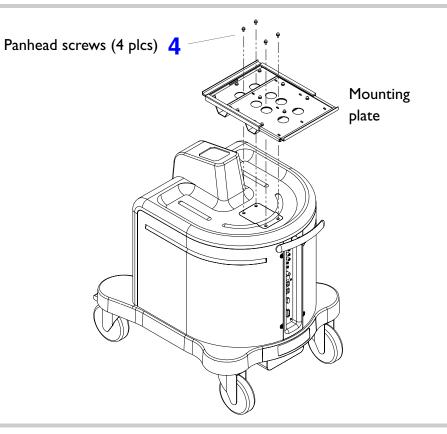
Figure 5-24 Removing the Top Cover Access Plate Screws



3. Remove the four screws securing the top cover access plate. Do not remove the plate.

**CSIP:** Level 2





4. Install the universal peripheral mounting plate to the HD3 system top cover using four screws.

4535 612 34161

**CSIP:** Level 2

### Installing the Mounting Strap on the **Universal Peripheral Mounting Plate**

Mounting strap 5



5. Thread the mounting strap through the appropriate slots in the universal peripheral mounting plate.

4535 612 34161

**CSIP:** Level 2

## Placing and Strapping the VCR to the Universal Peripheral Mounting Plate

6 Placement



**7**Strapped



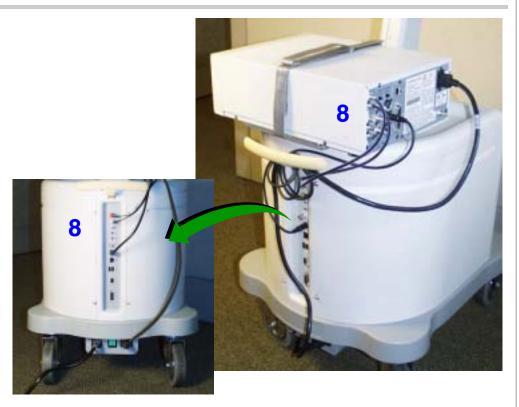
- Decide which side you want the VCR to face and place it centered on the mounting plate.
- 7. Strap the VCR to the mounting plate, tighten the straps, and secure the straps with the Velcro end.

Figure 5-28

4535 612 34161

**CSIP:** Level 2

### Cabling the VCR to the HD3 System



8. Install the VCR cables. Refer to Figure 11-3 for the top-monuted VCR cabling diagram.

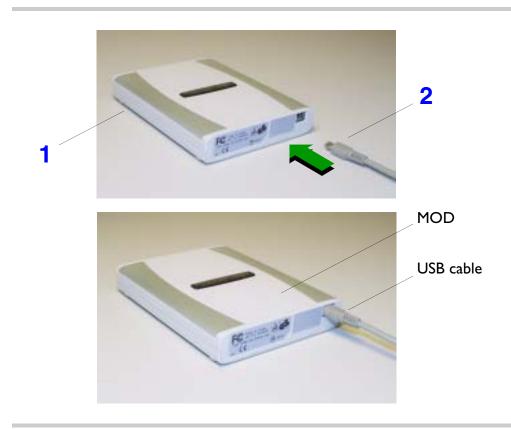
### **MOD Drive**

**CSIP:** Level 2

4535 612 34161

Figure 5-29

Connecting the USB Cable to the MOD Drive



### ➤ To install the MOD drive

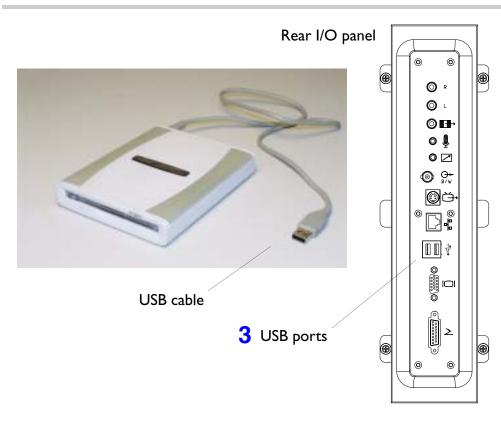
- I. Place the MOD drive on the HD3 system in a place that is preferable for your use. It is recommended that the MOD drive be mounted on a horizontal surface. Attach it with the velcro strips supplied with the MOD drive.
- 2. Connect the small connector end of the USB cable to the USB port on the rear of the MOD drive.

Figure 5-30

4535 612 34161

**CSIP:** Level 2

**Connecting the USB Cable to the HD3 System** 



3. Connect the USB cable to either of the two USB ports on the HD3 system Rear I/O Panel.

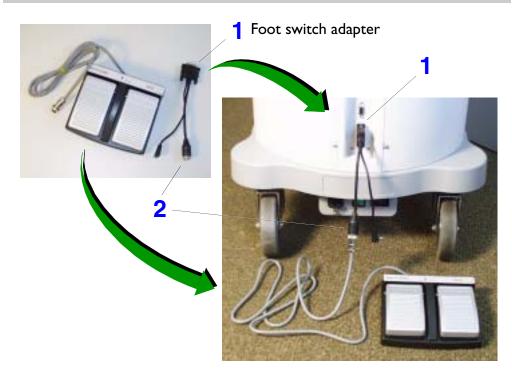
### **Foot Switch**

**CSIP:** Level 2

4535 612 34161

Figure 5-31

Foot Switch Cabling



Rear of system

### > To install the foot switch

- I. Connect the foot switch adapter to the lower foot switch serial port on the Rear I/O panel.
- 2. Connect the foot switch adapter round connector to the foot switch assembly cable.

4535 612 34161

**CSIP:** Level 2



Front of system

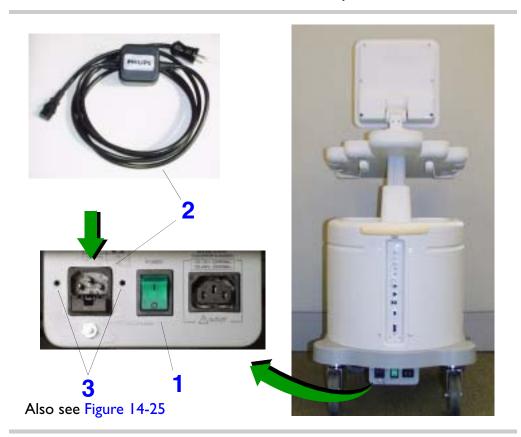
3. Place the foot switch assembly in front of the system where suitable.

### System Power Cord

4535 612 34161 CSIP: Level 2

Figure 5-33

Connecting the System Power Cord (Power Cord with Inline Filter)



### ➤ To install the system power cord

For installing a power cord with an inline filter, see Figure 5-33.

For installing a power cord with an additional inline filter power adapter cable, see Figure 5-34.

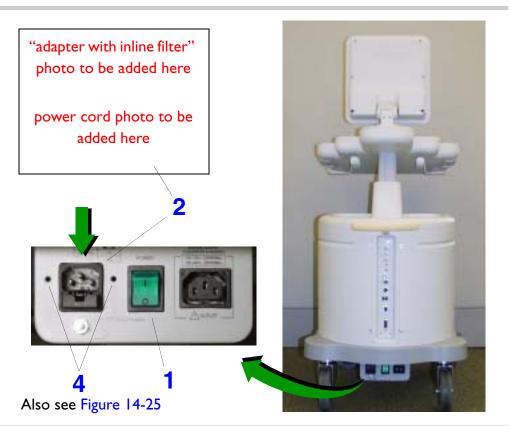
- Verify that the AC Mains power switch is in the off position (down: "O" is pushed in).
- Insert the system power cord that came supplied with the system into the power I/O box receptacle located at the lower rear of the system.
- 3. Install the power cord retainer bracket using two screws.
- 4. Connect the system power cord to the AC supply source.

Figure 5-34

4535 612 34161

**CSIP: Level 2** 

**Connecting the System Power Cord (Power** cord with Separate Inline Filter Power Adapter)



### ➤ To install the system power cord

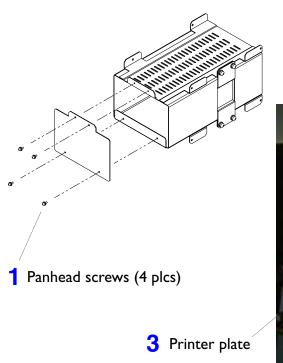
- I. Verify that the AC Mains power switch is in the off position (down: "O" is pushed in).
- 2. Insert the inline filter power adapter that came supplied with the system into the power I/O box receptacle located at the lower rear of the system.
- 3. Connect the system power cord to the inline filter power adapter.
- 4. Install the power cord retainer bracket using two screws.
- 5. Connect the system power cord to the AC supply source.

4535 612 34161

### **B/W Printer Plate (No-Printer Systems)**

Figure 5-35

B/W Printer Plate Storage





NOTE Most HD3 systems will be delivered with a B/W printer installed. Use these instructions if a B/W printer needs to be installed and you don't have the upgrade instructions.

- Remove the four screws securing the printer plate at the back of the printer bay.
- 2. Replace the two screws to the top of the printer bay.
- 3. Turn the plate upside-down and remount it to the printer bay so that it hangs below the bay and allows access for cabling the B/W printer. Install the two remaining plate screws from inside the printer bay.

Refer to Figure 11-1 for B/W printer cabling diagram.

### **6** Performance Tests

### Introduction

This section calls for examinations that determine functional confidence and ensure that the system is operating as intended at initial installation and after upgrades or repairs.

The goal here is to verify system functionality. If system testing reveals any problems, trouble-shoot, repair, and retest the system before presenting it to the customer for use.

# Warnings and Cautions

Review Section 3, "Safety" before continuing. Also follow any additional warnings and cautions contained in this section.

# Visual Inspection for Mechanical Integrity

At initial installation and after upgrades or repairs, inspect the systemcart, controls, cables, power cord, connectors, and transducers for outward signs of wear or physical damage that would suggest the system may not be able to function correctly and safely:

Check the system for abnormalities or conditions that do not meet as-manufactured specifi-

- cations.
- Ensure mechanical moving parts are functional and operate correctly:
  - Caster wheels all roll smoothly, both front wheel brakes lock.
  - User Interface Control Panel up/down movement can be actuated via the front handle latch mechanism. Movement in both directions is smooth.
  - The moveable controls operate smoothly.
  - Video Monitor can be tilted up or down and with the neck assembly can be rotated left and right or up/down while being able to hold position without sagging when the desired adjustment is completed.

Operate the system as Philips intended (refer to the HD3 Getting Started manual as required) all the time observing and verifying that the following is true while checking system modalities and

# Functionality

**System** 

basic operations:

Ongoing Observations

### Ongoing Observations

- The image is correctly positioned on the video display.
- The indicators and backlighting associated with the controls on the control panel indicate correctly.
- The system responds correctly to all controls, including the foot switch if applicable.

### System Modalities and Basic Operations to Check

- Every HD3 transducer purchased for the system can be connected and initialized in both transducer ports.
  - 2D
    - Color
    - ---
  - CPA
  - PW Doppler
  - M-mode
  - IM-mode
  - 3D
  - Connectivity
  - Review
  - Annotations
  - Body Markers
  - Body MarkeAnalysis

- **Peripherals** 
  - The image printers, if installed, make a print of the system screen: Print images are correctly positioned horizontally and vertically and contain all the information being displayed on the system monitor. The color of the printed image, if applicable, is accurate.
  - The VCR, if installed, records clear video and audio (check by playing back on a review station).
  - The report printer, if installed, prints and that all report information is present and legible.
- Image and patient data transfer to removeable media
- DICOM print and export (send)

Perform these tests after any service or maintenance to detect abnormalities that could prove dangerous to a patient or operator and to assure that system safety and functions have not been compromised:

**NOTE** No safety testing of the system is needed upon installation. Also, the system power supply is a self-contained unit that is safety-tested by its manufacturer, so no safety testing is needed when the power supply or system power cord is replaced. Safety testing need only be performed during the yearly Preventive Maintenance.

- The Chassis to Ground Resistance test checks the entire system for electrical resistance between the chassis and ground. See "Chassis to Ground Resistance Test" on page 127.
- The Ground Wire Leakage Current test checks the entire system for leakage on ground leads. See "Ground Wire Leakage Current Test" on page 129.

### **Electrical Safety**

4535 612 34161

CSIP Level I

- The Transducer Leakage Current test checks a transducer for electrical leakage while it is connected to the ultrasound system. The system sends normal operating voltages to the transducer, which is tested for leakage. See "To test transducer leakage current" on page 133.
- The Transducer Isolation Leakage Current test applies AC mains voltage to the leads to check a transducer for electrical leakage. See "Transducer Isolation Leakage Current Test" on page 134.

The limits referenced in these tests are prescribed by UL, CSA, and IEC. Local regulations may require additional tests.

Chassis to Ground Resistance Test This test checks the entire system for electrical resistance between the chassis and ground. Figure 6-1 shows the basic electrical concept of the ground resistance test. Use a safety analyzer and complete "To test the system for resistance between chassis and ground" on page 129.

### **WARNING**

Some users routinely perform a safety-earth or ground-bonding test at currents in excess of 10 A. Test currents in excess of 1 A will likely exceed the impedance limit specification, and can damage the RFI protection finger contacts. Exposed metal on the transducer assembly, including the connector, are for RFI and are not safety grounds.

### **CAUTION**

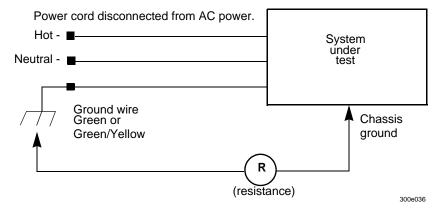
Do not use automated test equipment that will interrupt power to the ultrasound system without allowing the user to power down normally. Interrupting the system power while the system is powered-on can result in corrupted files and could render the system inoperative.

Figure 6-I

4535 612 34161

**CSIP** Level I

### **Chassis to Ground Resistance Test Diagram**



LIMIT: UL, CSA and IEC:R = 200 milliohms maximum

- ➤ To test the system for resistance between chassis and ground
- I. Inspect the power cord for cracks and wear.
- 2. Set the mode on the analyzer to measure resistance in the power cord.
- 3. Plug the analyzer into an available AC wall outlet. Plug the ultrasound system power plug into the test receptacle on the analyzer.
- 4. Make the appropriate connections between the analyzer and the ground lug on the ultrasound system's I/O panel.
- 5. Read chassis ground resistance in milliohms. Flex the ultrasound power cord during the test to detect intermittent changes in resistance value.
- 6. Record the highest resistance value measured in step 5. Check that the highest resistance value is within the limit specified in Figure 6-1. If the reading exceeds the specified limit, check the power cord and the associated primary wiring.

A comprehensive ground impedance measurement can be performed using the safety analyzer. The impedance test drives a load current through the ground wire while measuring the AC voltage drop across the entire length of the power cord and to the system chassis. The reading will be in milliohms.

### Ground Wire Leakage Current Test

This test checks the entire system for leakage on chassis ground wires. Figure 6-2 shows the basic electrical concept of the test. Use a safety analyzer and complete "To test the system ground wiring for leakage" on page 131.

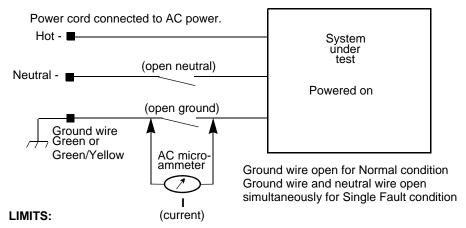
### **WARNING**

This test can be hazardous. Avoid any contact with line voltage. Any time during the test that the ground connection is open, do not touch the chassis or the patient cable.

### Figure 6-2

4535 612 34161 CSIP Level 1

### **Ground Wire Leakage Current Test Diagram**



UL: I = 300 microamperes Normal condition, 1000 microamperes Single Fault condition

CSA and IEC: I = 500 microamperes Normal condition, 1000 microamperes Single Fault condition

7ASW025

➤ To test the system ground wiring for leakage

for Normal condition in Figure 6-2.
4. Take ground wire leakage current measurements in an open ground and open neutral condition, with both normal and reverse polarity. Record the highest value, and compare it to the limit specified for Single Fault condition in Figure 6-2.

3. Take ground wire leakage current measurements in an open ground condition, with both

normal and reverse polarity. Record the highest value, and compare it to the limit specified

Page 131

**Performance Tests: Electrical Safety** 

A reading higher than acceptable limits can indicate a problem with the power cord, with its

associated connections, or with the power transformer.

This section describes two electrical leakage current tests for transducers. To ensure patient

safety, it is very important to verify the integrity of the insulating layers of all transducers.

When you perform the safety tests, use saline solution in a container as a conductive medium.

The solution penetrates any cracks or holes in the transducer insulation and provides an electrical path between the submerged lead wire and the inner transducer shield.

The following tools are required for these transducer safety tests:

- Safety analyzer
- Saline holder

**HD3 Service Manual** 

- ECG lead wire
- Saline solution. If saline is not available, mix 27 grams of table salt in 3 liters of tap water.

### Transducer Tests

4535 612 34161

**CSIP Level I** 

### **Transducer Leakage Current Test (Source)**

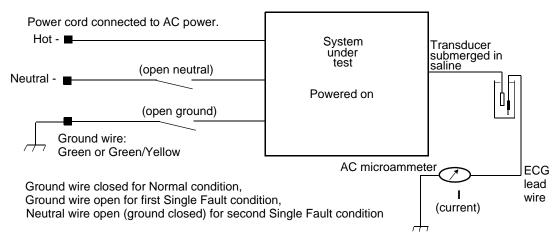
This test checks a transducer for electrical leakage while it is connected to the ultrasound system. The system sends normal operating voltages to the transducer, and leakage is measured using a safety analyzer. Figure 6-3 shows the basic electrical concept of the Transducer Leakage Current test. Complete the procedure "To test transducer leakage current" on page 133.

### Figure 6-3

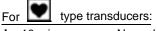
4535 612 34161

**CSIP Level I** 

### Transducer Leakage Current Test Diagram



**LIMITS:** UL, IEC, and CSA:



I = 10 microamperes Normal condition, 50 microamperes Single Fault condition



type transducers:

I = 100 microamperes Normal condition, 500 microamperes Single Fault condition

7ASW027

Page 133

### ➤ To test transducer leakage current

- I. Set the analyzer mode to test ECG leads.
- 2. Plug the analyzer into an available AC wall outlet. Plug the ultrasound system power plug into the test receptacle on the analyzer.
- 3. Turn on the ultrasound system.
- 4. Plug the transducer to be tested into the ultrasound system. Connect an ECG lead wire to the appropriate jack on the analyzer.
- 5. Fill a test container with enough saline to completely cover the appropriate parts of the transducer. Insert the exposed end of the ECG lead into the saline, and carefully insert the transducer. For transthoracic and endocavity transducers, submerge the head and 5 cm (2 in) of the cable. Be careful not to submerge the connector.
- 6. Set the analyzer to read leakage current in microamperes.
- 7. Read the current in both normal and reverse polarity, and record the highest value. Check that the highest value is within the limit specified for Normal condition in Figure 6-3. (Match the transducer type symbol on the transducer connector or cable with the symbol in the figure.)
- 8. Read the current with an open ground condition imposed, in both normal and reverse polarity. Write down the highest value; this is the value for the first Single Fault condition.
- 9. Read the current with an open neutral condition imposed, in both normal and reverse polarity. Write down the highest value; this is the value for the second Single Fault condition.

10. Check that the highest current value measured in step 8 and step 9 is within the limit specified for Single Fault condition in Figure 6-3. Values exceeding the limits may indicate a fault in the transducer housing or the cable sheath. To locate a fault precisely, repeat the measurement while slowly inserting the transducer into the saline. The aberrant reading appears when the fault in the cable enters the saline.

**CSIP Level I** 

**NOTE** Endocavity transducers have a grounded jacket just under the outer plastic skin of the cable. Their leakage currents can measure within the specified limits even if there is a fault in the outer skin. Step 11 tests for this condition.

11. In normal polarity with an open ground condition imposed, measure ground wire leakage (see "Ground Wire Leakage Current Test" on page 129). Compare this to the highest value for transducer leakage current, Single Fault condition obtained in step 10. If the transducer leakage is greater than 80% of the chassis leakage, there is a fault in the transducer. To locate the fault, slowly insert the transducer in the saline, as in step 10.

### **Transducer Isolation Leakage Current Test**

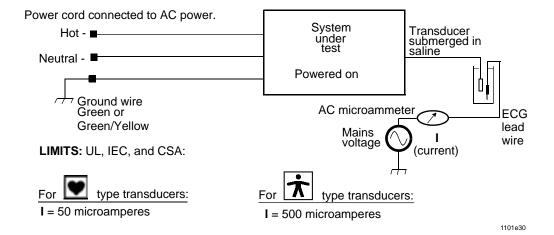
Figure 6-4 shows the basic electrical concept of the Transducer Isolation Leakage Current test. The transducer is submerged in a container of saline solution. AC Mains voltage is introduced into the saline solution, and leakage current in the transducer is measured using a safety analyzer. Complete the procedure "To test transducer isolation leakage current" on page 136.

### Figure 6-4

4535 612 34161

**CSIP Level I** 

### Transducer Isolation Leakage Current Test Diagram



### Transducer Isolation Leakage Current Test Procedure

### WARNING

This test is hazardous. It applies line voltage to the ECG and transducer cables. Avoid accidental contact with the line voltage. Do not touch the chassis or the ECG or transducer cables while performing the test. Keep the ECG and transducer cables at least 20 cm (8 in) from any grounded or conductive surfaces.

### ➤ To test transducer isolation leakage current

**NOTE** During this test, select only *normal* polarity. Do *not* impose open ground or open neutral conditions.

- I. Set the analyzer to test ECG.
- Plug the analyzer into an available AC wall outlet. Plug the ultrasound system power plug into the test receptacle on the analyzer.
- 3. Turn on the ultrasound system.
- Plug the transducer to be tested into the ultrasound system.
- Fill a test container with enough saline to completely cover the appropriate parts of the transducer.
- 6. Insert the exposed end of the ECG lead wire into the saline, and then carefully insert the transducer. For transthoracic and endocavity transducers, submerge the head and 5 cm (1.96 in) of the cable. Be careful not to submerge the connector.
- 7. Measure the isolation leakage current of the transducer. Record the value, and check that it is within the limit specified in Figure 6-4.

### **Adjustments**

### Introduction

4535 612 34161

**CSIP Level I** 

This section contains information for adjusting the system monitor. Except for the monitor, there are no other calibration or alignment adjustments to make in the field for this system. There are no voltage adjustments to make in the field for this system.

### Adjusting the **Monitor**

You can adjust the brightness of the monitor image to compensate for ambient light.

The only monitor adjustment is the video brightness, there are no adjustments for contrast, brightness range, or contrast range. Use the brightness controls on the control panel to set the brightness.

### ➤ To adjust the monitor brightness

Do either of the following to adjust the brightness:

- To increase the brightness, press **F12**.
- To decrease the brightness, press FII.

### **Positioning** the Monitor

You can adjust the position of the monitor to suit different operating positions and operator heights. The monitor can be tilted up and down, swiveled left and right. To position the monitor, grasp it by the sides and adjust the tilt and swivel to suit the operator.

Page 138

### **Preventive Maintenance** 8

### Introduction

4535 612 34161

CSIP Level I

This section identifies activities supporting the quality assurance audit (QAA) concept that you should perform in accordance with Customer Field Service policies and schedules. Refer to the HD3 Getting Started manual for additional information on the general care and preventive mainteneance of the HD3 system. QAA activities include, but are not necessarily limited to, the following types of concerns:

- System Mechanical Integrity
- System Performance
- System Electrical Safety
- System Cleaning

See Section 6, "Performance Tests" for information about checking mechanical integrity, system performance, and electrical safety.

### Warnings and **Cautions**

Review Section 3, "Safety" before continuing. Also follow any additional warnings and cautions contained in this section.

### Cleaning

Clean the system components and peripherals as circumstaces or Customer Field Service policies and schedules require.

### **CAUTION**

To avoid damaging the system, do not use acetone, methyl ethyl ketone (MEK), paint thinner, or other strong solvents to clean plastic surfaces.

**Assemblies** 

Interior

**Exterior** and

airflow passages and components associated with the fan assemblies, PCBs, and any other system components and peripherals that may have accumulated dust or dirt. Use mild, nonabrasive, standard computer-cleaning products to clean the monitor, keyboard, system, and peripheral surfaces.

Use a vacuum cleaner, compressed air, or soft-bristle brush to remove any lint and dust from the

### CAUTION

When cleaning the system keyboard and monitor, take care not to get any solution inside the housings. Also, take care not to scratch the face of the monitor while cleaning it.

### Trackball

Clean or replace the trackball as its condition warrants.

### ➤ To clean the trackball

- I. Unscrew and remove the bezel that surrounds the trackball on the system control panel.
- 2. Push the trackball up from the underside of the control panel to remove it.
- 3. Clean the trackball with an alcohol-dampened pad.
- 4. Clean the two encoder shafts and the bearing surface with an alcohol-dampened pad.
- 5. Reinstall the trackball and bezel.

### **Transducers**

Refer to the HD3 Getting Started manual for information on the general care, handling, cleaning, and storing of Philips transducers for the HD3 ultrasound system.

Page 140

**Preventive Maintenance: Warnings and Cautions** 

**HD3 Service Manual** 

soapy water.

4535 612 34161

**CSIP Level I** 

### 9 Troubleshooting

### Introduction

This section provides information about the following topics:

- Troubleshooting (page 141)
- Backing up and restoring system information (page 151)
- Loading application and device driver software (page 151)
- Managing system options (page 151)
- Viewing system information and logs (page 152)

# Warnings and Cautions

Review Section 3, "Safety" before continuing. Also follow any additional warnings and cautions contained in this section. Before taking any action that might cause data to be lost, back up data as described in "Backing Up and Restoring" on page 151.

### All Troubleshooting Starts Here

Reviewing and applying the following basic guidelines can produce effective troubleshooting and responsible call resolution. Even an experienced and successful troubleshooter who can solve problems without stepping through the Effective Problem-Solving Checklist (Table 9-1), might find it beneficial to review it. Always make notes as you troubleshoot; if properly communicated, some or all of the information you discover can help you or others in the future.

Table 9-1 Effective Problem-Solving Checklist

Basic Troubleshooting Step	Link to Detailed Guidelines
Identify the symptom	"Clarifying Symptoms" on page 142
Re-create the problem	"Re-creating a Problem" on page 143
Isolate the cause	"Isolating Causes" on page 143
Develop a solution	"Developing a Solution" on page 145
Perform a corrective action	"Implementing a Solution" on page 145
Verify that the system works	"Verifying Corrective Actions" on page 146
Put system in service and close the call	"Returning the System to Service" on page 147

# Clarifying Symptoms

4535 612 34161

**CSIP Level I** 

These actions and considerations can help to clearly describe a symptom, which is useful in isolating the cause and can also be useful later when documenting the problem and the solution. Make notes about the problem you are investigating as you read through this section:

- Have the user restate problem and verify that you are checking the correct system.
- Are there any other systems exhibiting this symptom or is it exclusive to one system?
- Is this the symptom of a real problem, or is it possibly an unrealistic expectation of the system features and options set?
- Clarify the symptom: Is it a hang, a crash, a shutdown, an image artifact, an error code, not booting, or other symptom? Write down a clear statement of what the symptom is and how it manifests itself:
  - How does it happen: What keystrokes, what modality, what preset, what transducer?

- When does it happen: Time of day, during boot-up, during scan, image review, sending to a network, during a calculation, during a measurement, playing/recording VCR, printing, acquiring an image, annotating, other?
  How often does it happen: Intermittently, predictably, all of the time?
- Categorize/localize the problem:
  - Is it a printing problem, an image quality or viewing problem, a data export or import problem, or other?
- Consider if the symptom indicates an operating procedural error or a system failure. If it
  is a system failure, determine whether it seems to be a hardware or software problem. If
  it is a software problem, determine if it is an operating system or ultrasound problem.

If possible, make hardcopy prints of the system displays that shows the first and subsequent

- indications of the failure. Do this as soon as possible to ensure this type of data is not lost. (Relevant data is often lost when the system is rebooted.)
- What, if anything, does the user do to recover from the problem?

**Re-creating a** Su

Successfully re-creating a problem that doesn't damage the system can produce information that is useful to troubleshooting and solution verification. But, before you try, be sure that you have noted all the useful information you can. Before changing anything, consider if the attempt will cause the loss of information or will change a circumstance that is better than re-creating the

problem. If you decide to attempt to re-create the problem, try to do so several times.

Isolating Causes

**Problem** 

Remember that, sometimes, more than one cause can produce similar symptoms. Try to identify as many causes for the given symptom as your experience and research allows and then prioritize them in order of most likely root cause of the problem. Attempt to eliminate them one-by-one, staring with the most likely cause.

### **Checking for Obvious Causes**

Check for the following obvious causes:

- Check for correct voltage at electrical outlets, "tripped" circuit breakers, blown fuses, and disconnected or damaged wires. Always check that power cords are plugged in, and inspect them for wear.
- Consider the situation: Was there a system option or hardware change recently? When was the last time the system was working correctly and what, if any, influencing circumstances have occurred since?
- Check if the symptom and probable cause may already be documented.

### **Investigating and Testing**

If you haven't discovered the cause of the problem yet, more in-depth analysis is necessary:

- Take a moment to review the data you've collected about the problem so far. Hopefully, you have been able to categorize the symptom as a hardware, software, operator-induced, or environmental failure.
  - Hardware failure: Cause usually determined through use of troubleshooting tools (RST, Device Manager, Debug Info, and Event Logs). A fix is typically realized by replacing suspect/candidate hardware until the problem is resolved.

**NOTE** Consider the value against the difficulties of swapping (suspect) hardware components with good ones. Do not cause additional problems or confuse your search. Never swap parts if a known good item might be damaged.

4535 612 34161

**Developing** a

**HD3 Service Manual** 

- a future release that might solve the problem. Environmental: Are there any electrical power, EMI/RFI, or network connectivity difficulties external to the system affecting its performance? Verify more easily checked factors first, such as system setup/configuration. If you haven't already, verify that all system voltages are present and within tolerance.
- Conduct tests from Section 6, "Performance Tests" as required to determine if and how the

pulling the plug, or other)? A solution can be more user training or a work-around. Investigate to see if an option ought to be enabled or if there is an enhancement scheduled in

Page 145

system is failing.

# When think you know what the problem is, decide what changes you need to make to correct the problem and write down the steps you want to take to make the repair, especially if the

Solution sequence of your actions is important. Even if you don't think you need to do this for yourself, it can be useful to others when you properly document the problem and its resolution. You may benefit from this yourself in the future. Implementing a Implement your solution by performing the corrective actions you developed. Proceed cau-**Solution** tiously and systematically. Make only one change at a time, and verify that the change you made

brings about the result you expected before making any other change. It is not unusual for another problem to surface when you are applying changes to fix what you thought was the problem. If the change didn't bring about the result you expected, consider if

sider returning the system to the known condition it was in before your last change and verify its condition before proceeding.

Review your solution and any "discovery" that your change produced. Decide if you should proceed with your original solution or go back to investigating and testing. To avoid producing con-

ceed with your original solution or go back to investigating and testing. To avoid producing confusing and conflicting data, do not deviate too far from the methodical approach that allows you to isolate the failure by eliminating possible causes along the way.

Verifying
Corrective
Actions

Once the system fault has been identified and you have performed (authorized) corrective actions to repair the failure, conduct whatever tests are necessary to ensure that the problem is fixed and that the system meets its optimum level of performance. Typically, it will be the same testing that led you to isolating the cause of the specific problem (refer to your notes) and then additional tests that give you confidence that the system is generally performing as it should.

CSIP Level I	Troubleshooting: Symptoms, Causes, and Corrective Actions
Returning the System to	Once the reported problem is fixed and the system tests are successful, return the system to the customer and close the call:
Service	<ul> <li>Formally document the problem and the solution: Write down exactly what problems you discovered and what corrections you made.</li> </ul>
	<ul> <li>Provide feedback: Communicate to all affected parties what problems you discovered, how you arrived at that conclusion, and what corrections you made. Include this information with parts that are returned for repair and, if appropriate, send e-mail with this information to ISS personnel who could find it useful.</li> </ul>
Symptoms, Causes, and Corrective Actions	Some problem considerations are documented here.
Disk is Full	In this release, the system does not automatically manage hard drive disk space. That is, studies are not automatically deleted as the hard drive disk becomes full. If the disk space alloted for studies is filled, the system may behave erratically or generate errors.

Page 147

**HD3 Service Manual** 

4535 612 34161

Disk is Full

In this release, the system does not automatically manage hard drive disk space. That is, studies are not automatically deleted as the hard drive disk becomes full. If the disk space alloted for studies is filled, the system may behave erratically or generate errors.

Checking for

Electromagnetic interference (EMI) and radio frequency interference (RFI) can degrade the performance of the HD3. For example, a transducer placed close to an ECG cable can increase interference. Moving the ECG cable or other medical equipment away from the transducer can reduce interference. EMI and RFI can conceivably cause image noise or monitor distortion if the system EMI shielding has been compromised. EMI and RFI can be generated by a variety of electrical devices. The interference can be transmitted over power lines or radiated through the air. Answering the following questions can help locate the source of interference and help determine whether the problem is with the system or with the scanning environment.

- DoesDo twIs theCan thDoes EMI/R noise
- Is the interference intermittent or constant?
- Does the interference appear with only one transducer or with several transducers?
- Do two different transducers operating at the same frequency have the same problem?
- Is the interference present if the system is moved to a different location in the facility?
- Can the EMC coupling path be attenuated?
- Does operating an AM radio tuned between stations around 1,600 Hz (thus using it as an EMI/RFI source tester) identify interference, which would be noticeable as audible static noise on the radio while walking it around the room. Sometimes EMI/RFI sources are not constant, but are temporary or surge situations that may only occur at certain times.
- Considering and locating the source/cause is important, but regardless of the source, since
  the system is shielded against EMI and RFI, troubleshoot the system to determine if the EMI/
  RFI shielding has been compromised. One place to start is to verify that all the system panels
  are appropriately secured with all of the factory-approved fasteners.

# System Hangs or Crashes

Often the terms "hang" and "crash" are used interchangeably to describe the same symptom. However, these two terms describe two different behaviors. It is important to understand the difference between these terms because the causes are different, the troubleshooting techniques are different, and the information available to the FSE is different.

A "hang" is when the system stops responding to the keyboard. There is a normal image on the monitor and the system may continue to be working (updated data in the image area, clock is correct and continues changing), but the system does not respond to hard keys, soft keys, or the trackball.

There is not any specific data associated with a "hang" (because from the software point of view, everything is behaving normally. The best source of information is to ask the customer about the keystrokes prior to a "hang." Also check the Keystroke Log.

A "crash" occurs when the system detects an abnormal condition in either the hardware or the software. A crash is an unexpected software event that causes the system to diaplay an error message and forces the user to re-boot the system.

**NOTE** Cycle power at least once a week if a system is left on permanently. (As the user presses buttons and different parts of the software are used, different segments of "virtual memory" are acquired and released. Virtual memory is handled on the hard drive and as it is used and released, it is subject to fragmentation. After a while, the virtual memory area can become fragmented into small pieces, so that there is no longer a large enough "chunk" for the system to do what is needed. If this happens, the system can crash.)

# DICOM/

Verify that the DICOM option is enabled (See "Verifying the System Options" on page 76.). If the DICOM option is enabled, verify that it has been configured correctly (See "Configuring the DICOM Feature" on page 78.), including the DICOM network test. When you test a network setting, the system performs two tests, "TCP/IP Ping" to verify that it can connect to the specified IP address and "DICOM Verify" (C-ECHO command) to verify that it can connect to the specified DICOM server.

If the TCP/IP Ping test fails, make sure the IP address and port number specified for the system and for the DICOM server are correct. If the DICOM Verify test fails, make sure the AE Title specified for the system and for the DICOM server are correct. The AE Title is case-sensitive; make sure it has been entered correctly.

If the DICOM server is using high-security settings, you may need to add the system AE Title and IP address to the server's list of systems that are authorized to access it.

### **Network Failures**

In addition to the messaging presented to you during Setup and Export, the HD3 has a DICOM log that records DICOM network activity. The DICOM log contains the following information:

- Service & Transfer Type
- The Called and Calling devices and their communication parameters
- Status of the export operation
- The number of images expected to be sent
- The number of images successfully sent
- The number of images that failed

You may want to view or copy the DICOM log (see "To display the keystroke or DICOM log" on page 153.)

Page 151

**Backing Up** and Restoring

Before you begin installing software, replacing a hard drive, or taking any service action that might cause data to be lost, perform the following tasks:

- Ensure that the customer has saved any important studies. If they have the Review option, back up patient exams as described in Section 12, "Review," of the HD3 Getting Started manual.
- Make a system backup as described in Section 16, "System Administration," of the HD3 Getting Started manual. System settings, DICOM (network) settings, and options are saved when you perform a backup.

Loading Software and **Drivers** 

Subsequent releases of the ultrasound application software will be available on CD ROM. Installation is accomplished by inserting the CD into the CD-RW drive and accessing the Admin screen as described in Section 16, "System Administration," of the HD3 Getting Started manual. The HD3 has the capability of updating device drivers without the need to upgrade or Ghost the

application software. This is also described in Section 16, "System Administration," of the HD3 Getting Started manual.

**Managing System Options** 

To manage system options, See "Verifying the System Options" on page 76.

# Viewing System Information and Logs

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**CSIP Level I** 

The HD3 has some software tools that are accessible to all users:

- Display System Info Displays system model number, serial number, and software version.
- Keystroke Log There is a keystroke log file that records the keystrokes made during operation. (In the first release, only "hard key" presses are recorded; Softkey presses and "mouse clicks" in Review mode are not recorded). Any user can view keystroke logs, as well as copy the log files to a CD, MOD, or USB flash memory drive. The keystroke log is always running, and as the current file becomes full, it is closed, renamed with a date-time stamp, and a new current keystroke log file is started.
- DICOM Log There is a log that records DICOM network activity. The DICOM log contains the following information:
  - Service & Transfer Type
  - The Called and Calling devices and their communication parameters
  - Status of the export operation
  - The number of images expected to be sent
  - The number of images successfully sent
  - The number of images that failed

As with the keystroke logs, you can view the DICOM logs, or copy them to CD, MOD, or USB flash memory drive.

Use the **Admin** tab in setups to display system information, and to view the keystroke and DICOM activity logs. Use **Keystroke Log** and **DICOM Log** to specify log settings and to view log files, copy log files onto removable media, and to delete log files.

- ➤ To display system information
- I. Press Set Up (FI0).
- Click the **Admin** tab.
- In the Service area, click **Show** to display system information.
- 4. Use the scroll bars to view the system information.
- 5. Click **Close** when done.
- ➤ To display the keystroke or DICOM log

I. Press Set Up (FI0).

- 2. Click the **Admin** tab.
- In the Service area, click **Open** to open the keystroke or DICOM log.
- 4. In the dialog box, do the following:

ple keystroke logs.

- Enter the number of days a log file should be active. For example, if you enter 31 days, the log file is deleted when it becomes older than 31 days.
- Enter the maximum size of the log file in kilobytes.
- 5. To view a log file, select the log file and click **View selected file**.
- 6. To copy a log file or files, select the file or files, select the removable media destination, and click Copy selected files.

**NOTE** You can view only one keystroke log at a time. However, you can copy or delete multi-

- 7. To delete a file after copying, select the **Delete files after copy** check box.
- Click Close.

### **Disassembly** 10

### Introduction

This section provides specific information about system disassembly that may be required for the removal and installation of field-replaceable parts. If not covered by a detailed procedure, the means of removing a system part can be discerned from the illustrations in this section as well as from those in Section 13, "Configuration" and Section 14, "Parts". Instructions for crating the system for shipment are also included.

### Warnings and **Cautions**

Review Section 3, "Safety" before continuing. Also follow any additional warnings and cautions contained in this section.

### WARNING

Always turn the power off, disconnect the main power cord from the wall outlet, and wait at least 30 seconds before removing or installing any PCB, module, or component.

### **CAUTION**

Always use correct ESD procedures. ESD damage is cumulative and may not be noticeable at first. ESD symptoms may be first exhibited as a slight degradation of performance or image quality.

**NOTE** The batteries inside this product contain mercury and must be recycled or disposed of according to local, state, and federal laws. Do not replace individual batteries in the field. Return all products containing mercury to Bothell for disposal.

Refer to Figure 10-1 for links to disassembly procedures by specific part.

### Disassembly (Removal) Procedures

Figure 10-1 **Disassembly Procedure List (1 of 2)** 

**NOTE** Unless otherwise noted, reassembly is essentially the reverse of the disassembly procedure.



### **System Enclosures**



**Video Monitor** 



**Control Panel** 



**VCR** or Color Printer



**Universal Peripheral Mounting Plate** 



Peripheral Bay (B/W Printer, **Printer Bay, CD/Hard Drive** Rack, and Power Transformer)



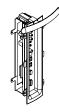
E-box Bay (E-box Assembly, **Transducer Connector** Assembly, E-box Boards, Power **Supply and Cooling Fans)** 

NOTE

The numbers in the installation illustrations correspond to the steps in the disassembly procedure.

List Continued

Figure 10-2 **Disassembly Procedure List** (2 of 2)



**Rear I/O Panel** 



**Power I/O Box** 



Lift Column Gas Strut



The numbers in the installation illustrations correspond to the steps in the installation procedure.



**System Casters** 



**Crating the HD3 Ultrasound System** 

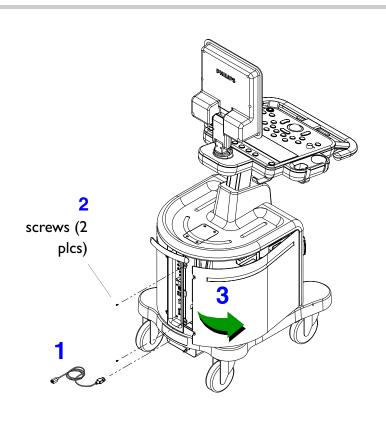
**Previous List** 

### System Enclosures

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**CSIP Level 2** 

Figure 10-3 Removing the Left Side Enclosure

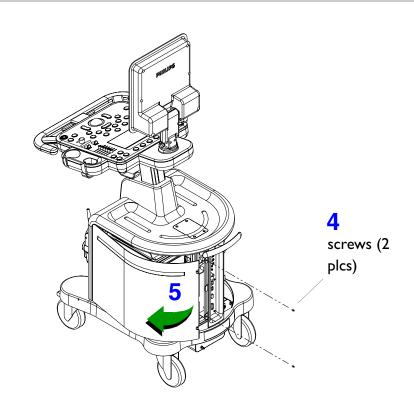


NOTE The two side enclosures must be removed before removing the front enclosure or top cover.

- ➤ To remove the system enclosures
- 1. Properly power off the system and then disconnect the system power cord from the main AC supply.
- Remove the two screws securing the left side enclosure. Removing this enclosure allows access to the B/W printer, hard drive, CD drive, and transformer.
- 3. Pivot the back side of the enclosure away from the system and then gently slide the enclosure toward the rear to remove it. Proceed to step 4.

**CSIP Level 2** 

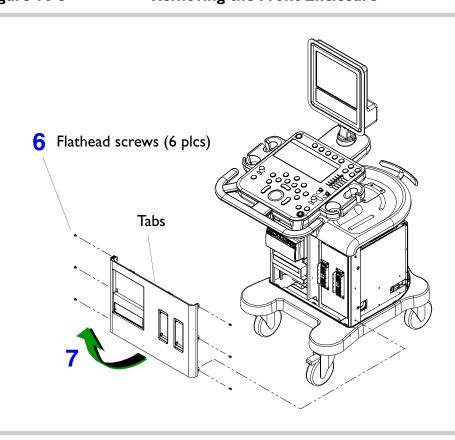
### Removing the Right Side Enclosure



- 4. Remove the two screws securing the right side enclosure. Removing this enclosure allows access to the E-box and power supply assemblies.
- 5. Pivot the back side of the enclosure away from the system, and then gently slide the enclosure toward the rear to remove it. Proceed to step 6.



4535 612 34161



- 6. Remove the six screws securing the front enclosure.
- 7. Pull the bottom side of the enclosure outward so the tabs at the top of the front panel slide out of the top cover slots.

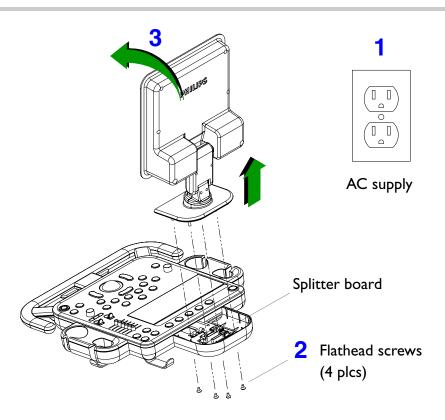
Return to Disassembly Procedure List (I of 2).

### **Video Monitor**

Figure 10-6

**CSIP Level 2** 

Removing the Video Monitor



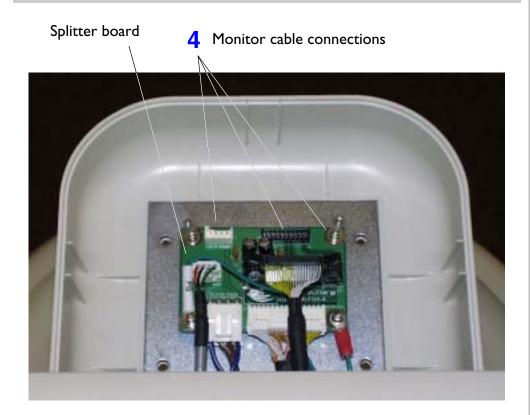
### ➤ To remove the system monitor

- I. Properly power off the system and then disconnect the system power cord from the main AC supply.
- 2. From the underside of the control panel housing, remove the four screws securing the monitor assembly to the control panel.
- 3. Lift the monitor slightly and tilt it toward the keyboard. Proceed to step 4.

4535 612 34161

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### **Disconnecting the Video Monitor Cables**



4. Disconnect the three monitor cable connections from the control panel splitter board.

This completes the video monitor removal procedure.

Return to Disassembly Procedure List (I of 2).

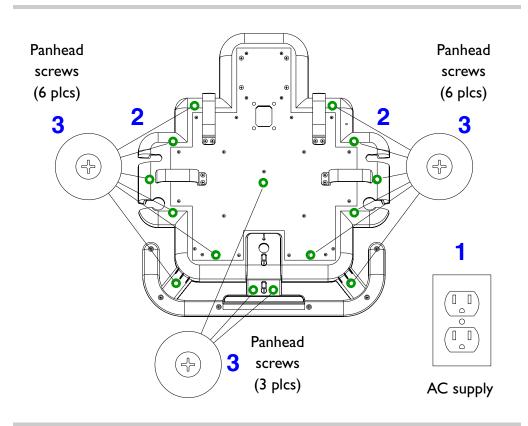
### **Control Panel**

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**CSIP Level 2** 

### Figure 10-8

### Removing the Top Control Panel Enclosure

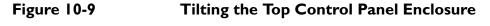


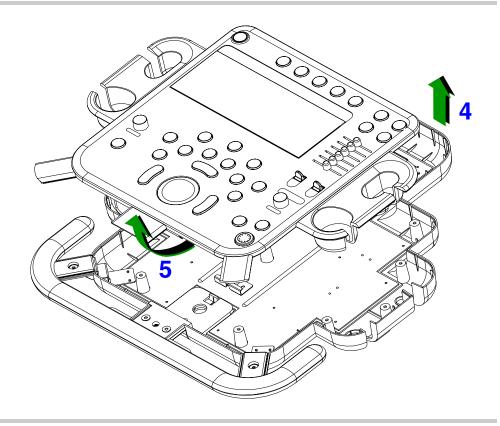
- ➤ To remove the control panel, trackball assembly, keyboard assembly, and splitter board
- I. Properly power off the system and then disconnect the system power cord from the main AC supply.
- 2. Remove all transducers from the transducer holders and place them in a safe location.
- 3. From the underside of the control panel, remove the 15 screws (recessed holes) securing the top control panel enclosure to the control panel housing. Remove only these 15 screws. Proceed to step 4.

**NOTE** To access the control panel splitter board you must first remove the video monitor. Refer to Figure 10-6.

4535 612 34161

**CSIP Level 2** 



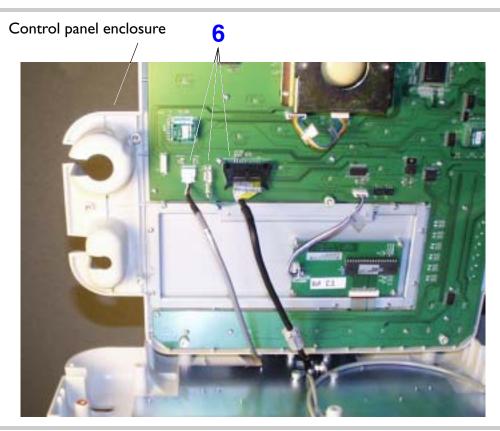


- 4. Lift the control panel enclosure slightly upward.
- 5. Carefully tilt it up from the front side to the vertical position. Proceed to step 6.

**CSIP Level 2** 

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### **Disconnecting the Control Panel Cables**



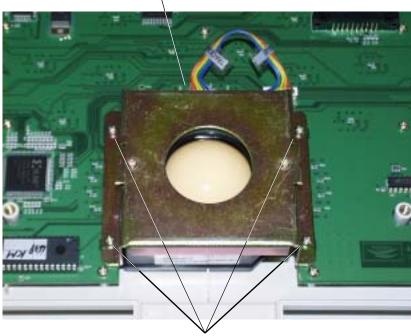
6. While holding the control panel enclosure up, disconnect the three cable connections from the control panel board.

**CSIP Level 2** 

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### Removing the Trackball Assembly

Trackball cable connection



Panhead screws (4 plcs)

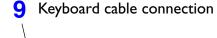
- 7. Disconnect the cable from the trackball assembly. Leave the other end of the cable connected to the control panel board.
- 8. Remove the four screws securing the trackball assembly to the control panel board.

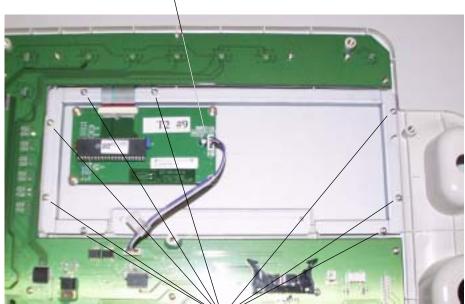
This completes the trackball removal procedure.

4535 612 34161

**CSIP Level 2** 

### Figure 10-12 Removing the Keyboard Assembly





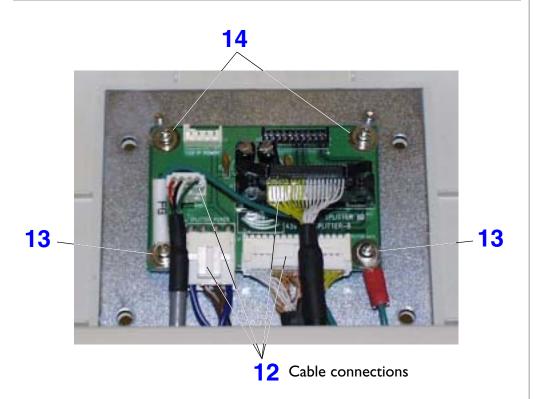
Panhead screws (8 plcs)

- 9. Disconnect the cable from the keyboard assembly. Leave the other end of the cable connected to the control panel board.
- 10. Remove the eight screws securing the keyboard assembly to the control panel board.

**CSIP Level 2** 

4535 612 34161

Removing the Splitter Board



- 11. Refer to Video Monitor for video monitor removal before proceeding with the following procedure.
- 12. Disconnect the four cable connections from the control panel splitter board.
- 13. Remove the two screws securing the two ground wires and the splitter board.
- 14. Remove the two remaining screws securing the splitter board to the control panel housing.

Return to Disassembly Procedure List (I of 2).

### **VCR** or Color Printer

Figure 10-14 Removing the VCR or the Color Printer





**VCR** Color printer

### ➤ To remove the VCR or the color printer

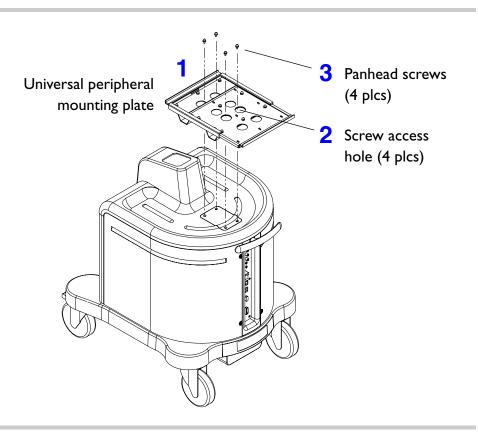
- I. Turn the peripheral off and disconnect the cables on the rear of the peripheral.
- 2. Unstrap the unit and remove it from the system.

Return to Disassembly Procedure List (I of 2).

### **Universal Peripheral Mounting Plate**

**CSIP Level 2** 

Figure 10-15 Removing the Universal Peripheral Mounting **Plate** 



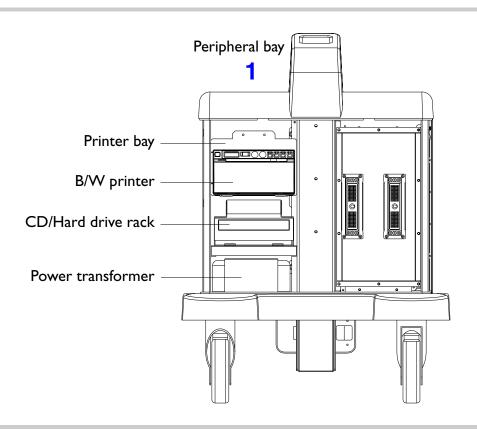
### ➤ To remove the universal peripheral mounting plate

- I. Refer to VCR or Color Printer for VCR or color printer removal before proceeding with the following procedure.
- 2. Locate the four screw access holes in the mounting plate.
- 3. Remove the four screws securing the universal peripheral mounting plate to the HD3 system top cover.

Return to Disassembly Procedure List (I of 2).

### Peripheral Bay (B/W Printer, Printer Bay, CD/Hard Drive Rack, and Power Transformer)

Figure 10-16 **Peripheral Bay Components** 



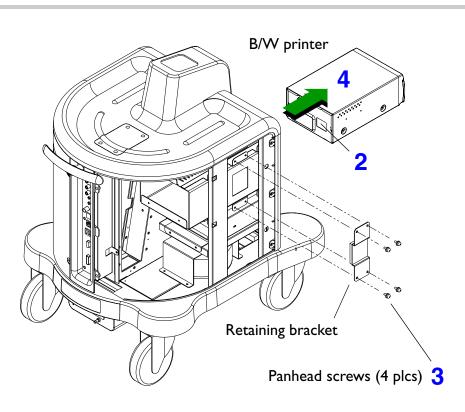
- ➤ To remove the B/W printer, CD/ Hard drive rack, power transformer, and printer bay
- I. Refer to System Enclosures for system enclosures removal and perform all the steps before proceeding with the following procedures.

**NOTE** Only the left side enclosure Figure 10-3 needs to be removed if you are only removing either the B/W printer or the CD/Hard drive rack, otherwise follow the entire procedure in the sequence presented to remove the printer bay or power transformer.

4535 612 34161

**CSIP Level 2** 

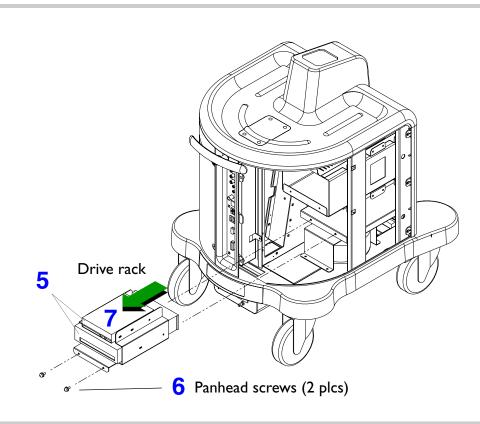
### Disconnecting the B/W Printer Cables and Removing the Printer Retaining Bracket



- 2. With the black and white printer in place, disconnect all the cables from the rear of the unit.
- 3. Remove the four screws securing the printer retaining bracket to the printer bay.
- 4. Slide the printer out of the printer bay through the front of the system.

**CSIP Level 2** 

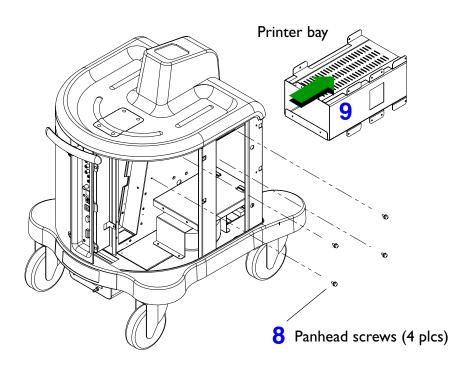
Disconnecting the Drive Cables and Removing the Drive Rack Assembly



- 5. With the CD/Hard drive rack in place, disconnect all the cables from the rear of the two units.
- 6. Remove the two screws securing the drive rack to the cart frame.
- 7. Slide the drive rack out of the peripheral bay through the rear of the system.

4535 612 34161

### Figure 10-19 Removing the B/W Printer Bay



- 8. Remove the four screws securing the printer bay to the cart frame.
- Slide the printer bay out of the peripheral bay through the front of the system.

**CSIP Level 2** 

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### **Power Transformer Cable Tie**



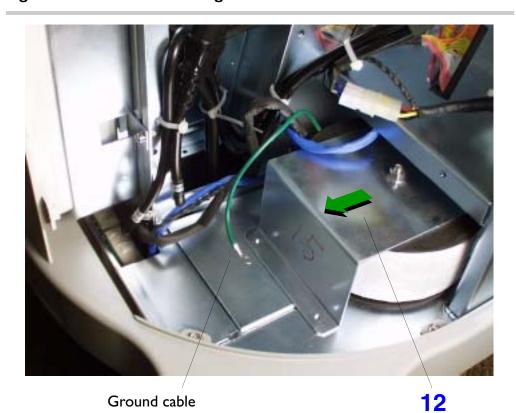
Cable tie 10

11 Panhead screws (2 plcs)

- 10. Cut the cable tie that binds the transformer and CD cables together.
- II. Remove the two screws securing the power transformer to the cart frame.

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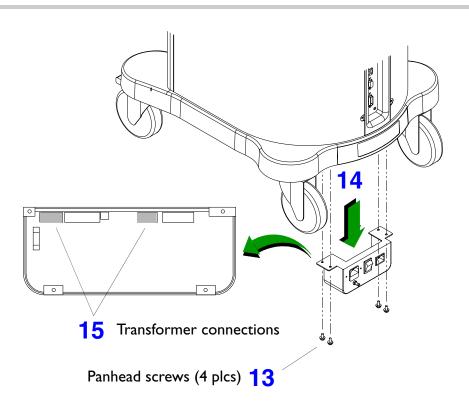
**CSIP Level 2** 



12. Pull the transformer out of the retaining slot and slide it back approximately three inches toward the rear of the system.

### Figure 10-22 Removing the Power I/O Box

**CSIP Level 2** 

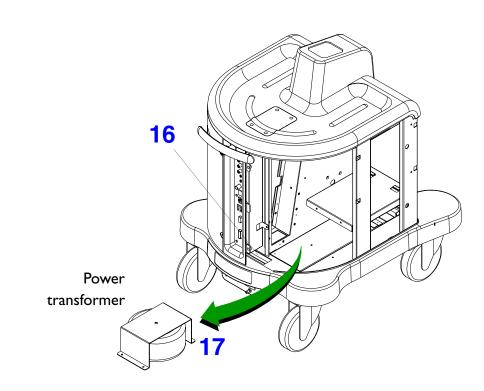


- 13. Remove the four screws securing the power I/O box to the cart frame.
- 14. Slide the transformer back as you lower the power I/O box away from the underside of the system.
- 15. Disconnect the two transformer cable connections from the backside of the power I/O box. Only disconnect these two cables.

4535 612 34161

**CSIP Level 2** 

### **Removing the Power Transformer**

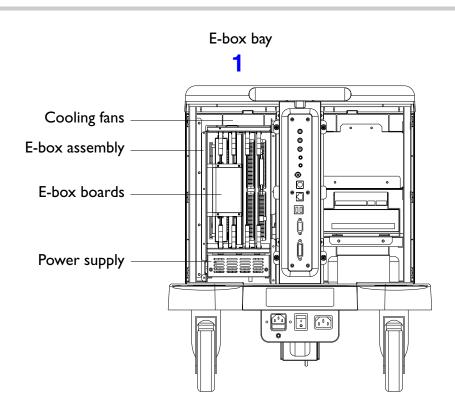


- 16. Pull the transformer cables up through the cart housing.
- 17. Lift the transformer out of the peripheral bay through the rear of the system.

Return to Disassembly Procedure List (I of 2).

## E-box Bay (E-box Assembly, Transducer Connector Assembly, E-box Boards, Power Supply and Cooling Fans)

Figure 10-24 E-box Bay Components



 To remove the E-box assembly, transducer connector assembly, E-box boards, power supply and cooling fans

You can perform most E-box service without removing the E-box from the system.

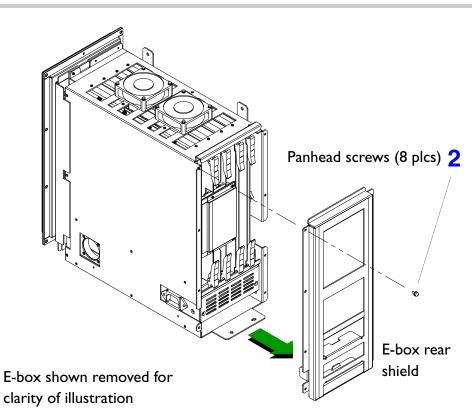
 Refer to Figure 10-3, Figure 10-4, and Figure 10-5 for system enclosure removal before proceeding with the following procedures. To remove the transducer connector assembly, proceed to step 14.

Only the right side enclosure
Figure 10-4 needs to be
removed if you are only removing the power supply.

**CSIP Level 2** 

4535 612 34161

### Removing the E-box Rear Shield



- 2. Remove the eight screws securing the E-box rear shield to the E-box case.
- 3. To remove the power supply, E-box assembly, cooling fans or Backplane board, proceed to step 4. To remove the E-box boards, proceed to step 8.

**CSIP Level 2** 

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### **Disconnecting the Power Supply Power Cord**

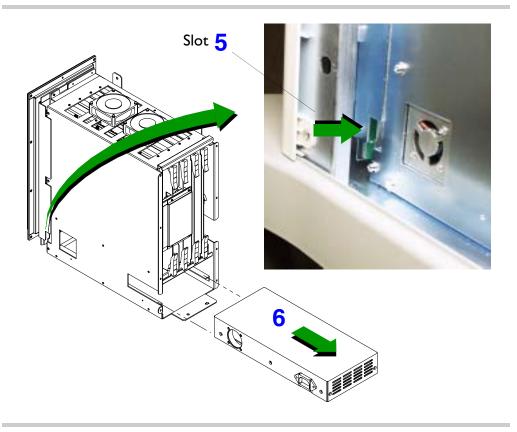


4. Disconnect the power supply power cord from the right side of the E-box.

**CSIP Level 2** 

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#### **Removing the Power Supply**

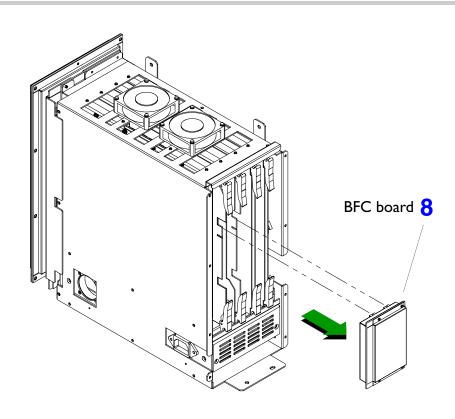


- Disengage the power supply by placing a slotted screwdriver into the slot at the rear side of the E-box case. Gently pry the screwdriver toward the front of the system until you feel the power supply release. It does not take much pressure to do this.
- 6. Slide and remove the power supply out from the rear of the E-box.
- 7. Either proceed to step 8, or to remove the E-box assembly, cooling fans or Backplane board proceed to step 11.

Figure 10-28 Removing the BFC Board

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**CSIP Level 2** 

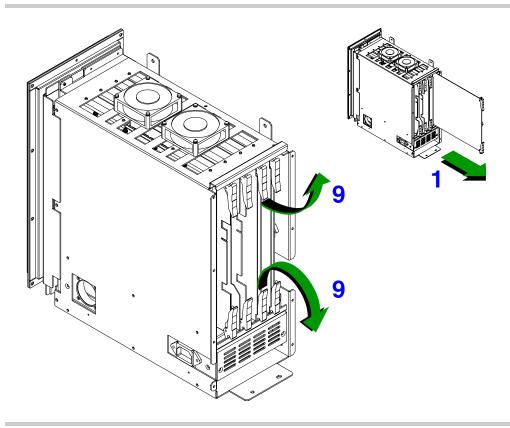


8. Grasp the top and bottom side of the BFC board and gently pull it off the FE and BF boards.

**CSIP Level 2** 

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#### Removing the FE, BF and DSC Boards

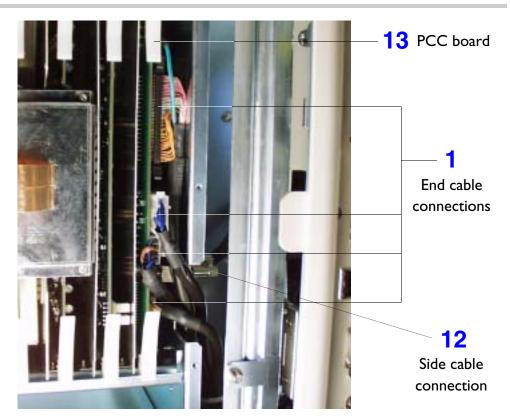


- 9. To remove the FE, BF, or DSC boards, pull out on the card retainers to release the board from the Backplane board.
- 10. Slide the board out of the card cage and place it on an anti-static mat.

**CSIP Level 2** 

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Removing the PCC Board



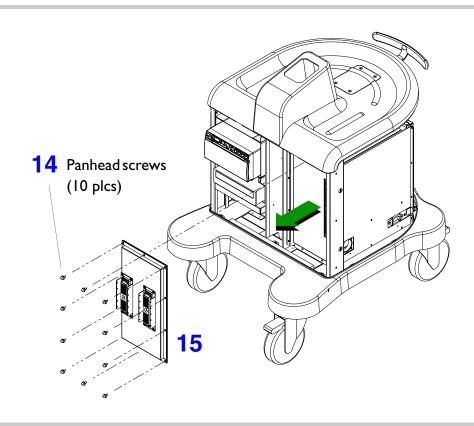
II. To remove the PCC board, disconnect the four main cables and two ground lugs (green wires) connected on the end of the board and the one cable connected on the side of the board.

**NOTE** The left side panel must be removed in order to access the one cable that connects to the side of the PCC board.

- 12. Reach in from the left side of the system, through to the connector, and loosen the two connector screw lugs. Pull the connector off the board.
- 13. Pull out on the card retainers to release the board from the Backplane board and slide the board out of the card cage and place it on an anti-static mat.

**CSIP Level 2** 

#### Figure 10-31 **Removing the Transducer Connector** Assembly (TCA)



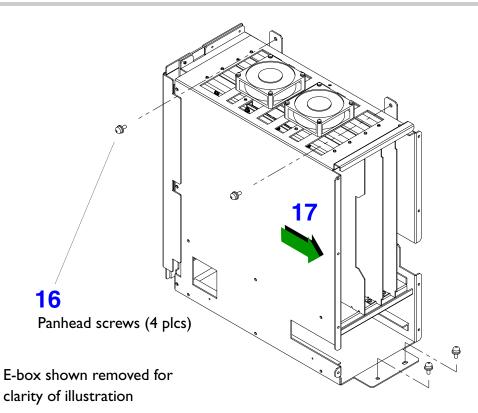
- 14. Remove the ten screws securing the transducer connector assembly to the E-box and cart chassis.
- 15. Gently pull the transducer connector assembly off the front of the E-box assembly.

**NOTE** To reinstall the transducer connector assembly, the E-box rear shield must first be installed to prevent the E-box boards from moving out of position. Refer to step 2 for reinstalling the E-box rear shield.

4535 612 34161

**CSIP Level 2** 

Removing the E-box Assembly

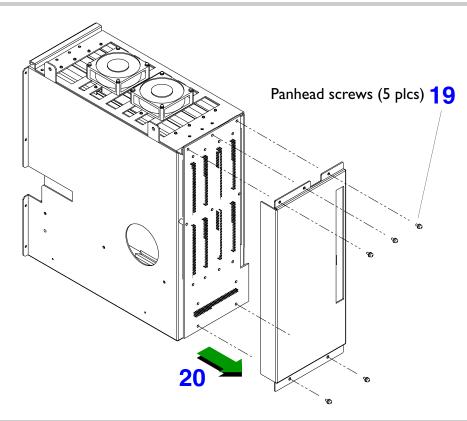


- 16. Remove the four screws securing the E-box assembly to the cart chassis.
- 17. Slide the E-box towards the rear of the system and lift it out of the E-box bay.
- 18. To remove the Backplane board proceed to step 19. To remove the cooling fans proceed to step 24.

**CSIP Level 2** 

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### Removing the Backplane Board Shield

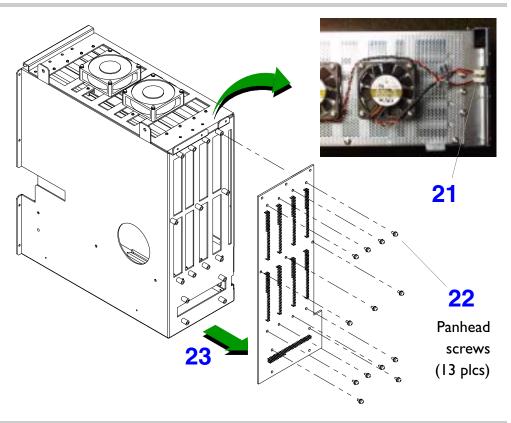


- 19. Remove the five screws securing the Backplane board shield to the E-box case.
- 20. Pull the shield off the E-box and set it aside.

4535 612 34161

**CSIP Level 2** 

#### Figure 10-34 Removing the Backplane Board

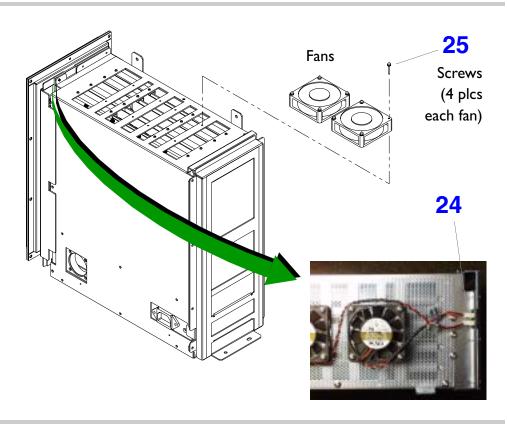


- 21. Disconnect the two speaker cables from the top of the Backplane board.
- 22. Remove the 13 screws securing the Backplane board to the E-box case.
- 23. Pull the Backplane board off the box.

**CSIP Level 2** 

4535 612 34161

#### Removing the E-box Cooling Fans



- 24. Disconnect the two speaker cables from the top of the Backplane board.
- 25. Remove the four screws securing each cooling fan to the top of the E-box case.

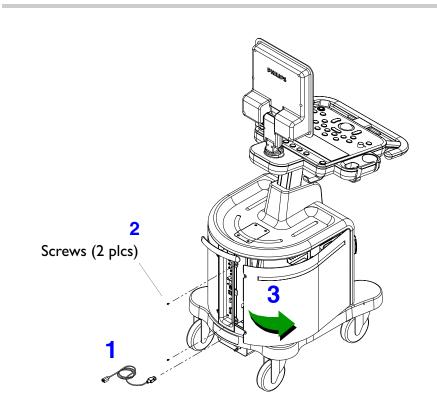
Return to Disassembly Procedure List (I of 2).

#### Rear I/O Panel Assembly

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**CSIP Level 2** 

Figure 10-36 Removing the Left and Right Side Enclosures



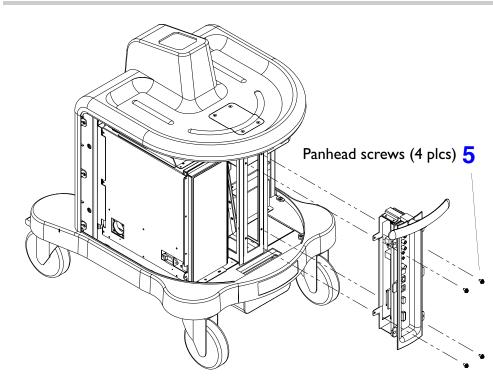
**NOTE** Both side enclosures must be removed before removing the Rear I/O assembly.

- ➤ To remove the Rear I/O panel assembly
- I. Disconnect the system power cord from the main AC supply.
- 2. Remove the two screws securing the left side enclosure.
- 3. Pivot the back side of the enclosure away from the system, and then gently slide the enclosure toward the rear to remove it.
- 4. Repeat step 2 and step 3 for right side enclosure removal.

4535 612 34161

**CSIP Level 2** 





5. Remove the four screws securing the Rear I/O panel to the cart frame.

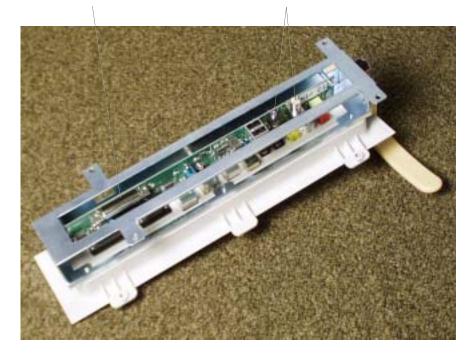
**CAUTION** When removing any of the four Rear I/O panel assembly screws, ensure that the screws don't drop into the Power I/O box opening below. If this happens you will have to remove the Power I/O box to retrieve them, Figure 10-40.

**CSIP Level 2** 

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# Disconnecting the Rear I/O Panel Assembly PCB Cables

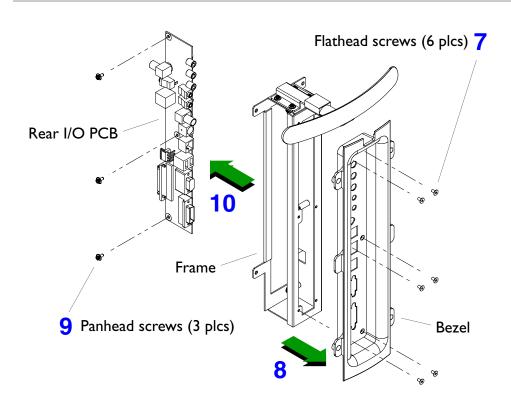
- 6 PCC interface cable
- **6** B/W printer cables (if used)



 Pull the Rear I/O panel assembly out of the cart frame enough to disconnect all the cables connected to the Rear I/O panel assembly board.

**CSIP Level 2** 

#### Removing the Rear I/O Panel Assembly PCB



- 7. Remove the six screws securing the Rear I/O panel bezel to the Rear I/O panel assembly frame.
- 8. Slide the bezel off the front of the Rear I/O panel assembly frame.
- 9. Remove the three screws securing the Rear I/O panel PCB to the Rear I/O panel assembly frame.
- 10. Slide the PCB out the backside opening of the frame.

Return to Disassembly Procedure List (2 of 2).

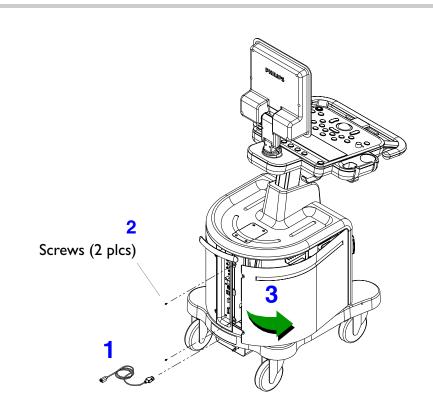
#### **Power I/O Box**

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**CSIP Level 2** 

Figure 10-40

Removing the Left and Right Side Enclosures



**NOTE** Both side enclosures must be removed before removing the Power I/O box.

#### ➤ To remove the Power I/O box

- I. Disconnect the system power cord from the main AC supply.
- 2. Remove the two screws securing the left side enclosure.
- 3. Pivot the back side of the enclosure away from the system, and then gently slide the enclosure toward the rear to remove it.
- 4. Repeat step 2 and step 3 for right side enclosure removal.

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#### **Disconnecting the Power Supply Power Cord**



5. Disconnect the power supply power cord from the right side of the E-box.

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#### **Cutting the Cable Ties on the Power Cables**



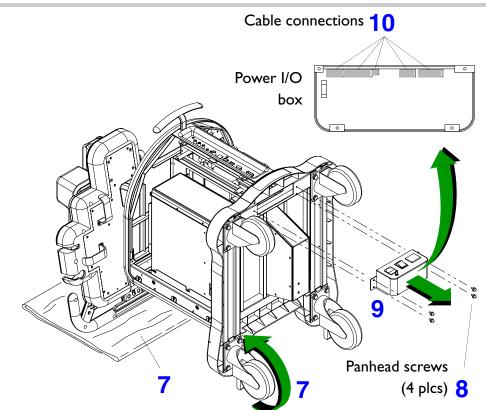
Cable ties 6

6. Cut the two cable ties that bind the transformer and CD cables together.

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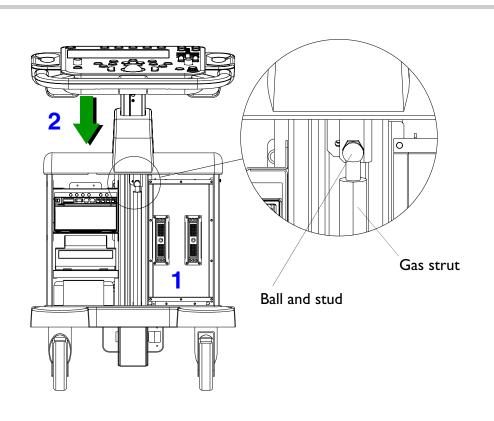


- 7. Place a soft material protector pad on the floor and carefully rotate the system over on its front casters so that the control panel handle rests on the protector pad.
- 8. Remove the four screws securing the Power I/O box to the cart frame.
- 9. Pull the Power I/O box away from the underside of the system.
- 10. Disconnect all five power cable connections from the backside of the Power I/O box PCB.

Return to Disassembly Procedure List (2 of 2).

#### Lift Column Gas Strut

Figure 10-44 **Lowering the Control Panel** 

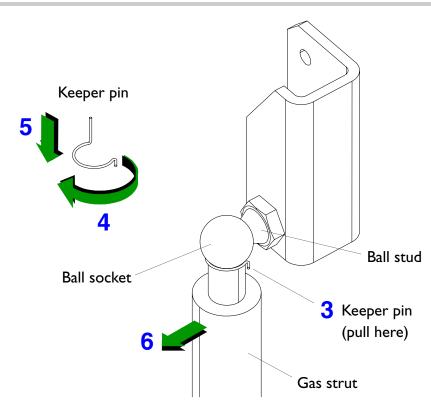


- ➤ To remove the lift column gas strut
- I. Refer to "System Enclosures" on page 157 for system enclosures removal and perform all the steps before proceeding.
- 2. Lower the control panel until the ball and ball stud end of the gas strut is visible and accessible.

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#### Removing the Gas Strut from the Ball Stud



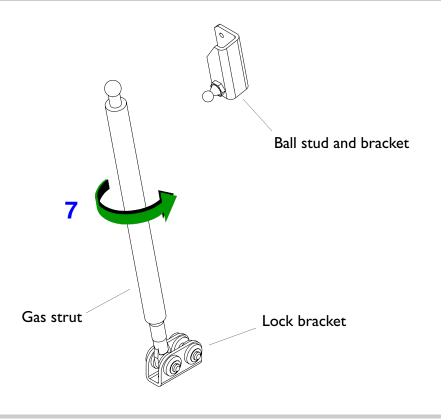
- 3. Pull the end of the keeper pin outward (right side of gas strut ball socket).
- 4. Rotate the keeper pin (counterclockwise).
- 5. Slide the pin down until it comes out of the ball socket holes.
- 6. Pull the gas strut off of the ball stud.

4535 612 34161

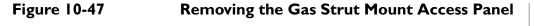
**CSIP Level 2** 

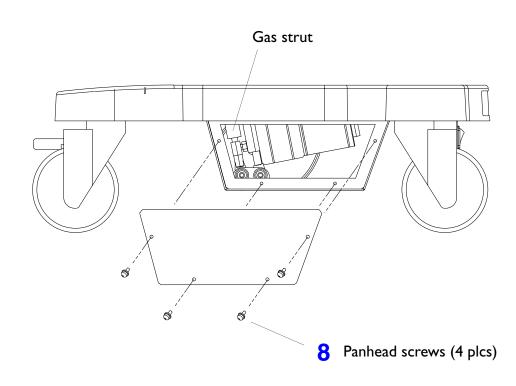
Disassembly: Disassembly (Removal) Procedures

Figure 10-46 Removing the Gas Strut from the Lock Bracket



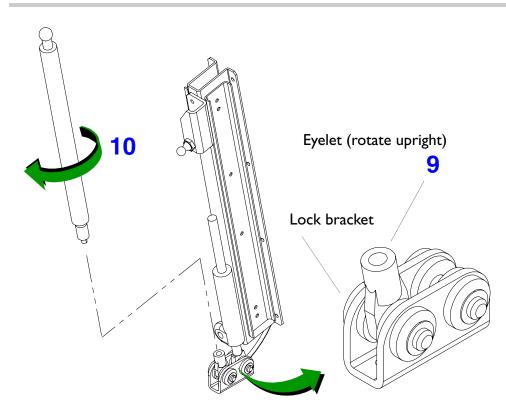
7. Unscrew the gas strut (counterclockwise) until it releases from the eyelet on the lock bracket. The gas strut is now removed. **CSIP Level 2** 





8. Remove the four screws securing the gas strut mount access plate to the lower cart frame.

### Figure 10-48 Installing the Gas Strut into the Lock Bracket

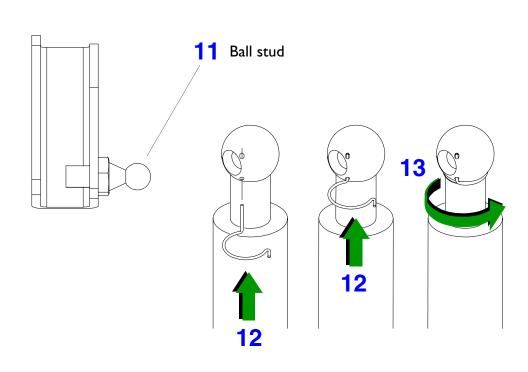


- Reach in through the gas strut mount access opening and rotate the lock bracket eyelet upward until you see the screw hole. Hold it in that position.
- Screw the gas strut (clockwise) into the lock bracket eyelet until it is snug.

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**CSIP Level 2** 

Inserting the Gas Strut onto the Ball Stud



- 11. Press the gas strut ball socket onto the ball stud.
- 12. Insert the keeper pin through the two holes in the ball socket.
- 13. Rotate the keeper pin (clockwise) around the shaft and snap it into place.

Return to Disassembly Procedure List (2 of 2).

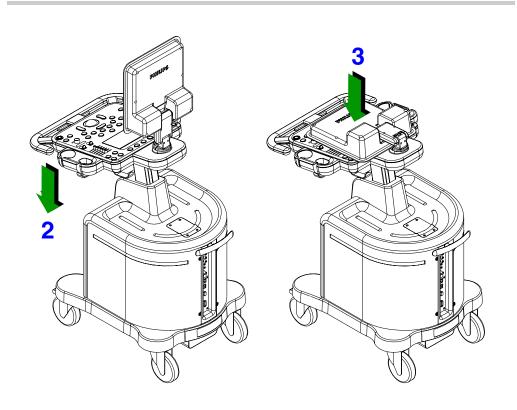
#### **System Casters**

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**CSIP Level 2** 

Figure 10-50

**Preparing the System for Caster** Replacement



#### To remove a system casters

Disconnect the system power cord from the main AC supply.

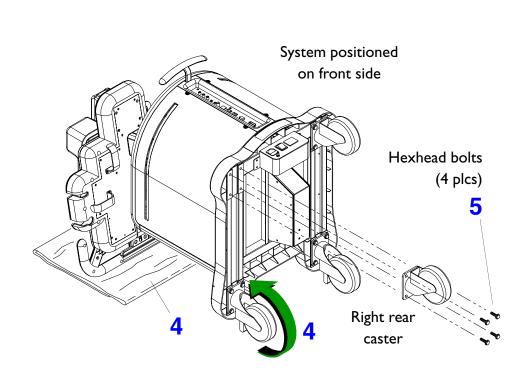
#### WARNINGThe following steps require that the system be tipped over to the floor. To reduce the risk of injury or system damage from toppling, tilt the monitor down onto the control panel surface and lower the control panel to its lowest position.

- 2. Lower the control panel to its lowest position.
- Tilt the monitor down onto the control panel.

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**CSIP Level 2** 

#### Figure 10-51 Tipping the System to Remove the Rear **Casters**

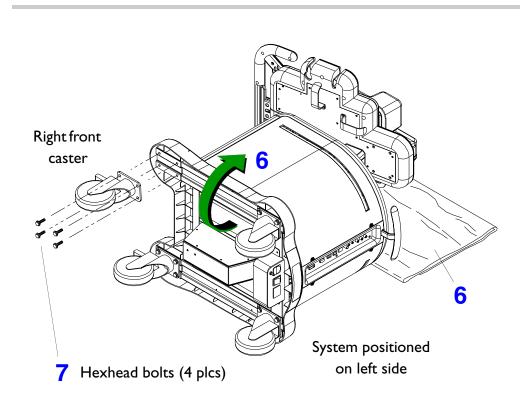


- 4. Place a soft material protector pad on the floor and carefully rotate the system over on its front casters so that the control panel handle rests on the protector pad.
- 5. Remove the four bolts securing the rear caster to the cart weldment.

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**CSIP Level 2** 

#### **Tipping the System to Remove the Front Casters**



- 6. Place a soft material protector pad on the floor and carefully rotate the system over on its right side (for left front caster removal) or on its left side (for right front caster removal). Orient the system so that the control panel transducer holder rests on the protector pad.
- 7. Remove the four bolts securing the front caster to the cart weldment.

Return to Disassembly Procedure List (2 of 2).

#### **Crating the HD3 Ultrasound System**

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**CSIP Level 2** 

Figure 10-53 **Locking the Front Casters** 



To crate the HD3 Ultrasound **System** 

**NOTE** You must have the shipping crate package to be able to perform this procedure. This package contains all the hardware necessary for proper shipping.

I. Lock both front casters by pressing down on each caster lock lever to prevent the system from moving during the crating procedure.

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**CSIP Level 2** 







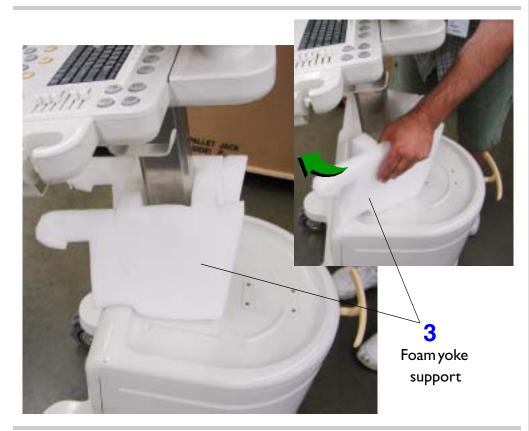
2. Grasp the control panel handle; engage the trigger release, and raise the control panel to its highest position.

Figure 10-55

**CSIP Level 2** 

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#### **Placing the Foam Yoke Support**



3. Spread apart the foam yoke support and place it on top of the system top cover and then fold it around the lift column.

**CSIP Level 2** 

4535 612 34161

#### **Lowering the Control Panel**



Foam yoke support

Grasp the control panel handle; engage the trigger release, and lower the control panel until it rests firmly against the foam yoke support.

**CSIP Level 2** 

4535 612 34161

Tilting the Video Monitor



5. Grasp both sides of the video monitor and tilt it toward the front of the system until it is in a horizontal position above the control panel.

**CSIP Level 2** 

4535 612 34161

#### **Placing the Foam Monitor Support**



6. Carefully slide the foam monitor support over the control panel. Ensure that the opening in the foam for the monitor is at the top.

**CSIP Level 2** 

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#### **Securing the Video Monitor**

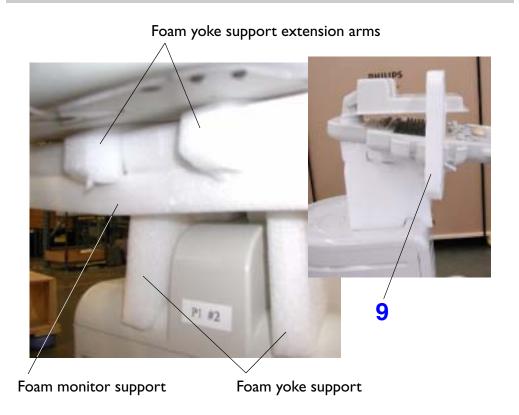


- 7. Align the video monitor with the cut-out in the foam support.
- 8. Slide the foam support further up the control panel allowing the monitor to slide through the upper cut-out.

**CSIP Level 2** 

4535 612 34161

#### Fastening the Two Foam Supports Together



9. Below the control panel, slide the foam monitor support back so that the two foam arms extending from the foam yoke support come through the holes. Push until both foam arm extensions hook and hold the foam monitor support in place.

**CSIP Level 2** 

4535 612 34161

### Covering the System with an Antistatic Bag



10. Place an antistatic bag over the system.

**NOTE** With the exception of the casters, the antistatic bag must cover every part of the system that contacts the crate.

Figure 10-62 **Placing the Ramp** 

4535 612 34161

**CSIP Level 2** 



11. Place the crate ramp in front of the crate opening with the beveled edge positioned at the lower end and facing up.

**CSIP Level 2** 

4535 612 34161

#### Loading the System onto the Crate



- 12. Unlock both front casters by pressing down on each caster tab lock release.
- 13. Slightly lift the antistatic bag and position yourself on one side of the crate toward the front of the system.
- 14. Grasp the control panel handle and carefully pull the system up the ramp and onto the crate, guiding the underside of the system into the crate floor support. The rear of the system should be facing the ramp side of the crate.

Figure 10-64 Rotating the Rear Casters

4535 612 34161

**CSIP Level 2** 



15. Rotate the rear casters 180 degrees.

Figure 10-65 Placing the Wheel Chock

4535 612 34161

**CSIP Level 2** 



16. Place the wheel chock so that the beveled side seats against the wheels of the casters.

**CSIP Level 2** 

4535 612 34161

#### Placing the System Hold-Down Brace



17. Place the system hold-down brace over the rear wheels.

**CSIP Level 2** 

4535 612 34161

#### Mounting the Ramp to the Crate



- 18. Turn the ramp around and place the ramp into the pallet with beveled edge up and facing outward.
- 19. Secure the ramp to the crate using four bolts.

**CSIP Level 2** 

4535 612 34161

Placing the Corrugated Wrap



20. Place the one-piece corrugated wrap over the ramp and onto the pallet. The corrugated wrap should be set so that the wrap fits on the inside of each corner retainer bracket.

**CSIP Level 2** 

4535 612 34161

#### **Placing the Corrugated Top Cover**

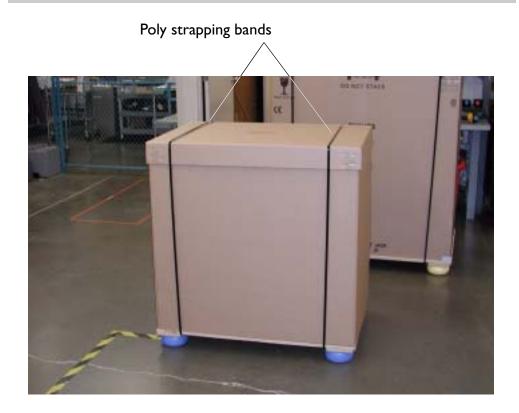


21. Place the corrugated top cover on the crate container and press it into place at each corner.

**CSIP Level 2** 

4535 612 34161

#### **Banding the System Crate**



22. Band the crated system container from the side with two poly strapping bands.

Return to Disassembly Procedure List (2 of 2).

## **Cabling**

#### Introduction

4535 612 34161

**CSIP Level I** 

This section contains system cabling and connector information. Use the illustrations (figures) and parts tables in this section to locate and identify system cables and their part numbers. Part numbers are shown on the illustrations and are listed and described in the corresponding tables.

**NOTE** Cable part numbers are located on at least one end of the cables.

## **System**

System signal interconnect and power distribution cabling diagrams are shown in Figure 11-1 and Figure 11-2. For reference, system-to-peripheral connection diagrams are provided in **Cabling** Figure 11-1 through Figure 11-3. **Diagrams** 

Cable Part Table 11-1 is a parts list of the interconnect cables shown in Figure 11-1 and the power distribution cables shown in Figure 11-2. Refer to Table 14-2 for additional information on peripherals Numbers and applicable cables.

Figure 11-4 through Figure 11-11 are illustrations of the system primary connector assemblies.

#### **System** Connectors

Figure 11-1 HD3 Ultrasound System Signal Interconnect Diagram

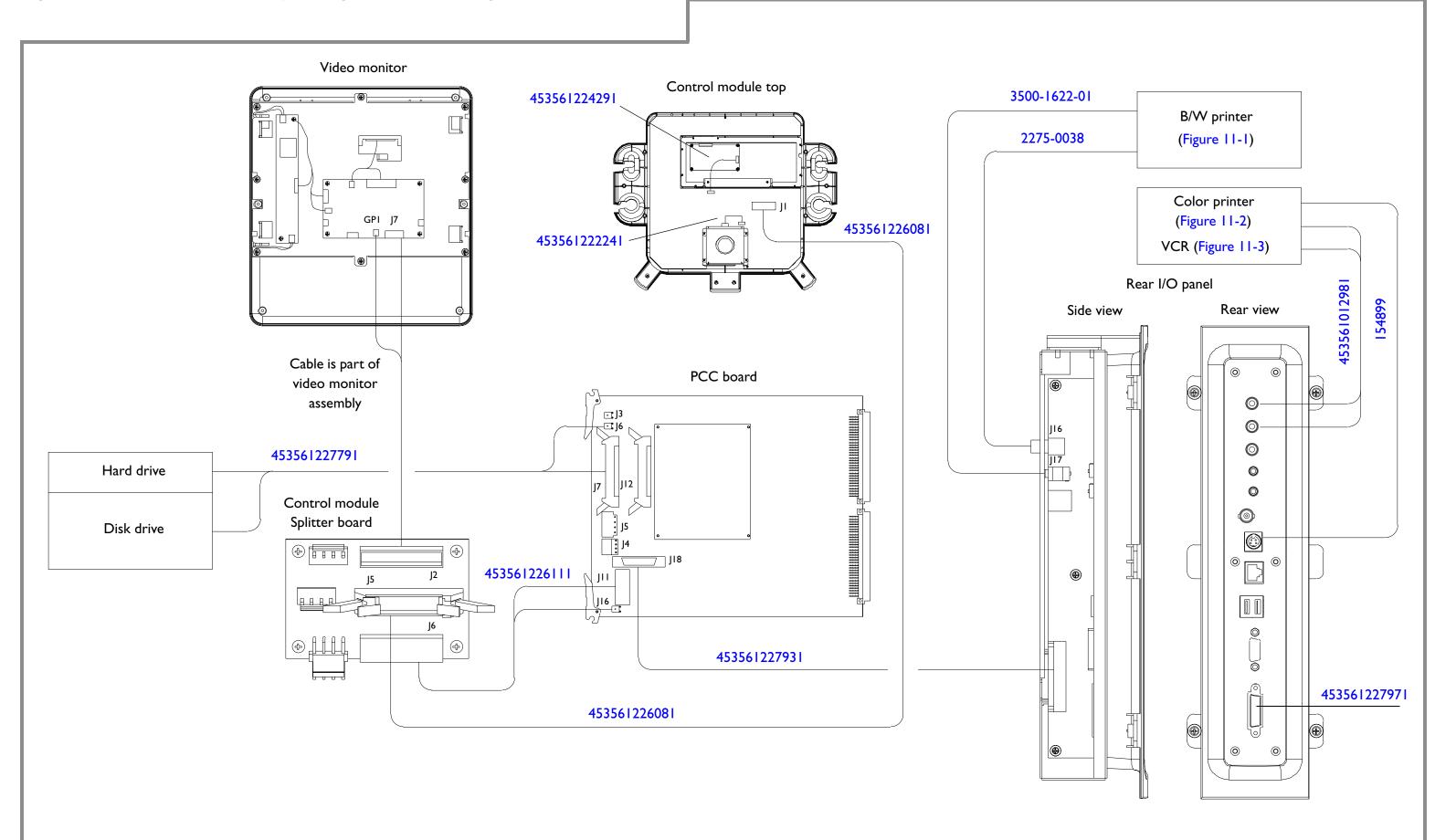


Figure 11-2 HD3 Ultrasound System Power Distribution Diagram

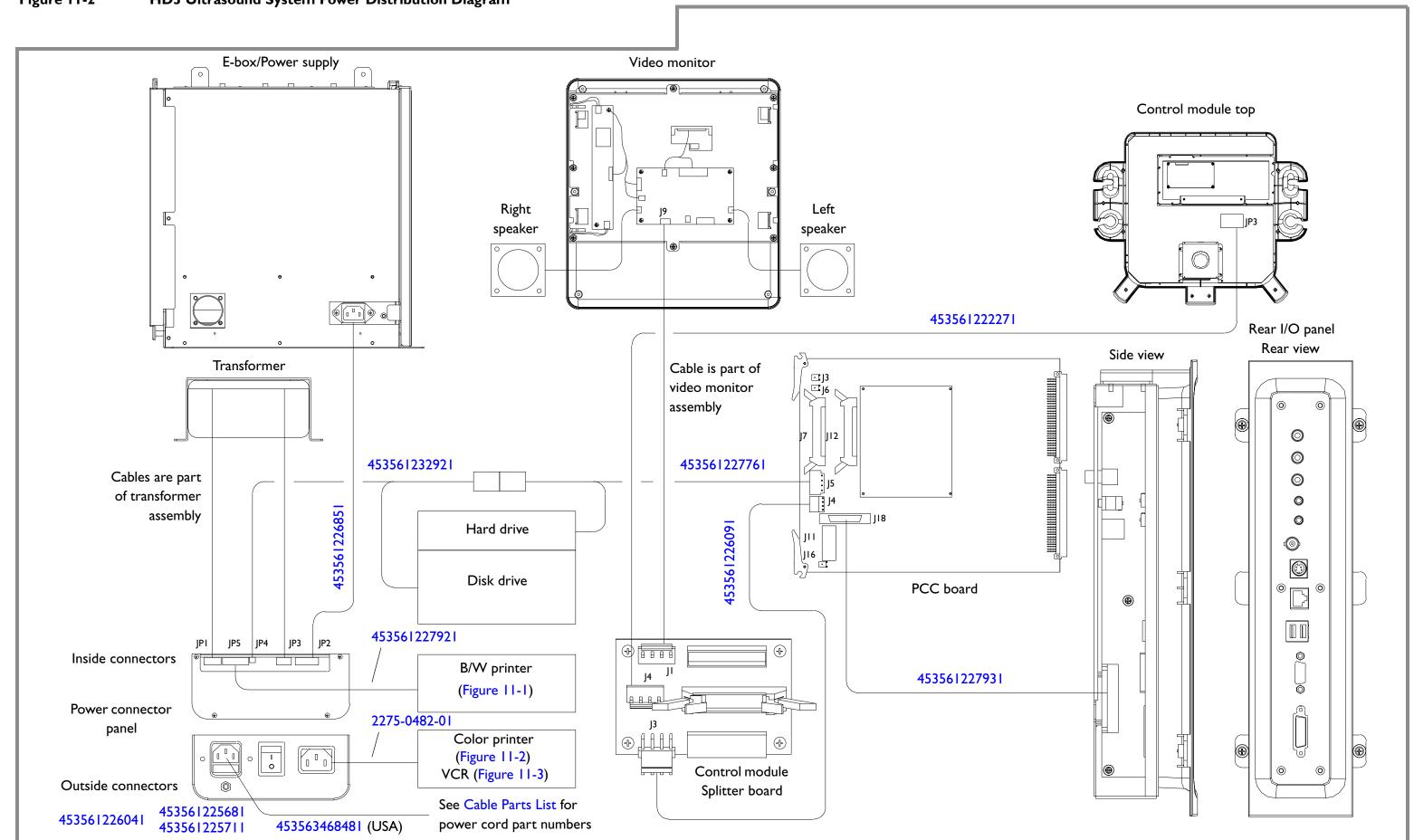


Diagram: Figure 11-1 and Figure 11-1 453561227791 Cable Assy, CD/Hard Drive, Data Manufacturing No: WH-439-SIG-08-00 Diagram: Figure 11-1 453561227761 Cable Assy, CD/Hard Drive, Power Manufacturing No: WH-439-PWR-04-00 Diagram: Figure 11-2 453561232921 Cable Assy, CD-RW, External Power Manufacturing No: WH-439-PWR-07 Diagram: Figure 11-2 3500-1622-01 Alias No: 453561018331 Cable Assy, Print Trigger Diagram: Figure 11-1 and Figure 11-1 453561226851 Cable Assy, E-Box Power Manufacturing No: WH-439-PWR-06 Diagram: Figure 11-2 Manufacturing No: WH-339-PWR-03 453561227971 Cable Assy, Foot Switch Adapter Diagram: Figure 11-1 Parts Info: Figure 14-31 453561226081 Manufacturing No: WH-439-SIG-07-00 Cable Assy, Keyboard Data Diagram: Figure 11-1

CSIP Level I	Cabling: Cable Parts Lis		
Table    -	HD3 System Signal and Power Cable Part Numbers (Continued)		
Part Number	Cable Description Notes/Reference		
453561222271	Cable Assy, Keyboard, Power	Manufacturing No: WH-439-PWR-03-00	
		Diagram: Figure 11-2	
453561224291	Cable Assy, QWERTY Keyboard	Manufacturing No: WH-439-SIG-05-00	
		Diagram: Figure 11-1	
453561227931	Cable Assy, PCC to Rear I/O Panel	Manufacturing No: WH-439-SIG-03-00	
		Diagram: Figure 11-1	

**Page 229** 

Manufacturing No: ADAPTOR-FILTER

Diagram: Figure 11-2

4535 612 34161

453561226041

**HD3 Service Manual** 

Cable Assy, Power Adapter with Filter

without an integrated line filter can be used. If the HD3 system does not have the power adapter with filter, you should use ONLY one of the two power cords with integrated

Manufacturing No: CORD-110-FILTER

line filter.

Diagram: Figure 11-2
Parts info: Figure 14-25

4535 612 34161 CSIP Level I	HD3 Service Manual	Page 23 I Cabling: Cable Parts List
Table     -	HD3 System Signal and Power Cable Part Numbers (Continued)	
Part Number	Cable Description	Notes/Reference
453561225711	Cable Assy, Power Cord, 220 Vac with Filter	Inital shipments of HD3 systems shipped with power cords have integrated line filters (453561225681 or 453561225711).
		All remaining shipments of HD3 systems use the Cable Assy, Power Adapter with Filter. With this "universal filter", power cords without an integrated line filter can be used.  If the HD3 system does not have the power adapter with filter, you should use ONLY one of the two power cords with integrated line filter.  Manufacturing No: CORD-220-FILTER Diagram: Figure 11-2 Parts info: Figure 14-25
2275-0482-01	Cable Assy, Power Cord, Peripheral	Alias No: 453561013471 Used for top-mounted OEM's Diagram: Figure 11-2, Figure 11-2, and Figure 11-3
453563468451	Cable Assy, Power Cord, System, UK/Singapore/Hong Kong	Main AC system power cord Legacy No: M2540-60900

4535 612 34161 CSIP Level I	HD3 Service Manual Page 2 Cabling: Cable Parts L	
Table    -	HD3 System Signal and Power Cable Part Numbers (Continued)	
Part Number	Cable Description	Notes/Reference
453563468461	Cable Assy, Power Cord, System,	Main AC system power cord
	Australia/New Zealand	Legacy No: M2540-60901
453563468471	Cable Assy, Power Cord, System,	Main AC system power cord
	Continental Europe	Legacy No: M2540-60902
453563468481	Cable Assy, Power Cord, System,	Main AC system power cord
	USA/Canada/Japan	Legacy No: M2540-60903
		Diament Figure 11.2

	Continental Europe	Legacy 140. 1 123 10-00702
453563468481	Cable Assy, Power Cord, System,	Main AC system power cord
	USA/Canada/Japan	Legacy No: M2540-60903
		Diagram: Figure 11-2
453563468491	Cable Assy, Power Cord, System,	Main AC system power cord
	Switzerland/Lietenstein	Legacy No: M2540-60906
453563468501	Cable Assy, Power Cord, System,	Main AC system power cord
	Denmark/Greenland	Legacy No: M2540-60912
453563468511	Cable Assy, Power Cord, System,	Main AC system power cord
	Africa/India	Legacy No: M2540-60917
453563468521	Cable Assy, Power Cord, System,	Main AC system power cord
	Israel	Legacy No: M2540-60919
453563468531	Cable Assy, Power Cord, System,	Main AC system power cord
	Argentina	Legacy No: M2540-60920
453563468541	Cable Assy, Power Cord, System,	Main AC system power cord
	China	Legacy No: M2540-60922
453561012981	Cable Assy, RCA-RCA, Stereo, Molded, 6-Ft	Used for top-mounted VCR
		Diagram: Figure 11-1 and Figure 11-3

CSIP Level I	Cabling: Cable Parts List		
Table    -	HD3 System Signal and Power Cable Part Numbers (Continued)		
Part Number	Cable Description	Notes/Reference	
453561226111	Cable Assy, Splitter Board Data	Manufacturing No: WH-439-SIG-02-00	
		Diagram: Figure 11-1	
453561226091	Cable Assy, Splitter Board Power	Manufacturing No: WH-439-PWR-01-00	
		Diagram: Figure 11-2	
154899	Cable Assy, S-VHS, Shielded, 6-Ft	Alias No: 453561000921	
		Used for top-mounted OEMs	

Page 233

Diagram: Figure 11-1, Figure 11-2 and

Manufacturing No: WH-439-SIG-01-00

Figure 11-3

Diagram: Figure 11-1

**HD3 Service Manual** 

Cable Assy, Trackball

4535 612 34161

453561222241

**Peripheral** 

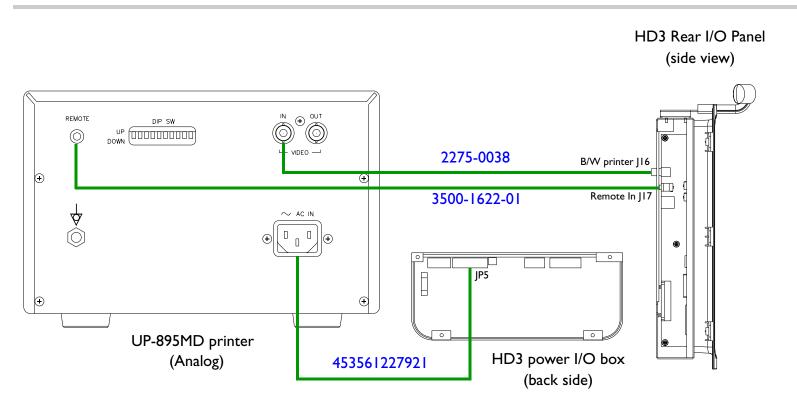
**CSIP Level I** 

4535 612 34161

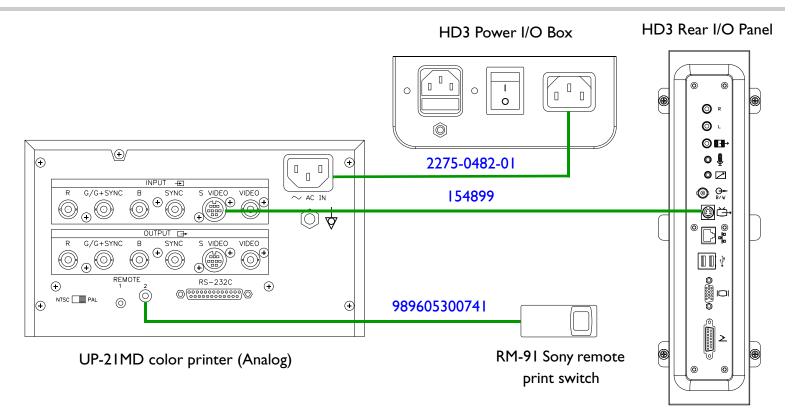
Cabling Diagrams

Figure II-I

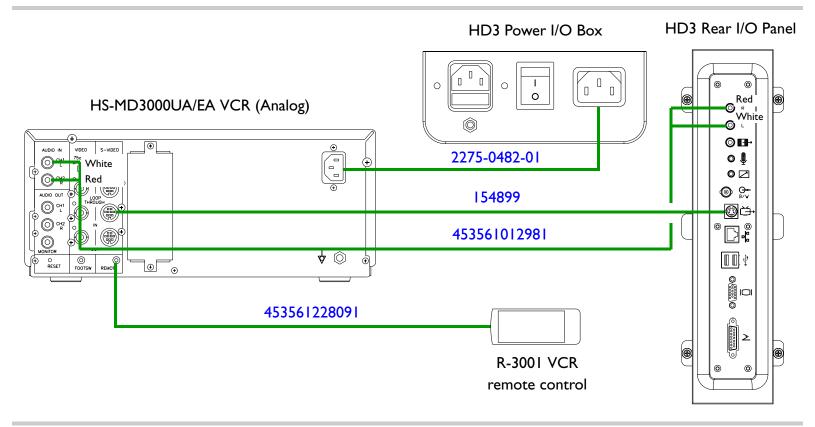
Sony UP-895MD B/W Printer Cabling Diagram



#### Sony UP-21MD Color Printer Cabling Diagram



#### Mitsubishi HS-MD3000UA/EA VCR Cabling Diagram



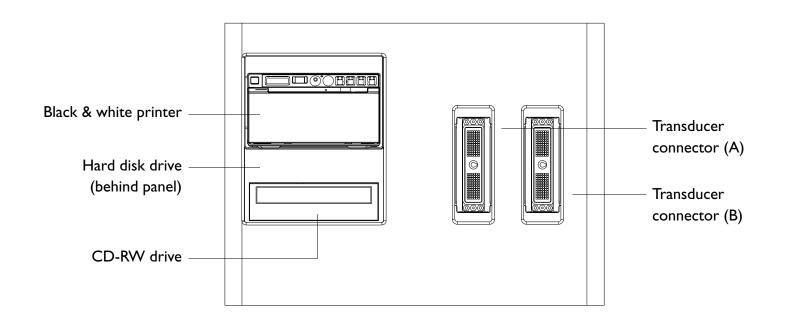
#### System

#### Connector

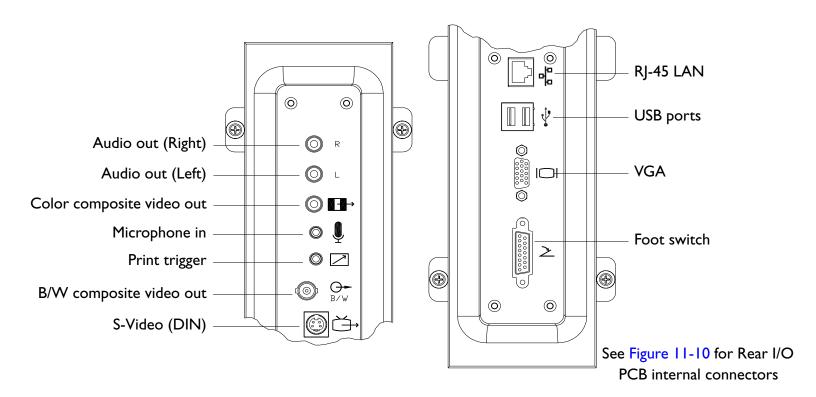
Illustrations

Figure 11-4

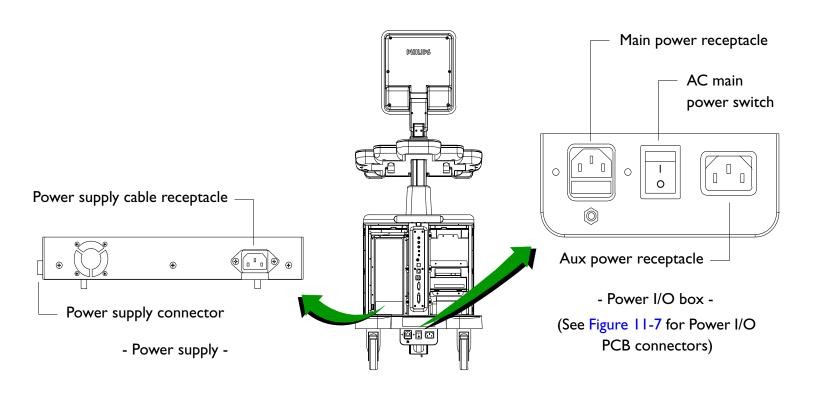
**HD3 System Connector Locations (Front Panel)** 



#### HD3 System Connector Locations (Rear I/O Panel)

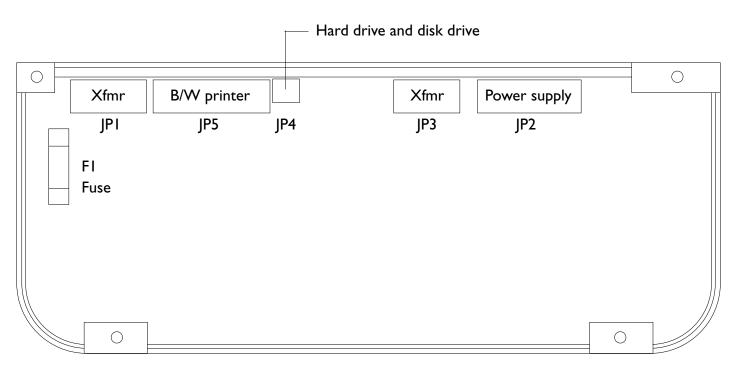


#### **HD3 System Connector Locations (Power Connectors)**



**CSIP Level I** 

#### **HD3 System Connector Locations (Power I/O Box Connectors)**



- Rear view with cover removed -

#### **HD3 Video Monitor PCB Cable Connector Locations**

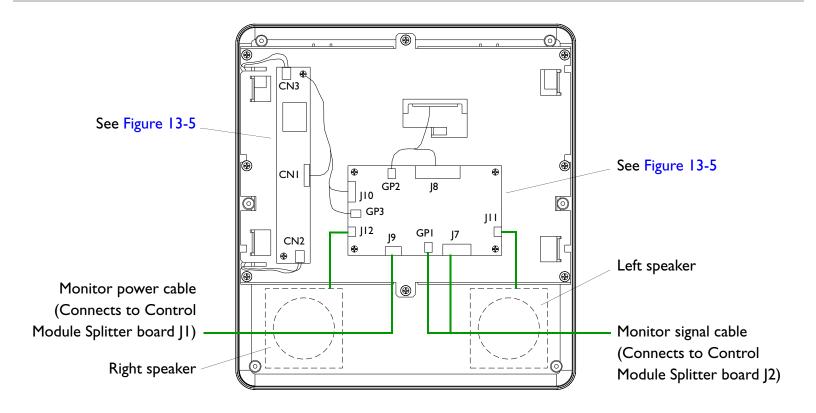
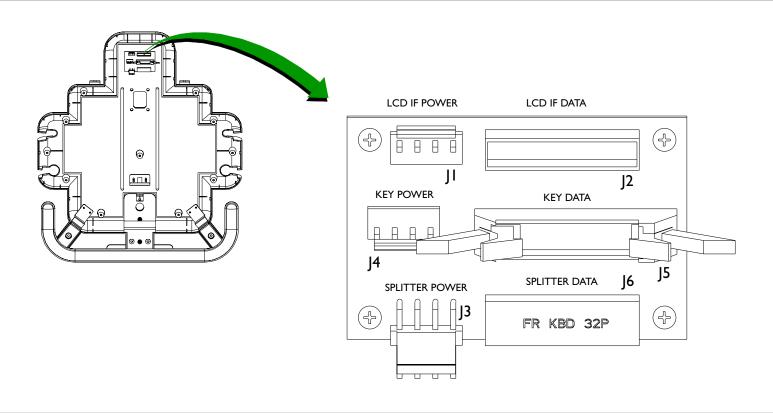


Figure 11-9

#### **HD3 Control Panel PCB Cable Connector Locations (Splitter Board)**



**CSIP Level I** 

4535 612 34161

HD3 Rear I/O PCB Internal Cable Connector Locations (Side View)

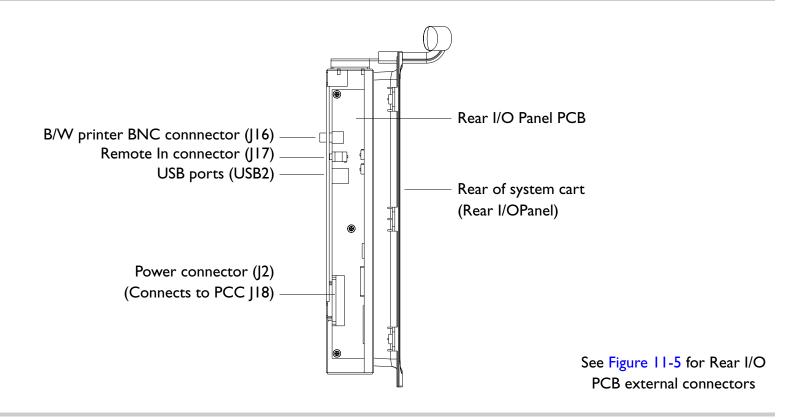
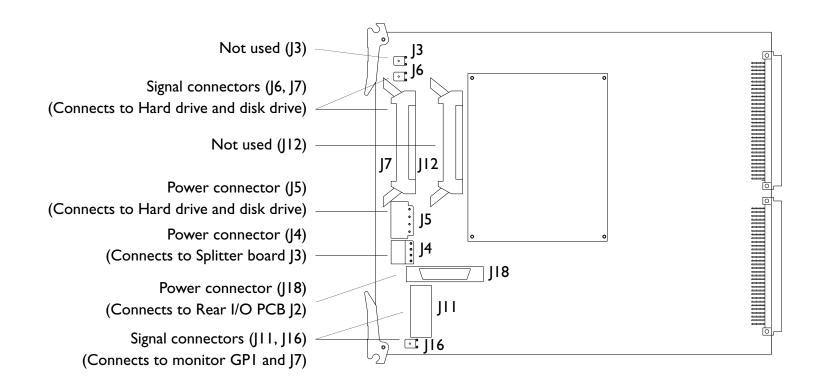


Figure | | - | |

#### **HD3 PCC PCB Cable Connector Locations**



### 12 Change History

#### Introduction

This section summarizes the software and hardware changes associated with specific software releases. Unless noted under "Hardware Changes," hardware changes do not always accompany a software release. See Section 13, "Configuration" for part numbers of the released software versions. Contact your Philips representative for the core information you need to determine the compatibility of primary system PCBs and certain hardware assemblies with respect to the system software releases. Any hardware part number additions or changes that accompany these releases are incorporated into the respective sections of this manual.

Initial System Release (v1.00.00 Build 085) Philips Ultrasound released the HD3 Ultrasound System for customer orders in August 2005.

#### 13 Configuration

#### Introduction

4535 612 34161

**CSIP Level I** 

This section lists all of the released software version part numbers for the system, identifies the primary system PCBs, and shows where these PCBs are located in the system. When applicable, additional PCB reference information is provided.

This section also contains configuration information such as the as-shipped system BIOS settings, hard drive jumper positions, and the Philips-recommended settings for the optional OEM peripherals sold with the system.

# Compatibility Information

Contact your Philips representative for the core information you need to determine the compatibility of primary system PCBs and certain hardware assemblies with respect to the system software releases.

# System<br/>Software

Software release levels and corresponding part numbers are listed in Table 13-1. See for a summarized history of the software and hardware changes associated with specific software releases.

Table 13-1	System Software CD Part Numbers		
Released			
Software	Build		
<b>V</b> ersion	No.	Disk Part No.	Notes
v1.00.00	.085	453561228661	System software initial release

# Locating and Identifying Primary PCBs

The HD3 primary PCB names and locations are shown in Figure 13-1through Figure 13-4. These figures provide linked references to the corresponding PCB illustration.

**Page 247** 

## Reference **Information**

**PCB** 

The following conventions apply to the PCB reference information provided in this section:

- PCB illustrations are provided as an aid to verifying physical integrity or matching the physical configuration of new PCBs.
- Any configurable jumpers and switches found on PCBs do not require configuration by field service representatives at installation. All configurable devices may not be shown.
- On line art, the positions of components and test points shown are relative locations only, not necessarily to scale. Not all components and test points are shown.
- Any potentiometers found on PCBs shall not be adjusted by field service representatives unless an authorized procedure instructs otherwise. Not all potentiometers are shown.

Figure 13-1

**CSIP Level I** 

4535 612 34161

#### HD3 Primary System PCB Names and Locations (E-box)

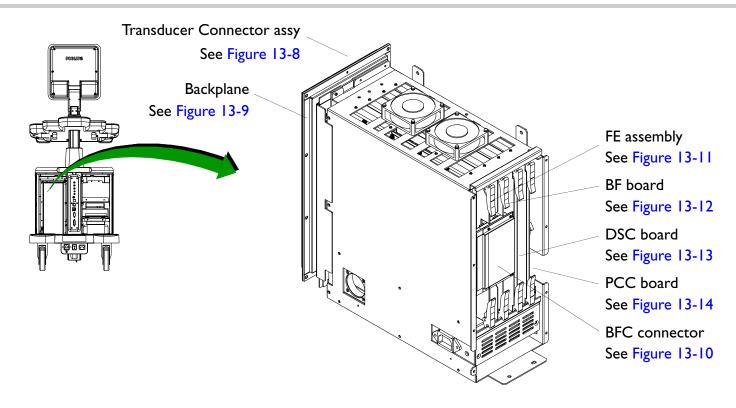


Figure 13-2

**CSIP Level I** 

4535 612 34161

#### HD3 Primary System Board Names and Locations (Rear I/O Panel)

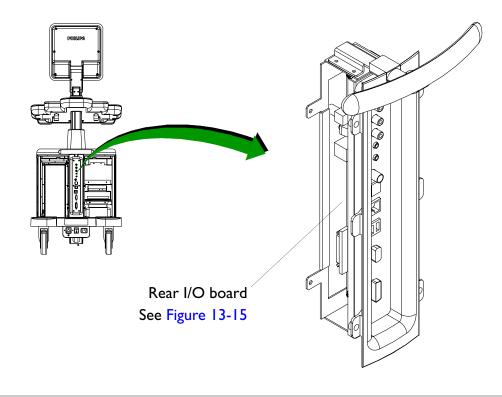


Figure 13-3

**CSIP Level I** 

4535 612 34161

**HD3 Primary System PCB Names and Locations (Power I/O Box)** 

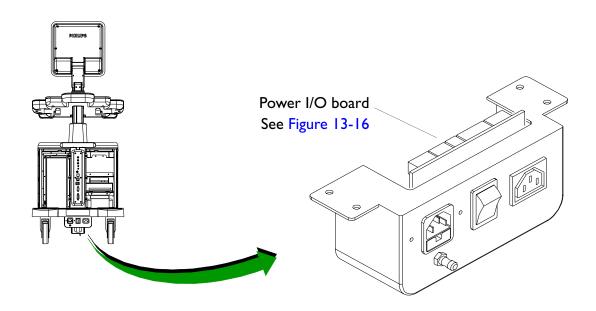
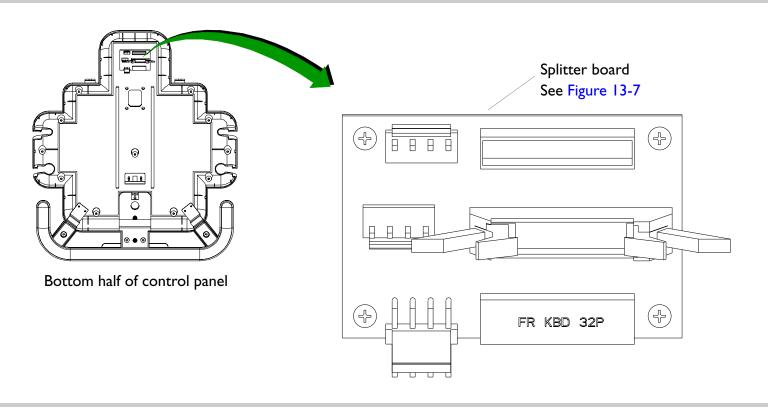


Figure 13-4

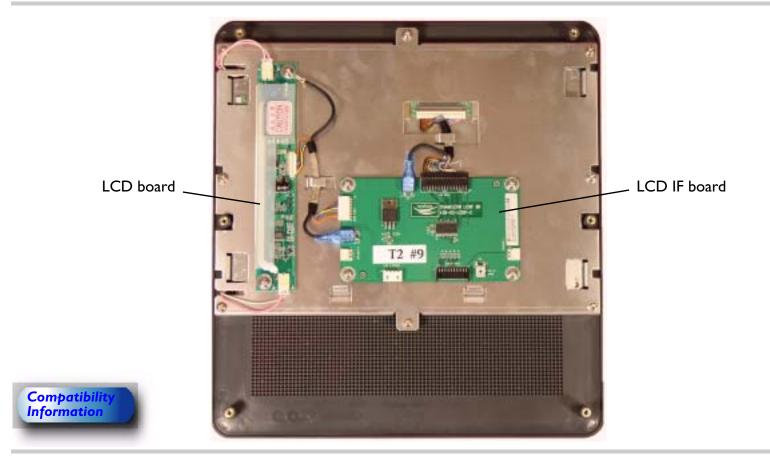
#### **HD3 Primary System PCB Names and Locations (Control Panel)**



**Video Monitor PCBs** 

Figure 13-5

**Video Monitor PCBs (Back of Monitor LCD)** 



**Control Panel PCBs** 

Figure 13-6

**Control Panel Interface and Keyboard PCBs (Top Half of Control Panel)** 

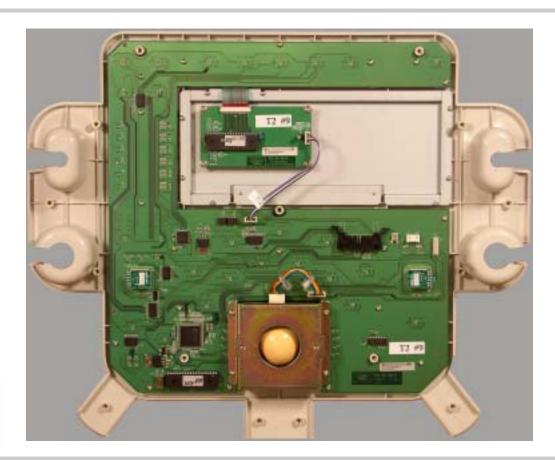
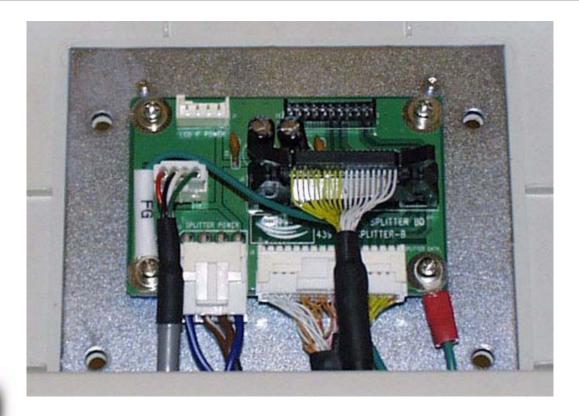




Figure 13-7

#### **Control Panel Splitter Board (Bottom Half of Control Panel)**





**E-box PCBs** 

**CSIP Level I** 

4535 612 34161

#### Figure 13-8 **Transducer Connector Assembly (TCA)**







- Front -

- Back -

Figure 13-1

Assembly

Figure 13-9

#### **Backplane Assembly**



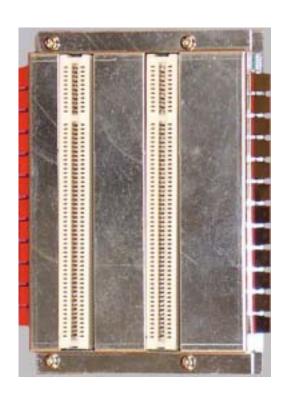
Board



Figure 13-1

**Beamformer - to - Frontend Connector (BFC)** 







4535 612 34161 **CSIP Level I** 

Figure 13-10

- Front -

- Back -

Figure 13-1

Figure 13-11

Front End (FE) Assembly

FE board PSA-IF PCB See Figure 14-16

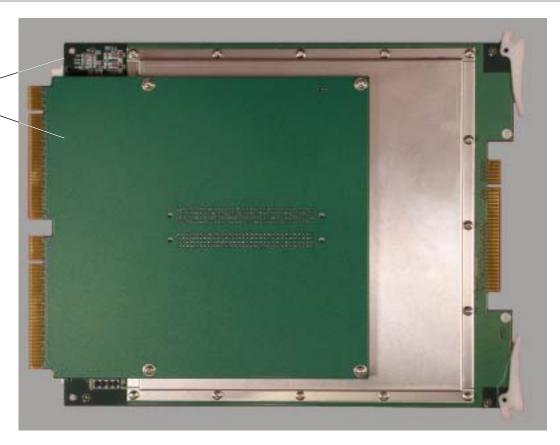




Figure 13-1

Figure 13-12

Beamformer (BF) Board





Figure 13-13 Digital Scan Converter (DSC) Board

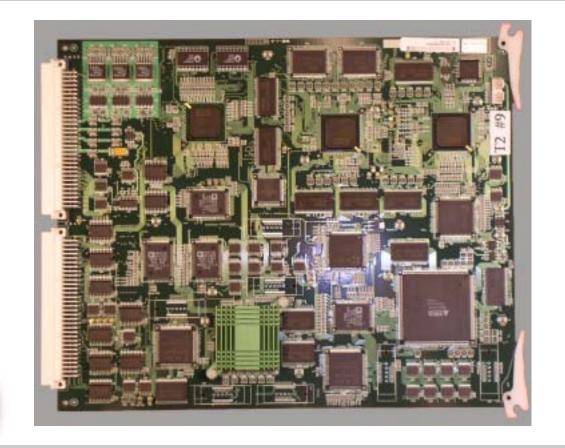




Figure 13-14

**PCC Board** 





Rear I/O Panel PCB

Figure 13-15 Rear I/O Panel PCB





Power I/O Box PCB

Figure 13-16

**Power I/O Box PCB** 





Disk Drive Settings

**CSIP Level I** 

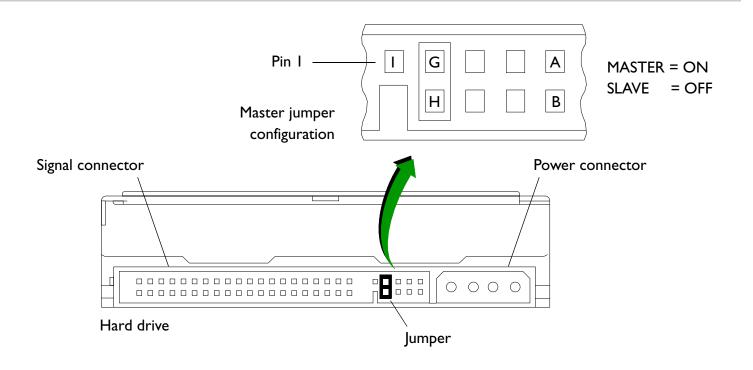
4535 612 34161

The jumper positions and switch settings of the drives in the HD3 system depend on the manufacturer of the drives.

Hard Drive Jumpers

Figure 13-17 shows typical hard drive jumper positions. Examine the drive itself for information on the correct settings. The hard drive is the only device on the primary IDE, and is usually set to MASTER or SINGLE.

Figure 13-17 Hard Drive Jumper Settings



CD-RW Drive Jumpers

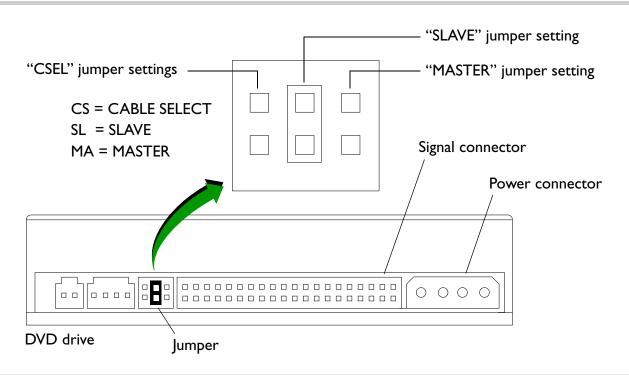
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**CSIP Level I** 

Figure 13-18

Figure 13-18 shows typical CD-RW drive jumper positions. Set the jumper to the MASTER position on the secondary IDE.

#### **CD-RW Drive Jumper Position**



4535 612 34161

**Jumpers** 

**Peripheral** 

**HD3 Service Manual** 

**Page 266** 

# Settings this section B/W Printer The Sony U switch setting Table 13-2

Table 13-2	UP-895MD Printer Switch Settings
CONTROL	SETTING
Front of Printer	
NOR/SML	NOR
STD/SIDE	SIDE
POSI/NEGA	POSI
BRIGHT	6
CONT	7
Inside the Paper T	ray
(The power must be	turned on to access the switches inside the
paper tray: Press <b>OP</b>	<b>PEN</b> and remove the paper roll.)
SHARPNESS	III
GAMMA	II
PAPER TYPE	V (UPP-I I0HG)
SMOOTHING	OFF

Color	Printe

**CSIP Level I** 

**Table 13-2 UP-895MD Printer Switch Settings (Continued)** 

Rear of Printer	
DIP Switches 1-12	Down

The Philips-recommended UP-21MD settings are listed in Table 13-3.

able 13-3 UP-21MD Printer Settings		
	HD3 Default Sett	ings <sup>l</sup>
Menus and Parameters	NTSC Settings	PAL Settings
COL:		
Load Color:	I	I
CYN – RED:	0	0
MAG – RGB:	0	0
YEL – BLU:	0	0
Dark:	1	I
Light:	-3	-3
Sharpness:	8	8
Interpol:	OFF	OFF
Save Color:	I [EXEC]	I [EXEC]
LAY:		
Memory:	Frame	Frame
Multi Pix:	I	I
Separate:	OFF	OFF

Table 13-3 UP-21MD Printer Settings (Continued)
Table 13-3 UP-21MD Printer Settings (Continued

	HD3 Default Settings I		
Menus and Parameters	NTSC Settings	PAL Settings	
Window:			
H Start:	-20 Dots	12 Dots	
V Start:	-4 Dots	-14 Dots	
H Width:	976 Dots	912 Dots	
V Width:	476 Dots	548 Dots	
Save:	Press [EXEC]	Press [EXEC]	
Caption:	OFF	OFF	
PRN:			
Print QLT:	I	I	
GAMMA:	NORMAL	NORMAL	
PRN Speed:	HIGH	HIGH	
Load user:	1	I	
System Setup:			
LCD. Center:	7	7	
Baud Rate:	4800	4800	
Beep:	ON	ON	
IRE.:	100	100	
Save User:	I	ſ	

Table 13
----------

#### **UP-21MD Printer Settings (Continued)**

	HD3 Default Settings	
Menus and Parameters	NTSC Settings	PAL Settings
Function:		
Auto Live:	OFF	OFF
Immed. Cap.:	OFF	OFF
RM2 Func.:	C&Print	C&Print
Clear:	ALL	ALL
Color Balance:		
BAL X:	50	50
BAL Y:	50	50
BAL Step:	5	5
IN:		
INPUT SEL:		
Video:	N/A	N/A
S – Video:	N/A	N/A
RGB:		
Hue:	0	0
Color:	0	0
Gain:	0	0
Offset:	0	0
AGC:	OFF	OFF

Table 13-3 UP-21MD Printer Settings (Continued)		
HD3 Default Settings		
Menus and Parameters	NTSC Settings	PAL Settings
OUT:		
Display:	OFF	OFF
RBN Remain:	OFF	OFF
Source:	THRU	THRU
Sync on G:	OFF	OFF
Moni C–R:	0	0
Moni M–G:	0	0
Moni Y-B:	0	0

I. The NTSC/PAL switch on the rear of the printer is set to the video format designated on the customer order.

## **VCR**

subishi HS-MD3000U/E VCR settings for use with the HD3 are given in Table 13-4, Table 13-5, and Table 13-6. **NOTE** All switches and internal menus settings should be set properly at the factory on VCRs

The VCR has front/rear panel switches, displayed menu settings, and hidden menu settings. Mit-

shipped with new systems. However, when a replacement VCR is ordered, you will need to check the switch settings and menu settings The displayed menu settings are listed in Table 13-5. To verify or reset these settings, see "To

Table 13-5 to enter the settings listed. (Only the numerical code that corresponds to setting is displayed. You will not see the setting titles.) The hidden menu settings are listed in Table 13-6. To verify or reset these settings, see "To

change the VCR displayed menu settings" on page 275. Enter the numerical code from

change the VCR hidden menu settings" on page 276.

Table 13-4	HS-MD3000U/E VCR Control and Switch Setting		
Parameter	NTSC Setting (MD3000U)	PAL Setting (MD3000E)	
Front Panel Controls			
Monitor	MIX	MIX	
Audio	HIFI	HIFI	
Keylock	OFF	OFF	
<b>Rear Panel Controls</b>			
75 Ohm Video	ON	ON	
75 Ohm S-Video	ON	ON	

4535 612 34161

**CSIP Level I** 

in in the second of the second			
Parameter	NTSC Setting (Not Displayed)	PAL Setting (Not Displayed)	Numeric Code (Displayed)
Menu I			
Rec Tape End	Stop	Stop	101:00
Tape End	Stop	Stop	102:00
Tape In	Stop	Stop	103:00
Tape Length	T-120	E-180	104:00
VISS	REC	REC	105:01
Time Code Rec.	OFF	OFF	106:00
Time Code Disp	OFF	OFF	107:00
Foot Switch	L.E.	L.E.	108:00
Dimmer	OFF	OFF	109:00
Menu 2			
S-VHS/S-ET	ON/OFF	Auto	201:01
Y-NR	ON	ON	202:01
C-NR	ON	ON	203:01
Y-Enhancer	ON	ON	204:01
TBC	ON	ON	205:01
Color Filter	OFF	OFF	206:00
Freeze Mode	Frame	Frame	207:00

Table 13-5	HS-MD3000U/E VCR Displayed Menu Settings		
Hi-Fi Audio	ON	ON	208:01
Normal Audio In	MIX	MIX	209:00
Menu 3			
Daylight Savings	OFF (No time/date	OFF (No time/	301:00
	set)	date set)	
Month	01	01	Do not set
Day	01	01	Do not set
Year	2004	2004	Do not set
Time	00:00:00	00:00:00	Do not set
Language Menu <sup>2</sup>			
Language	English (displayed)	English (displayed)	001:00

- 1. VCRs are shipped with the Menu 3 ("clock") functions left at the factory defaults shown because the system also provides these functions and the VCR clock is not likely to be used. If the VCR clock is set, it will cause the normal (standby) display of the VCR to display the time of day rather than tape location time, which may be confusing to some users. Pressing **RESET** restores these settings to the factory defaults shown, but also resets the Language setting (see <sup>2</sup>).
- 2. VCRs are shipped with the Language set to English. If you want to change the Language setting, press **RESET** and cycle through the languages displayed on the VCR display. Remember, pressing **RESET** also restores the VCR clock settings to the factory defaults (see | ).

4535 612 34161

**CSIP Level I** 

- I. Power up the VCR.
- 2. Press and hold **Menu** for at least 2 seconds to initiate the VCR display.
- Select items with **JOG/ADJUST**. Refer to Table 13-5 for displayed menu settings.
- 4. Select settings with **FRAME/FIELD ENTER**.
- 5. Change the settings with JOG/ADJUST.
- 6. Exit and save changes by pressing **MENU**.

**Table 13-6** Mitsubishi HS-MD3000E/U VCR Hidden Menu Settings

Setting/Item	Display	NTSC Setting	PAL Setting
Picture Control (Sharpness)	PC	0	0
(Head) Switching Point	SP	65	65
Position Up/Down	Ud	0	0
Position Left/right	Lr	0	0
Chroma Amplitude	CA	2	2
Hue (Color Phase)	СР	0	0
Color Delay	Cd	2	2
	bС	-I	-I
	CC	I	I
	bd	ON	ON

#### ➤ To change the VCR hidden menu settings

- Power up the VCR.
- 2. Press and hold **Stop** and **Play** simultaneously for at least 10 seconds to initiate the VCR display item corresponding to the functions.
- 3. Select settings with **FRAME/FIELD ENTER**. Refer to Table 13-6 for hidden menu settings.
- 4. Change the settings with **JOG/ADJUST**.
- 5. Exit and save changes by pressing **STOP**

4535 612 34161 HD3 Service Manual
CSIP Level I

Page 277
Parts: Introduction

#### 14 Parts

#### Introduction

This section contains general and specific parts information for the HD3 Ultrasound System.

## How and Where to Find a Part Number

In this manual, system field-replaceable parts and cables are shown in illustrations and are listed in tables.

Use the parts and cable illustrations to visually locate and identify the part you are looking for. The part number is included in the figure and is linked to the corresponding parts table where a part description is provided.

Or, to find a part number by its description, look in the parts tables Table 14-1, which are alphabetized by the part descriptions.

#### **Parts Locator Map**

Go to the "HD3 Ultrasound System Parts Locator Map" Figure 14-1 to start your search or one of the other applicable parts information links as follows:

- For signal interconnect cable part numbers, see Figure 11-1 and Table 11-1.
- For power distribution cable part numbers, see Figure 11-2 and Table 11-1.
- For transducer part numbers, see Section 15, "Transducers".
- For accessories and options part numbers, see Table 14-2.
- For peripheral part numbers and applicable cables, see Table 14-2.

#### Figure Conventions

1, 2, 3, etc

**Item Number** The item number for each part or subassembly shown in an illustration is a hypertext cross-reference linking to the parts/cable tables containing parts descriptions and additional information.

See Figure 14-X

4535 612 34161

**CSIP Level I** 

**See Figure** "See Figure" is a hypertext cross-reference link to a detail (subassembly) figure. In the subassembly figure you will find either the part number, a reference to another detail figure, or a reference to the table containing parts descriptions and additional information.

**SYSTEM VIEW** 

**System View Illustration Label** The "SYSTEM VIEW" (System Parts Locator Map), Figure 14-1 contains links to "PARENT VIEW" illustrations.

**PARENT VIEW** 

**Parent View Illustration Label** "PARENT VIEW" indicates an illustration that provides links to additional parts breakdown, indicated with a "See Figure" reference.

System View

**System View Button** The "System View" button is a hypertext cross-reference link to the "SYSTEM VIEW" (System Parts Locator Map). You can return to the "SYSTEM VIEW" (System Parts Locator Map) by clicking the "System View" button in the lower left corner of any figure in this section.

**Parent View** 

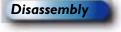
**Parent View Button** The "Parent View" button is a hypertext link to the parent-part or "PARENT VIEW" illustration.

Parts List

**Parts List Button** The "Parts List" button (located on the "System Parts Locator Map" only) is a hypertext cross-reference linking to the "Parts Table" containing parts descriptions and additional information. The "Parts List" can also be accessed by clicking one of the blue part numbers in any of the figures in this section.

Installation

**Installation Button** The "Installation" button is a hypertext link to a figure's corresponding installation/removal procedure.



4535 612 34161

**CSIP Level I** 



Disassembly Button The "Disassembly" button is a hypertext link to figures corresponding to a disassembly/assembly procedure.

**Green Arrow** The green arrows found throughout the parts illustrations are used to indicate movement (direction, rotation), or point to a specific area (details, breakdowns).

#### **Parts Table Definitions**

Item No. This column lists the item numbers that correspond to parts in the parts illustrations.

**Located On** This column lists all of the figures on which the part is found.

Legacy Part Number This column lists the legacy part number for an item. Use this column only if you are in North America or Canada, or you order directly from Bothell. These numbers correspond to the PRI SAP system. If a table is referenced in this column, the part number is on that table.

12NC Part Number This column lists the 12NC part number for an item. Use this column if you are ordering from an APEC, an EMEA, or an LATAM country. I2NC numbers can be used for parts orders worldwide. These numbers correspond to the MIP SAP system used by the SLIs and Miami. If a table is referenced in this column, the part number is on that table.

Part Description The name or common description of the item is listed here. Where appropriate, the description column also includes size, tolerance, type or model, and material data for the part. Parts tables are alphabetized by this column.

Attaching parts must be ordered separately. They are not provided with the assembly, the subassembly, or the component being attached.

**Notes/Reference** Manufacturer's part numbers, sometimes alternate part numbers, special applications, and other information pertaining to a specific part are listed in the Notes/Reference column. For top assemblies containing many replaceable parts, the applicable figure or table for further breakdown of parts is listed here.

## Field Service Engineers

For parts ordering procedures, FSEs should refer to their standard operating procedures.

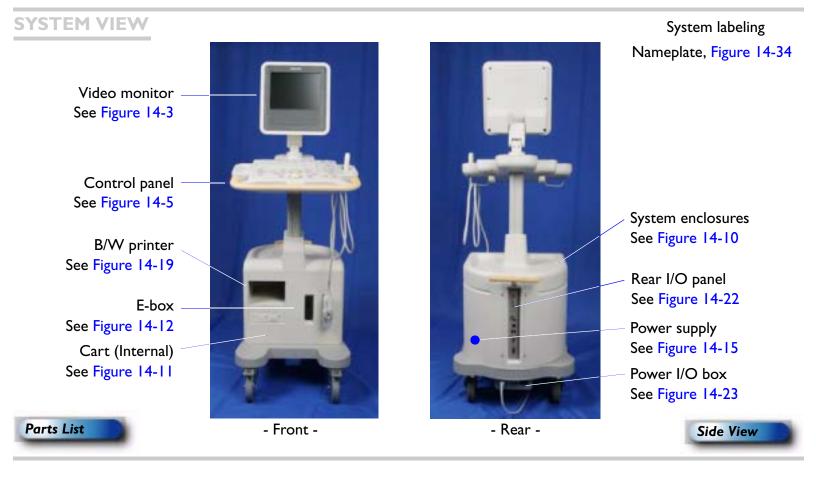
#### Customers

Customers can order parts through an FSE or directly from the Customer Service Order Processing Department. Customers ordering parts through an FSE will need to provide the following information:

- Shipping address
- Purchase order number of equipment
- Part numbers or sales order numbers
- Part descriptions and quantity needed

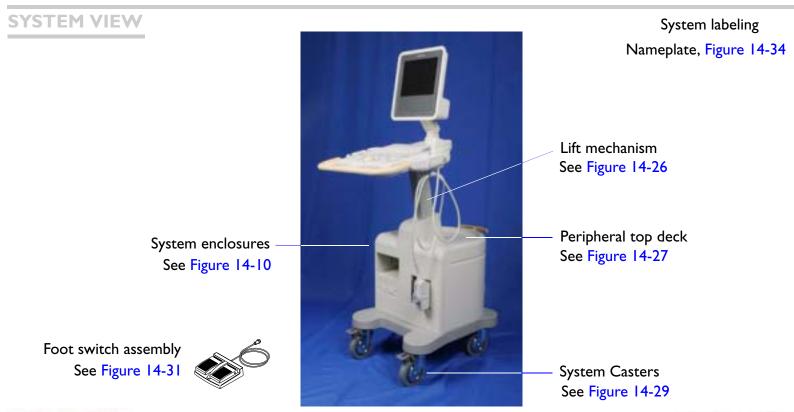
#### Illustrations

Figure 14-1 HD3 Ultrasound System Parts Locator Map (Front and Rear Views)



**End Views** 

#### HD3 Ultrasound System Parts Locator Map (Right Side)



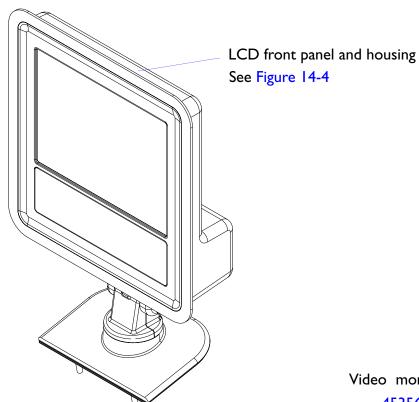
Parts List

- Right side -

Figure 14-3

#### Video Monitor Assembly

#### **PARENT VIEW**



Disassembly

System View

Video monitor assembly

453561221061

Page 284
Parts: Illustrations

Figure 14-4

Video Monitor Assembly (LCD Front Panel and Housing)

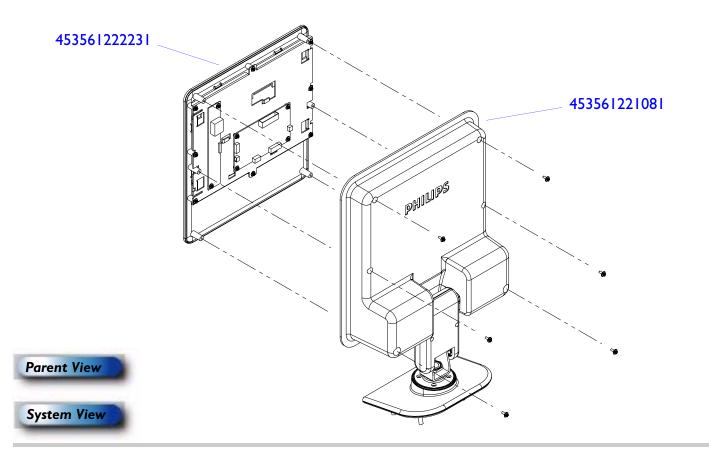


Figure 14-5

#### **Control Panel**

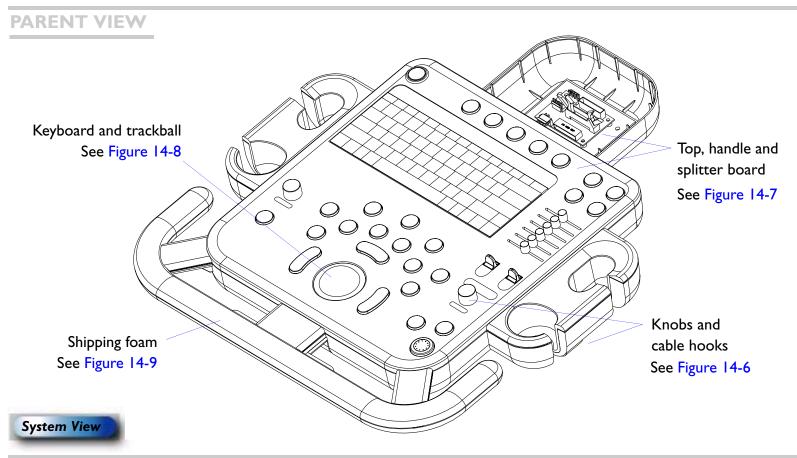


Figure 14-6

#### Control Panel (Knobs and Cable Hooks)

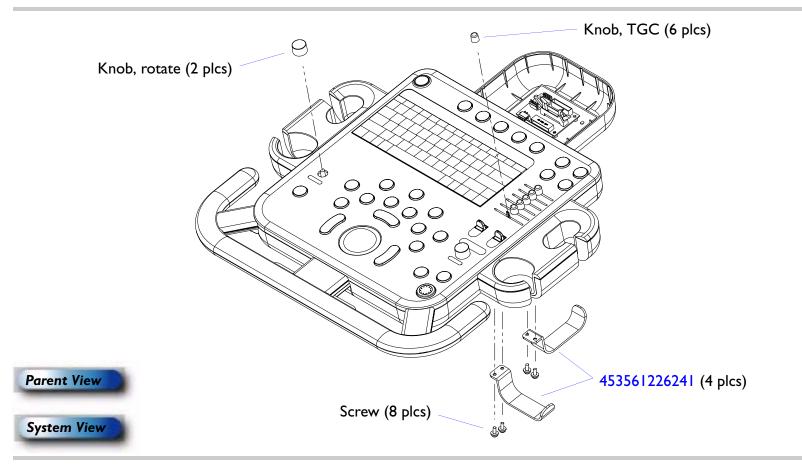


Figure 14-7

#### **Control Panel (Top, Handle and Splitter Board)**

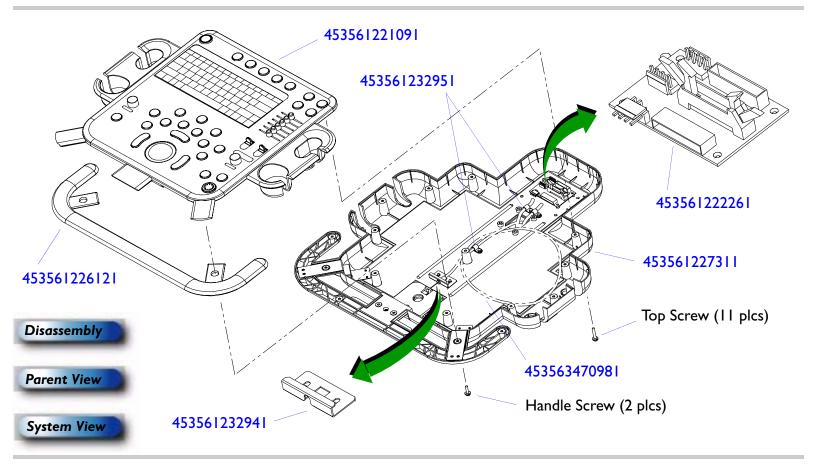
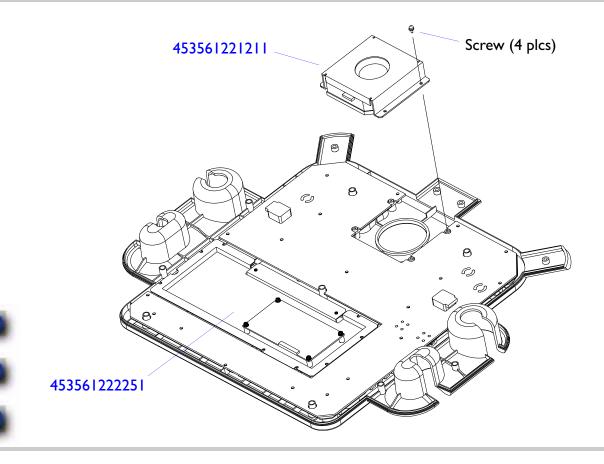


Figure 14-8

#### Control Panel (Keyboard and Trackball)



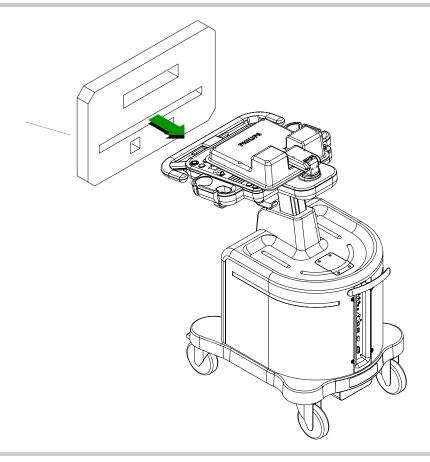
Disassembly

Parent View

System View

Page 289
Parts: Illustrations

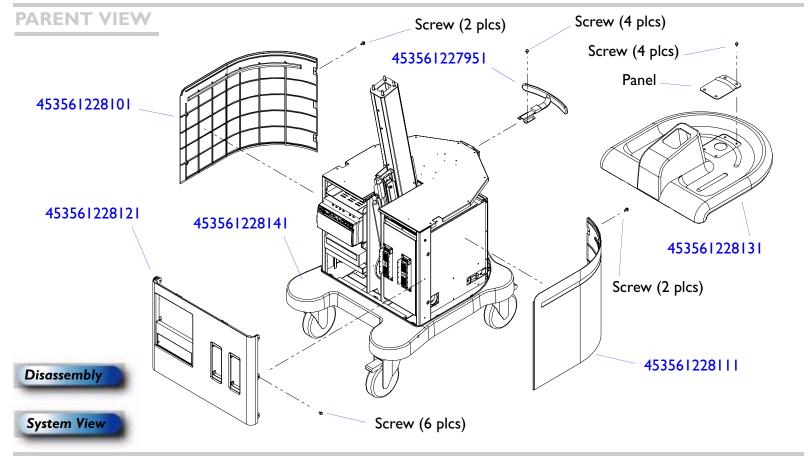
Figure 14-9 Control Panel (Monitor Support Shipping Foam)



Installation

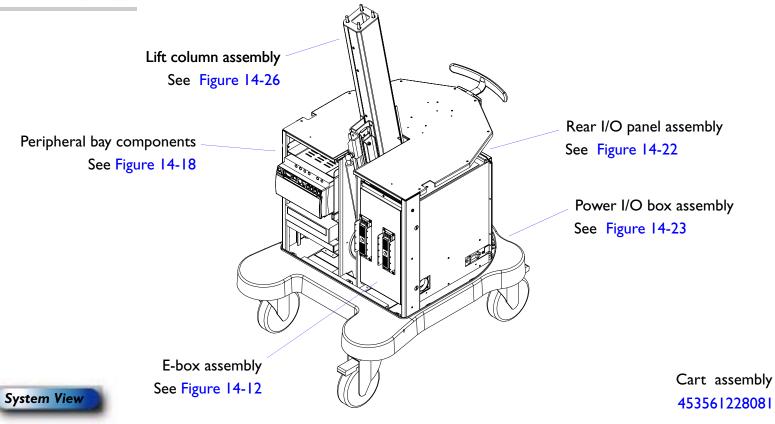
**Parent View** 

System Enclosures



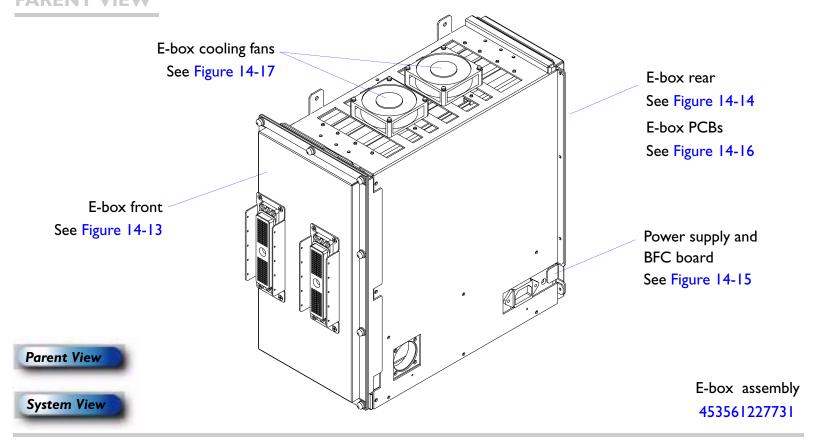
Cart (Internal)

#### **PARENT VIEW**



E-box Assembly





4535 612 34161 HD3 Service Manual Page 293
CSIP Level I Parts: Illustrations

Figure 14-13 Transducer Connector Assembly (TCA) and E-box Motherboard (Front Side of E-box)

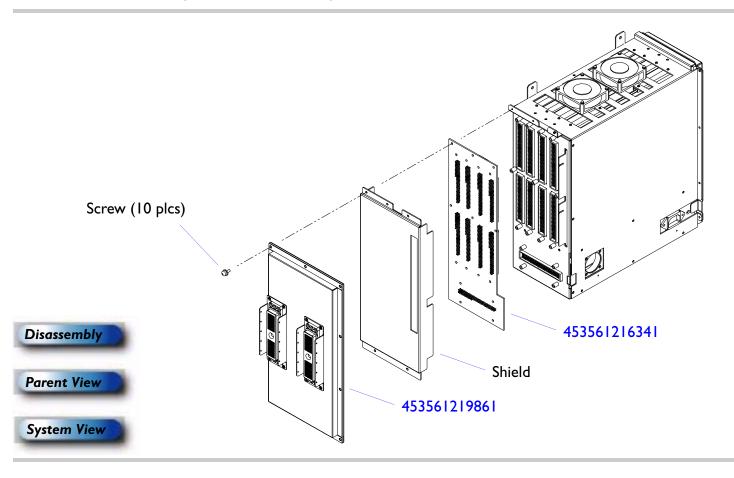
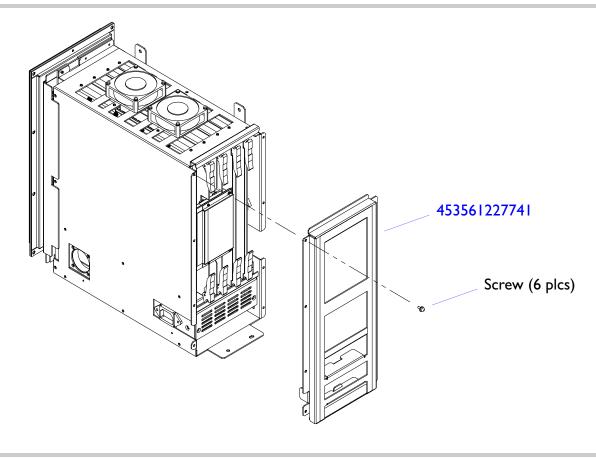


Figure 14-14

# E-box Boards and Power Supply Access Panel (Rear-side of E-box)



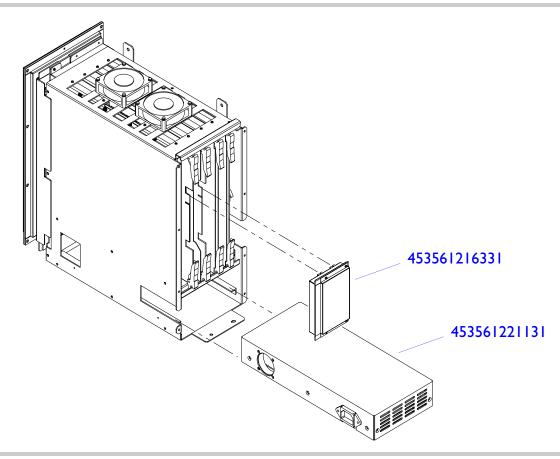
Disassembly

**Parent View** 

**HD3 Service Manual** 

Page 295 **Parts: Illustrations** 

**Figure 14-15 Power Supply and BFC Board** 



Disassembly

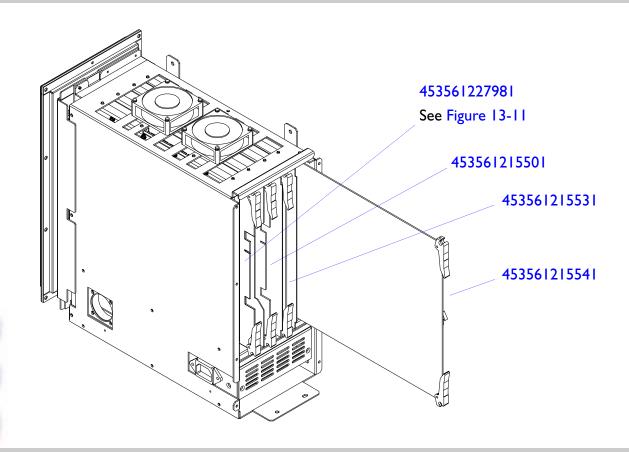
**Parent View** 

Page 296 Parts: Illustrations

Figure 14-16 E-box Boards

Disassembly

**Parent View** 



Disassembly

**Parent View** 

System View

E-box Cooling Fans

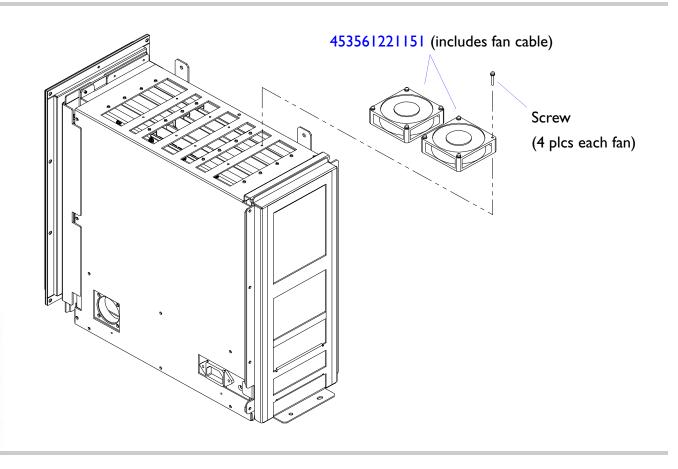
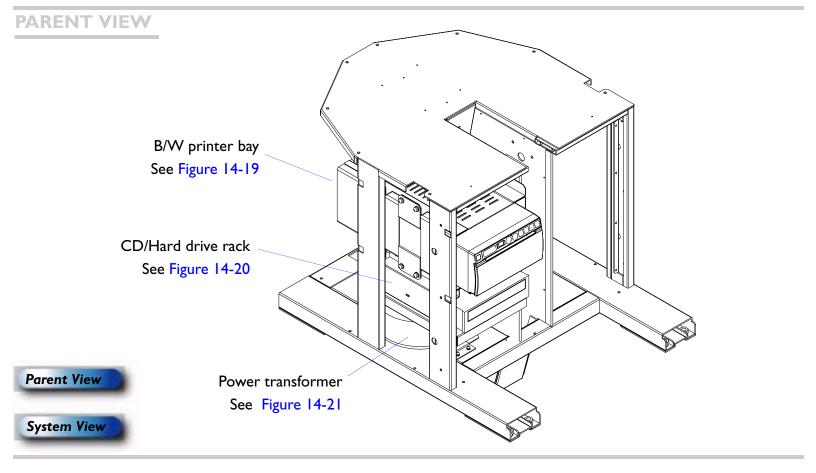
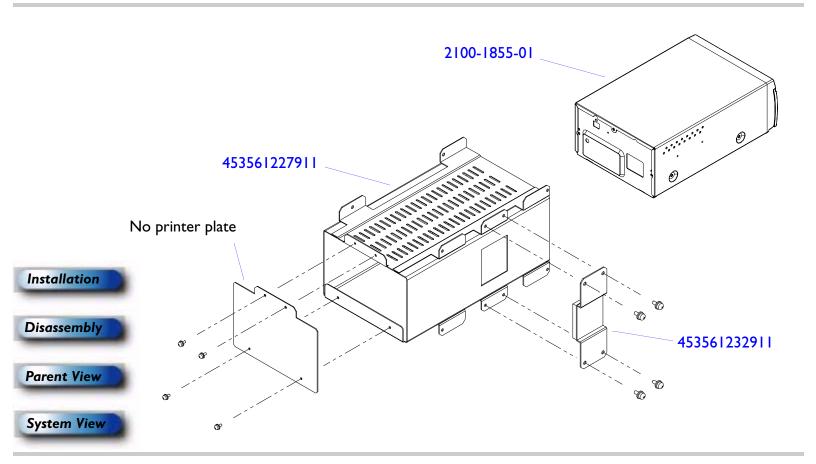


Figure 14-18

## **Peripheral Bay Components**



**B/W Printer Bay** 



Hard Drive and CD Drive Rack

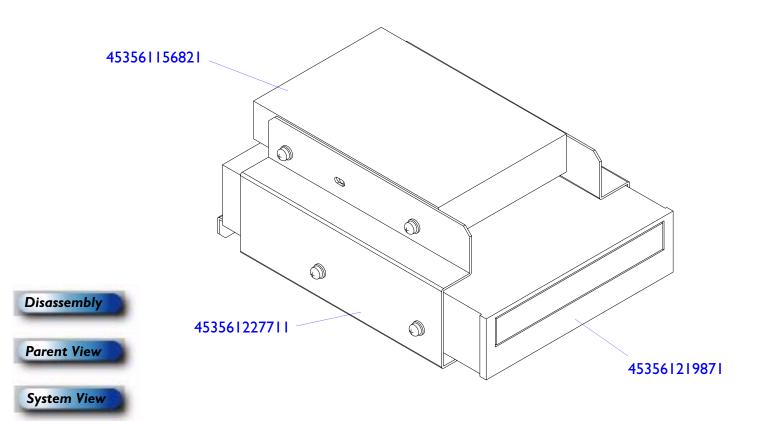
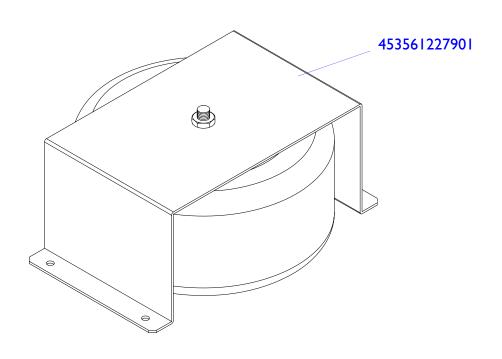


Figure 14-21 F

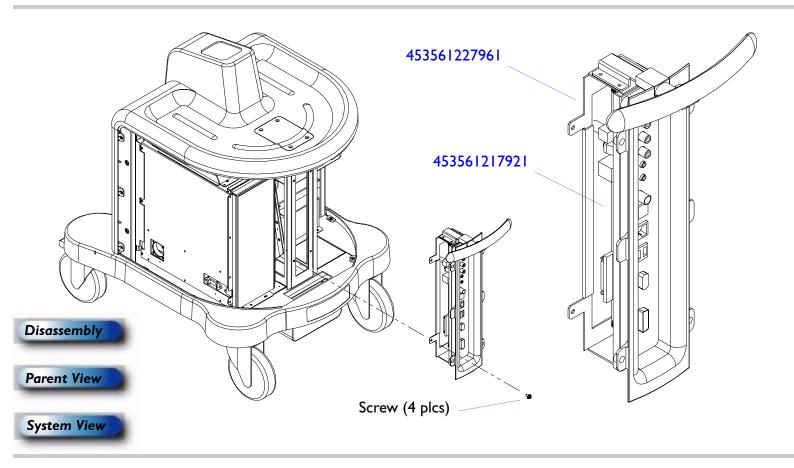
**Power Transformer** 



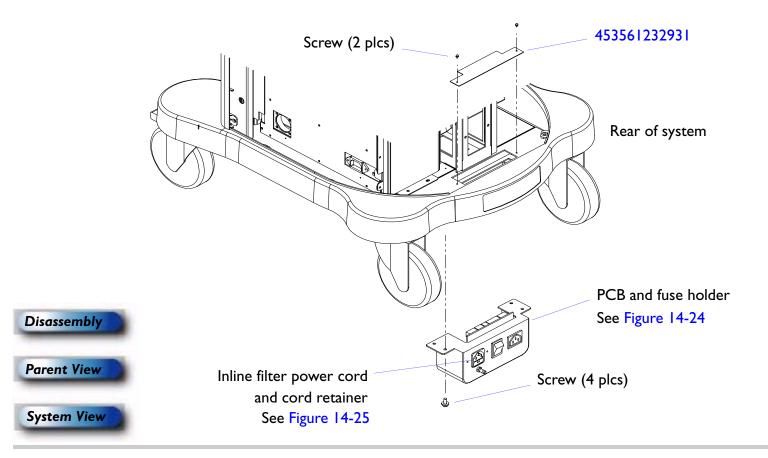
Disassembly

**Parent View** 

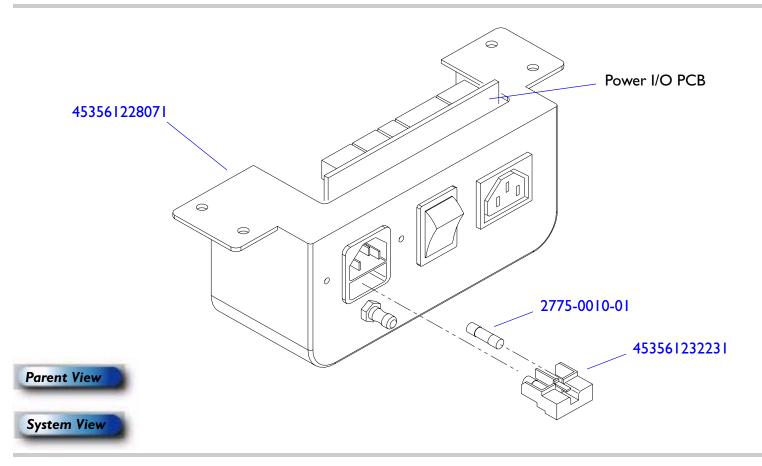
Rear I/O Panel Assembly



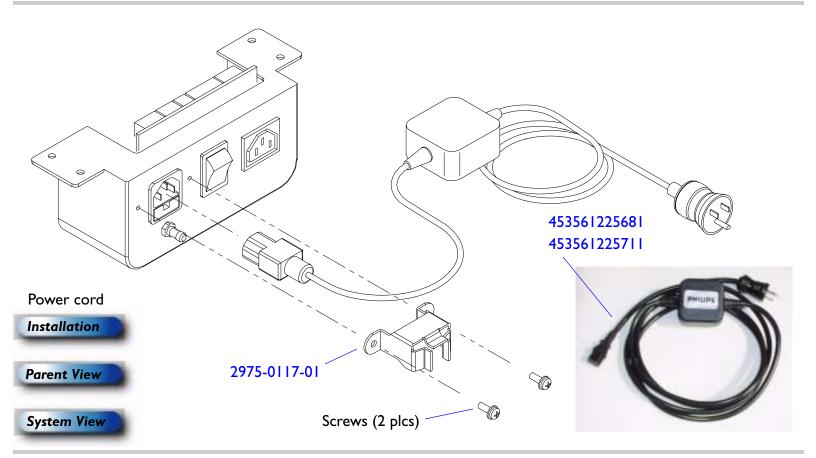
Power I/O Box Assembly



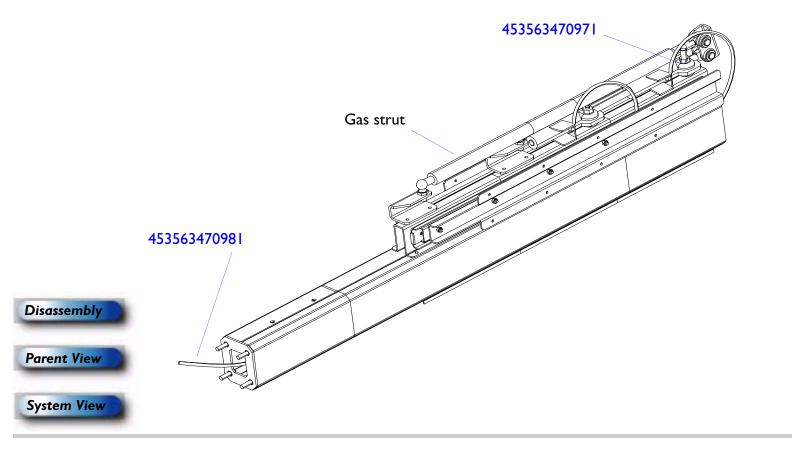
Power I/O Box (PCB and Fuse Holder)



# Power I/O Box (Inline Filter Power Cord and Cord Retainer)



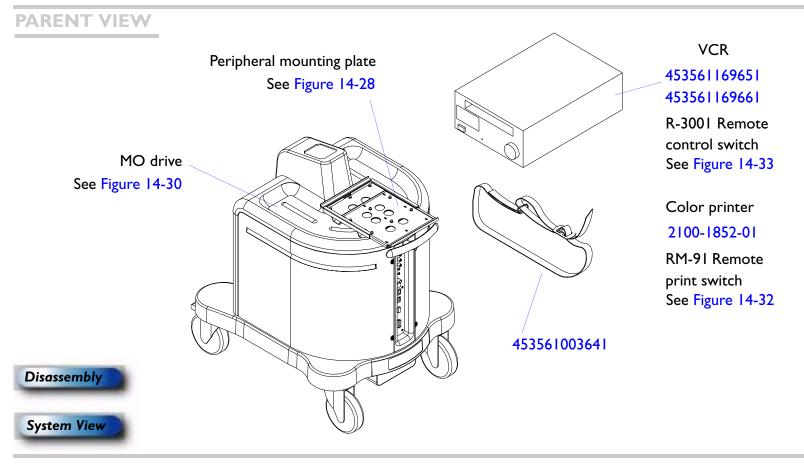
Lift Mechanism (Mechlok Assembly and Gas Strut)



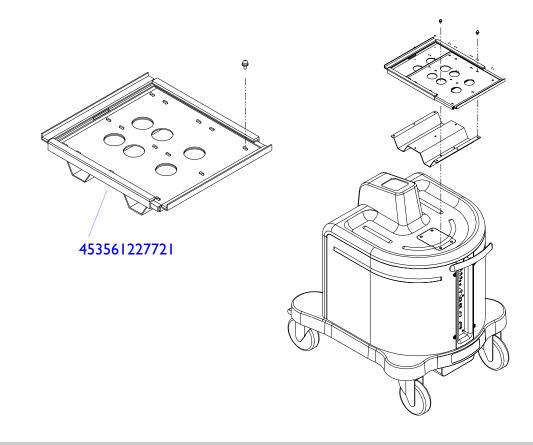
3 Service Manual Page 307
Parts: Illustrations

### Figure 14-27

# Peripheral Top Deck (VCR or Color Printer and MO drive)



# **Peripheral Mounting Plate (Uni-mount)**



Color printer

Installation

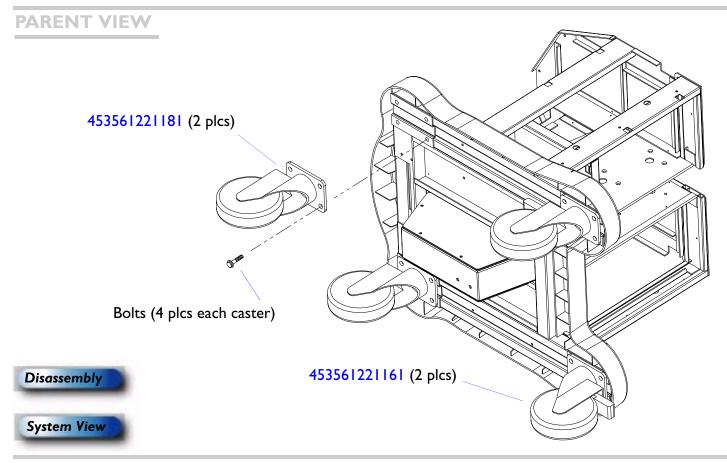
**VCR** 

Installation

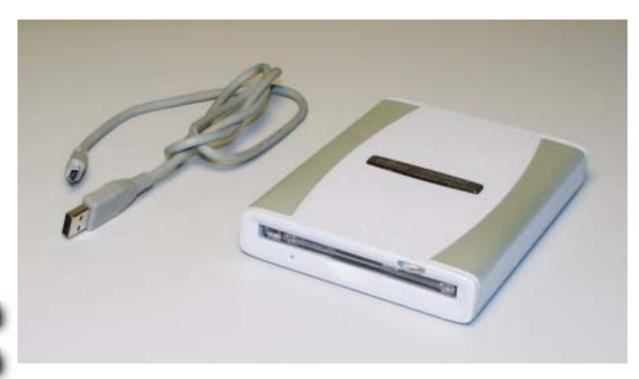
Disassembly

**Parent View** 

System Casters



**MO** Drive Figure 14-30



Installation

**Parent View** 

System View

MO drive assembly 453561217871

453561227971

Figure 14-31

# Foot Switch Assembly and Adapter Cable



453561217911

Installation

**HD3 Service Manual** 

Page 312 Parts: Illustrations

Figure 14-32 RM-91 Sony Color Printer Remote Control Print Switch



**Parent View** 

System View

RM-91 remote print switch 989605300741

Page 313
Parts: Illustrations

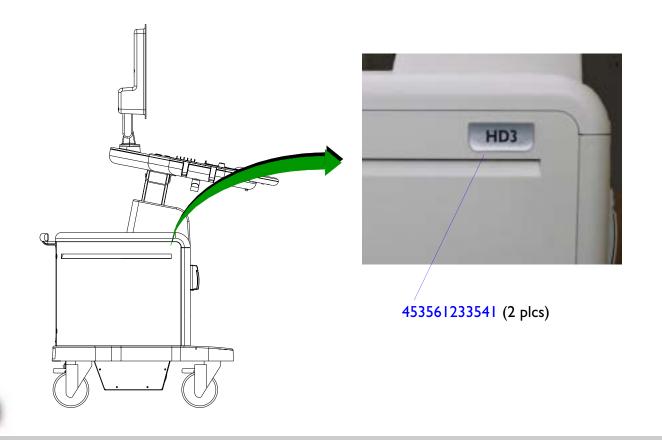
Figure 14-33 R-3001 Mitsubishi VCR Wired Remote Control



**Parent View** 

System View

R-3001 VCR remote control 453561228091



# Parts List

Table 14-1 HD3 Ultrasound System Parts List

Located			
On	Part Number	Part Description	Notes/Reference
Figure 14-7	453561232941	Bracket, Cable Adjustment	Control panel mechanical cable bracket
			Manufacturing No: 235-P-320A
Figure 14-20	453561227711	Bracket, CD/Hard Drive	Manufacturing No: 235-P-317A-00
Figure 14-25	2975-0117-01	Bracket, Plug, HDI 4000	AC power cord retainer bracket
			Manufacturing No: 235-P-149D
Figure 14-7	453563470981	Cable Assy, MechLok	Mechanical cable used on the MeckLok
Figure 14-26			assembly
			Legacy No: M2540-80035
Figure 11-2	Table II-I	Cables, Power Distribution	
Figure II-I	Table II-I	Cables, Signal Interconnect	
Figure 14-11	453561228081	Cart	Manufacturing No: ASP-439-CART
Figure 14-29	453561221161	Caster, Front (Wheel)	Manufacturing No: 333-Z-701-1
Figure 14-29	453561221181	Caster, Rear (Wheel)	Manufacturing No: 333-Z-015A
Figure 14-7	453561232951	Clamp, Cable, P-Clip	Manufacturing No: CLA-N5-01
Figure 14-7	453561221091	Control Panel Assembly	Manufacturing No: ASP-439-KBD
			Includes: Trackball
Figure 14-7	453561227311	Control Panel Lower Housing	Manufacturing No: A215-169A
Figure 14-14	453561227741	Cover, E-box	Manufacturing No: ASP-439-ECOVER

Page 316
Parts: Parts List

Table 14-1	I4-I HD3 Ultrasound System Parts List (Continued)		
Located On	Part Number	Part Description	Notes/Reference
Figure 14-20	453561219871	Drive, CD-RW	Manufacturing No: PC-CD/ RW-GCE-8526B-00
Figure 14-20	453561156821	Drive, Hard Disk, Seagate, 80GB	Manufacturing No: HDD-80G-SEAGATE-00
Figure 14-30	453561217871	Drive, MO, 1.3GB	Manufacturing No: PC-MO-MDK3130UK Includes: USB cable
Figure 14-12	453561227731	E-box Assembly	Manufacturing No: ASP-439-EBOX Includes: Fans, all E-box PCBs, BFC, and power supply
Figure 14-17	453561221151	Fan Assembly, E-box	Manufacturing No: AY-FAN-439-TOP-00 Includes: One fan with cable
Figure 14-19	453561232911	Fastener, Printer Bay	Manufacturing No: ASP-439-SPRBAY B/W printer retainer bracket
Figure 14-31	453561217911	Foot Switch Assembly	Manufacturing No: FOOT-S/W UNIT-00 See "Cable Assy, Foot Switch Adapter"
Figure 14-24	2775-0010-01	Fuse, 50T10L250V, Schuter, OEM Service	Alias No: 453561096111 Used in fuse holder located on power I/O box
Figure 14-24	453561232231	Fuse Holder, 2 Pole, Snap-In Mount	Part of power I/O box
Figure 14-26		Gas Strut	Lift mechanism

Part Number

**Notes/Reference** 

Page 317

Table 14-1	
Located	

On

# HD3 Ultrasound System Parts List (Continued)

**Part Description** 

		•	
Figure 14-7	453561226121	Handle, Front, Top	Manufacturing No: 252-M-035A-00
Figure 14-10	453561227951	Handle, Rear, Power Cable	Manufacturing No: A255-008A
Figure 14-6	453561226241	Hanger, Cable, Control Panel	Manufacturing No: 255-P-009A-00
Figure 14-19	453561227911	Housing Assy, Printer Bay, Black and White	Manufacturing No: ASP-439-PRBAY-00
Figure 14-23	453561232931	Insulator, Power I/O Assembly	Manufacturing No: 323-Z-008A
Figure 14-8	453561222251	Keyboard Assembly, QWERTY	Manufacturing No: ASP-439-ANK
Figure 14-34	453561233541	Label, Nameplate, System	Manufacturing No: 275-K-A244A
			HD3 Badge
			One on each side of system
Figure 14-4	453561222231	LCD Panel Assembly	Manufacturing No: ASP-439-LCD-00
			Includes: LCD, front panel, and LCD
			circuit boards
Figure 14-26	453563470971	MechLok Assembly	Lift mechanism
			Legacy No: M2540-80030
Figure 14-28	453561227721	OEM Tray Assembly	Universal peripheral mounting plate
Figure 14-10	453561228141	Panel, Bottom	Manufacturing No: 215-M-315A-00
Figure 14-10	453561228121	Panel, Front	Manufacturing No: 215-M-327A-00
Figure 14-10	453561228101	Panel, Left Side	Manufacturing No: 215-M-328A-00
Figure 14-10	453561228111	Panel, Right Side	Manufacturing No: 215-M-329A-00
Figure 14-10	453561228131	Panel, Top	Manufacturing No: 215-M-316A-00

# HD3 Ultrasound System Parts List (Continued)

On	Part Number	Part Description	Notes/Reference
Figure 14-16	453561215501	PCB Assy, Beamformer (BF)	Manufacturing No: BD-439-BF-0B
Figure 14-15	453561216331	PCB Assy, Beamformer Connector (BFC)	Manufacturing No: BD-439-BFC-0A
			Connects BF and FE PCBs
Figure 14-16	453561215531	PCB Assy, Digital Scan Converter (DSC)	Manufacturing No: BD-439-DSC-0A
Figure 14-13	453561216341	PCB Assy, Motherboard (Backplane)	Manufacturing No: BD-439-MTH-0A
Figure 14-16	453561227981	PCB Assy, Front End	Manufacturing No: ASP-439-FE
			Front End Assembly
Figure 14-16	453561215541	PCB Assy, Processor (PCC)	Manufacturing No: BD-439-PCC-0A
Figure 14-22	453561217921	PCB Assy, Rear I/O Panel	Manufacturing No: BD-439-RP-0A
Figure 14-7	453561222261	PCB Assy, Splitter Board	Manufacturing No: BD-439-SPLITTER-0A
Figure 14-24	453561228071	Power I/O Assembly	Manufacturing No: AY-439-I/O-Box-00
Figure 14-15	453561221131	Power Supply Assembly, E-box	Manufacturing No: AY-439-POWER-00
Figure 14-22	453561227961	Rear I/O Housing	Manufacturing No: ASP-439-RH
Figure 14-32	989605300741	Remote Control, Sony, RM-91	Remote print switch used for color
			printer installations
			Diagram: Figure 11-2
Figure 14-33	453561228091	Remote Control, VCR Wired, R-3001	Remote control used for VCR
			installations
			Diagram: Figure 11-3

Table 14-1

Includes: Speakers, cables, and hinge

Located			
On	Part Number	Part Description	Notes/Reference
Figure 14-9		Shipping Foam, Keyboard	Manufacturing No: 364-Z-094A
			Slides over control panel for support of the video monitor.
			For use when transporting the system in vans or other mobile units.
Figure 14-27	453561003641	Strap, Universal OEM	One strap required to secure OEM to
			peripheral mounting plate
Figure 14-8	453561221211	Trackball Assembly	Manufacturing No: 335-C-007A-00
Figure 14-13	453561219861	Transducer Connector Assembly	Transducer Select Assembly (TCA)
			Manufacturing No: ASP-439-PSA-0A
Figure 14-21	453561227901	Transformer	Manufacturing No: ASP-439-TRANS-00
			Includes: Shield and cables
Figure 14-3	453561221061	Video Monitor Assembly	Manufacturing No: ASP-439-MNT-00
Figure 14-4	453561221081	Video Monitor Housing	Manufacturing No: ASP-439-RMNT-00

Page 320

# **Peripherals Parts List**

**Table 14-2** 

**Peripherals and Applicable Cables** 

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No.	Part Description	Part Number	Power Cable	Signal Cable	References
I	Printer, Black-and-White,	2100-1855-01	453561227921	2275-0038	Alias No:
	UP-895MD, Sony				453561059841
					Photo
					Figure I-2
					Cabling diagram
					Figure 11-2
					Parts Illustration
					Figure 14-19
2	Printer, Color, UP-21MD, Sony	2100-1852-01	2275-0482-01	154899	Alias No:
	·				453561059831
					Photo
					Figure 1-2
					Cabling diagram
					Figure 11-2

**Table 14-2** 

Parts: Peripherals Parts List

Page 321

Item No.	Part Description	Part Number	Power Cable	Signal Cable	References
3	VCR Assy, HS-MD3000UA, NTSC, Mitsubishi	453561169651	2275-0482-01	154899 (Signal) 453561012981 (Audio)	Photo Figure 1-2 Cabling diagram Figure 11-3 NTSC version supports NTSC-M format
4	VCR Assy, HS-MD3000EA, PAL, Mitsubishi	453561169661	2275-0482-01	154899 (Signal) 453561012981 (Audio)	Photo Figure 1-2 Cabling diagram Figure 11-3 PAL version supports PAL-B format

#### 15 **Transducers**

#### Introduction

**CSIP Level I** 

This section summarizes general and parts information for the transducers that can be used with the HD3 system:

- C4-2 (Table 15-1)
- C5-2 (Table 15-2)
- C7-3 (Table 15-3)
- C9-4ec (Table 15-4)
- L9-5 (Table 15-5)

**NOTE** The customer is directed to order biopsy guides by contacting their Philips representative or an authorized distributor. Transducer covers and other supplies and accessories can be ordered from CIVCO Medical Instruments: See "Supplies and Accessories" on page 40.

Table 15-1 C4-2 Information

Parameter	Specification
Transducer Type	Curved linear array
Center Frequency	3.0 MHz
Radius of Curvature	26mm
Number of Elements	128
Element Pitch	0.328 mm
Elevation Aperture	I2 mm
Elevation Focus Depth	70.0 mm
Applications	Abdominal; pediatric; cardiac adult
Philips Part Number	453561201051

**CSIP Level I** 

**C5-2 Information** 

Parameter	Specification
Transducer Type	Curved linear array
Center Frequency	3.0 MHz
Radius of Curvature	38.7 mm
Number of Elements	128
Element Pitch	0.401 mm
Elevation Aperture	15.75 mm
Elevation Focus Depth	83.0 mm
Applications	Abdominal; pediatric; obstetrical;
	gynecological and fertility
Philips Part Number	453561201041

Table 15-3 C7-3 Information

Parameter	Specification
Transducer Type	Curved linear array
Center Frequency	4.5 MHz
Radius of Curvature	50 mm
Number of Elements	128
Element Pitch	0.474 mm
Elevation Aperture	II mm
Elevation Focus Depth	80.0 mm
Applications	Abdominal; pediatric; obstetrical;
	gynecological and fertility
Philips Part Number	453561201061

Table 15-4 C9-4ec Information

Parameter	Specification
Transducer Type	Endocavity curved linear array
Center Frequency	6.5 MHz
Radius of Curvature	1.0 mm
Number of Elements	128
Element Pitch	0.205 mm
Elevation Aperture	6 mm
Elevation Focus Depth	38.0 mm
Applications	Obstetrical; gynecological and fertility;
	prostate
Philips Part Number	453561201081

Table 15-5 L9-5 Information

Parameter	Specification
Transducer Type	Linear array
Center Frequency	7.5 MHz
Radius of Curvature	38.4 mm
Number of Elements	128
Element Pitch	0.3 mm
Elevation Aperture	6 mm
Elevation Focus Depth	20.0 mm
Applications	Small parts and superficial; pediatric;
	musculoskeletal; vascular
Philips Part Number	453561201071